

Datasheet

Sona™ IF573

Version 2.1

Revision History

Version	Date	Notes	Contributors	Approver
0.1	8 June 2023	Preliminary release	Various	Andy Ross
0.2	13 July 2023	Updates to Table 38: M.2 2230 E-Key pin definitions – WL_DEV_WAKE and BT_DEV_WAKE voltage	Jacky Kuo	Andrew Chen
0.3	8 Aug 2023	Added Transmit Power to Table 3: Specifications	Jacky Kuo	Andrew Chen
0.4	11 Aug 2023	Updated 7.1 M.2 1318 Solder-down	Jacky Kuo	Connie Lin
0.5	20 Oct 2023	Updated Table 12 through Table 21 in 8.5 WLAN Transmitter Characteristics	Jacky Kuo	Andy Ross
1.0	23 Oct 2023	Initial release	Andrew Chen Connie Lin Dean Ramsier Jacky Kuo Kris Sidle Peter Scharpf Andrew Dobbing	Andy Ross
1.1	5 Dec 2023	Updates to Table 37: M.2 1318 pin definitions and Table 38: M.2 2230 E-Key pin definitions . Removed channel sets as duplicated in Regulatory Information Guide.	Dean Ramsier Jacky Kuo Andrew Chen	Andy Ross
1.2	11 Dec 2023	Updated 19.1 Certified Antennas section	Connie Lin	Andy Ross
1.3	9 Jan 2024	Added 10 Crystal Oscillator Requirement	Dave Drogowski	Andy Ross
1.4	26 Jan 2024	Updates to Description of Control Signals	Jacky Kuo	Andy Ross
1.5	7 Feb 2024	Added RF Antenna Connector Configuration	Erik Lins	Andy Ross
1.6	23 Feb 2024	Updated Table 37 with info on pins 11-12	Jacky Kuo	Andrew Chen
1.7	29 July 2024	Fixed Pin 56 description in Table 38: M.2 2230 E-Key pin definitions Table 37: M.2 1318 pin definitions	Jacky Kuo	Dave Drogowski
2.1	22 Oct 2024	Updated the pull-down resistor values for “Pin 28” and “Pin 63” in the “ Table 37 ” to “50 k” from “200 k”.	Jacky Kuo	Dave Drogowski
1.9	30 Oct 2024	Updated Bluetooth Qualification process	Dave Drogowski	Jonathan Kaye
2.0	11 Feb 2025	Rebranded with Ezurio branding	Sue White	Dave Drogowski
2.1	16 May 2025	Updated for Bluetooth Core 6.0	Dave Drogowski	Andy Ross

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1 Scope

This document describes key hardware aspects of the Ezurio Sona™ IF573 series wireless modules providing either PCIe v3.0 Gen2 or SDIO 3.0 interface for WLAN connection and high-speed 4-wire UART interface for Bluetooth® connection. This document is intended to assist device manufacturers and related parties with the integration of this radio into their host devices. Data in this document is drawn from several sources and includes information found in the Infineon CYW55573MIWBGT data sheet issued on March 23, 2023, along with other documents provided by Infineon.

Note: The information in this document is subject to change. Please contact Ezurio to obtain the most recent version of this document.

2 Introduction

2.1 General Description

The Sona IF573 series wireless module is an integrated, small form factor Wi-Fi/Bluetooth module that is optimized for low-power mobile devices, featuring:

- Wi-Fi 6E: Tri-band 2x2 MIMO IEEE 802.11a/b/g/n/ac/ax WLAN
- Bluetooth® CAD files are uneditable in their current format and only feature LSR logo. Recommend leaving them: Dual Mode

The integration of all WLAN and Bluetooth functionality in a single package supports low cost and simple implementation along with flexibility for platform-specific customization. It is available in both M.2 2230 E-Key and M.2 1318 solder-down form factor.

This device is pre-calibrated and integrates the complete transmit/receive RF paths including bandpass filter, diplexer, switches, reference crystal oscillator, and power management units (PMU). Both variants support three integrated MHF4 connectors, with two ports for WLAN and one dedicated for Bluetooth. The M.2 1318 solder down module also supports an RF trace pin option for use with external antenna solutions. For a list of certified antennas see [Certified Antennas](#) in the datasheet.

The Sona IF573 series device supports IEEE 802.11ax tri-band (2.4/5/6 GHz) 2x2 MIMO with data rates up to MCS11 (287 Mbps PHY data rate for 2.4 GHz band and 1.2 Gbps PHY data rate for 5/6 GHz). The device has a dedicated Bluetooth port for best Wi-Fi + Bluetooth coexistence performance. The device's low power consumption, radio architecture and power management unit (PMU) proprietary power save technologies allow for extended battery life.

In addition, its tri-band IEEE 802.11ax and Bluetooth radio includes full digital MAC and baseband engines that handle all 802.11 CCK/OFDM/OFDMA® 2.4/5/6 GHz and Bluetooth Core 6.0 (Basic Rate, Enhanced Data Rate, and Bluetooth Low Energy) baseband and protocol processing.

The Sona IF573 series wireless modules include two product SKUs which have different RF paths. Please contact Ezurio Sales/FAE for further information. Ordering information is listed in [Table 1](#).

Table 1: Product ordering information

Part Number	Description
453-00117R	Sona IF573 1318 Module, MHF4, Tape and Reel
453-00117C	Sona IF573 1318 Module, MHF4, Cut Tape
453-00118R	Sona IF573 1318 Module, RF Trace Pin, Tape and Reel
453-00118C	Sona IF573 1318 Module, RF Trace Pin, Cut Tape
453-00119	Sona IF573 M.2 2230 Module, Key E, SDIO/UART
453-00120	Sona IF573 M.2 2230 Module, Key E, PCIe/UART
453-00119-K1	Sona IF573 M.2 2230 Module Development Kit, SDIO/UART
453-00120-K1	Sona IF573 M.2 2230 Module Development Kit, PCIe/UART

3 Sona IF573 Series Features Summary

The Ezurio Sona IF573 series device features are described in [Table 2](#).

Table 2: Sona IF573 series wireless module features

Feature	Description																											
Radio Front End	- Integrates the complete transmit/receive RF paths including bandpass filter, diplexer, switches, reference crystal oscillator, and power manage unit (PMU) - Supports tri-band (2.4/5/6 GHz) - Supports 20/40/80 MHz channel bandwidth - Supports 2x2 WLAN antenna configuration with dedicated Bluetooth antenna port																											
The <i>Bluetooth</i> ® word mark and logos are registered trademarks owned by Bluetooth SIG, Inc. Any use of such marks by Ezurio is under license. Other trademarks and trade names are those of their respective owners.																												
Power Management	Two buck regulator, multiple LDO regulators, and a power management unit (PMU) are integrated into the CYW55573MIWBGT. All regulators are programmable via the PMU. These blocks simplify power supply design for Bluetooth and WLAN functions in embedded designs.																											
Pre-Calibration	RF system tested and calibrated in production																											
Sleep Clock	An external sleep clock of 32.768 kHz is required. The external 32.768 kHz precision oscillator which meets the requirements listed following table must be used. <table><tr><th>Parameter</th><th>LPO Clock</th><th>Unit</th></tr><tr><td>Nominal input frequency</td><td>32.768</td><td>kHz</td></tr><tr><td>Frequency accuracy</td><td>±250</td><td>ppm</td></tr><tr><td>Duty cycle</td><td>30 – 70</td><td>%</td></tr><tr><td>Input signal amplitude</td><td>200 – 1800</td><td>mV, p-p</td></tr><tr><td>Signal type</td><td>Square-wave or sinewave</td><td>-</td></tr><tr><td>Input impedance</td><td>> 100k</td><td>Ω</td></tr><tr><td></td><td>< 5</td><td>pF</td></tr><tr><td>Clock jitter (during initial startup)</td><td>< 10,000</td><td>ppm</td></tr></table>	Parameter	LPO Clock	Unit	Nominal input frequency	32.768	kHz	Frequency accuracy	±250	ppm	Duty cycle	30 – 70	%	Input signal amplitude	200 – 1800	mV, p-p	Signal type	Square-wave or sinewave	-	Input impedance	> 100k	Ω		< 5	pF	Clock jitter (during initial startup)	< 10,000	ppm
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	< 5	pF																										
Clock jitter (during initial startup)	< 10,000	ppm																										
Host Interface	The Sona IF573 M.2 card provides two interfaces for customers to choose: 1. SDIO/UART , Wi-Fi section provides support for SDIO v3.0 and also is backward compatible with SDIO v2.0. Bluetooth section supports a high-speed 4-wire UART interface. 2. PCIe/UART , Wi-Fi section provides support for PCIe Gen2 (3.0 Compliant). Bluetooth section supports a high-speed 4-wire UART interface.																											
Advanced WLAN	- IEEE 802.11a/b/g/n/ac/ax compliant, tri-band capable (2.4/5/6 GHz) 2x2 MIMO providing up to 1.2 Gbps PHY data rate for 5/6 GHz (1024-QAM modulation) 2x2 MIMO providing up to 287 Mbps PHY data rate for 2.4 GHz (1024-QAM modulation) - Supports 20, 40, and 80 MHz channels with optional SGI (1024-QAM modulation) - Background channel availability check (CAC) scan for immediate switch to candidate DFS channel - On-chip power amplifiers and low-noise amplifiers for both bands - Support wide variety of WLAN encryption: WPA/WPA2/WPA3/TKIP/AES and IEEE 802.11i compatibility																											
Advanced Bluetooth	- Bluetooth Core 6.0 (BDR + EDR + Bluetooth LE) - Dedicated Bluetooth RF path port - Bluetooth Class 1 or Class 2 transmitter operation - Support data rate: 1 Mbps (GFSK), 2 Mbps (π/4-DQPSK), 3 Mbps (8-DPSK), LE-1 Mbps, LE-2 Mbps, LE-LR-500K (S=2) and LE-LR-125K (S=8) - Supports extended synchronous connections (eSCO) for enhanced voice quality by allowing for retransmission of dropped packets - Adaptive frequency hopping (AFH) for reducing radio frequency interference - Host controller interface (HCI) using a highspeed UART and PCM/I2S for audio data - Low power consumption improves battery life of IoT and embedded devices - Supports multiple simultaneous Advanced Audio Distribution Profiles (A2DP) for stereo sound - On-chip memory includes 512 KB SRAM and 2 MB ROM																											

4 Specifications

Table 3: Specifications

Feature	Description
Physical Interface	M.2 2230 E-Key standard form factor M.2 1318 108-pin LGA package (including 8 thermal ground pads under the package)
Wi-Fi Interface	PCIe v3.0 Gen2 Secure Digital I/O 2.0/3.0
Bluetooth/BLE Interface	Host Controller Interface (HCI) using high speed UART
Main Chipset	Infineon AIROC™ CYW55573MIWBGT
Input Voltage Requirements	Typical DC 3.3 V, operating range from DC 3.13V to 3.5V
I/O Signalling Voltage	Compliant with M.2 standard Typical DC 1.8 V ± 5%
Operating Temperature	-40° to +85°C (-40° to +185°F) Note: Absolute junction temperature 125 °C limit is maintained through active thermal monitoring, throttling, and turning off one of the TX chains or both.
Operating Humidity	10 to 90% (non-condensing)
Storage Temperature	-40° to +85°C (-40° to +185°F)
Storage Humidity	10 to 90% (non-condensing)
MSL (Moisture Sensitivity Level)	4
Maximum Electrostatic Discharge	Conductive 8KV; Air coupled 12KV (follows EN61000-4-2)
Size	M.2 1318 - Length: 18 mm - Width: 13 mm - Thickness: 0.43 mm M.2 E-Key - Length: 30 mm - Width: 22 mm - Thickness: 3.1 mm
Weight – g (oz.)	M.2 1318 ~0.7 M.2 E-Key 3
Wi-Fi Media	Direct Sequence-Spread Spectrum (DSSS) Complementary Code Keying (CCK) Orthogonal Frequency Division Multiplexing (OFDM) Orthogonal Frequency Division Multiple Access (OFDMA)
Bluetooth Media	Frequency Hopping Spread Spectrum (FHSS)
Wi-Fi Multimedia	WMM Wi-Fi Multimedia - PowerSave (WMM-PS with U-APSD) WMM-Sequential Access (WMM-SA)
Network Architecture Types	Infrastructure (client operation)
Wi-Fi Standards	IEEE 802.11ax, 11ac, 11a/b/g/n, 11d/h, 11i, 11r, 11w, 11e, 11k, 11ai, 11v
Bluetooth Standards	Bluetooth 2.1 + EDR, 3.0, 4.2, 5.0, 5.1, 5.2, 5.3, 5.4, Core 6.0
Wi-Fi Data Rates Supported	Support 802.11 ax/ac/a/b/g/n 2x2 MU-MIMO. 802.11b (DSSS, CCK) 1, 2, 5.5, 11 Mbps 802.11a/g (OFDM) 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n (OFDM, HT20/HT40, MCS0-15) 802.11ac (OFDM, VHT20, MCS0-8; OFDM, VHT40/HT80, MCS0-9) 802.11ax (2.4 GHz / OFDM / HE20 / MCS0-11; 2.4 GHz / OFDMA / HE20 / MCS0-11) 802.11ax (5 GHz, 6 GHz / OFDM / HE20, HE40, HE80 / MCS0-11; 5 GHz, 6 GHz / OFDMA / HE20, HE40, HE80 / MCS0-11)

Feature

Description

Modulation Table

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024-QAM

Modulation Type						OFDM (IEEE 802.11n/ac)												OFDM (IEEE 802.11ax)											
MCS Index			Spatial Stream	Modulation	Coding	20MHz				40MHz				80MHz				20MHz				40MHz				80MHz			
HT	VHT	HE				0.8us GI	1.6us GI	2.0us GI	0.8us GI	1.6us GI	2.0us GI	0.8us GI	1.6us GI	2.0us GI	0.8us GI	1.6us GI	2.0us GI	0.8us GI	1.6us GI	2.0us GI	0.8us GI	1.6us GI	2.0us GI	0.8us GI	1.6us GI	2.0us GI			
0	0	0	1	BPSK	1/2	6.5	7.2	13.5	15	29.3	32.5	8.6	8.1	7.3	17.2	16.3	14.6	36	34	30.6									
1	1	1	1	QPSK	1/2	13	14.4	27	30	58.5	65	17.2	16.3	14.6	34.4	32.5	29.3	72.1	68.1	61.3									
2	2	2	1	QPSK	3/4	19.5	21.7	40.5	45	87.8	97.5	25.8	24.4	21.9	51.6	48.8	43.9	108.1	102.1	91.9									
3	3	3	1	16-QAM	1/2	26	28.9	54	60	117	130	34.4	32.5	29.3	68.8	65	58.5	144.1	136.1	122.5									
4	4	4	1	16-QAM	3/4	39	43.3	81	90	175.5	195	51.6	48.8	43.9	103.2	97.5	87.8	216.2	204.2	183.8									
5	5	5	1	64-QAM	2/3	52	57.8	108	120	234	260	68.8	65	58.5	137.6	130	117	288.2	272.2	245									
6	6	6	1	64-QAM	3/4	78	86.7	162	180	351	390	103.2	97.5	87.8	206.5	195	175.5	432.4	408.3	367.5									
7	7	7	1	256-QAM	5/6	65	72.2	135	150	292.5	325	86	81.3	73.1	172.1	162.5	146.3	360.3	340.3	306.3									
8	8	8	1	256-QAM	3/4	78	86.7	162	180	351	390	103.2	97.5	87.8	206.5	195	175.5	432.4	408.3	367.5									
9	9	9	1	256-QAM	5/6	N/A	N/A	180	200	390	433.3	114.7	108.3	97.5	229.4	216.7	195	480.8	453.7	408.3									
10	10	10	1	1024-QAM	3/4	N/A	N/A	270	300	585	650	172.1	162.5	146.3	344.1	325	292.5	720.6	680.6	612.5									
11	11	11	1	1024-QAM	5/6	N/A	N/A	405	450	855	975	258.1	243.8	219.4	516.2	487.5	438.8	1080.9	1020.8	918.8									
8	0	0	2	BPSK	1/2	13	14.4	27	30	58.5	65	17.2	16.3	14.6	34.4	32.5	29.3	72.1	68.1	61.3									
9	1	1	2	QPSK	1/2	26	28.9	54	60	117	130	34.4	32.5	29.3	68.8	65	58.5	144.1	136.1	122.5									
10	2	2	2	QPSK	3/4	39	43.3	81	90	175.5	195	51.6	48.8	43.9	103.2	97.5	87.8	216.2	204.2	183.8									
11	3	3	2	16-QAM	1/2	52	57.8	108	120	234	260	68.8	65	58.5	137.6	130	117	288.2	272.2	245									
12	4	4	2	16-QAM	3/4	78	86.7	162	180	351	390	103.2	97.5	87.8	206.5	195	175.5	432.4	408.3	367.5									
13	5	5	2	64-QAM	2/3	104	115.6	216	240	468	520	137.6	130	117	275.3	260	234	576.5	544.4	490									
14	6	6	2	64-QAM	3/4	117	130	243	270	526.5	585	154.9	146.3	131.6	309.7	292.5	263.3	648.5	612.5	551.3									
15	7	7	2	64-QAM	5/6	130	144.4	270	300	585	650	172.1	162.5	146.3	344.1	325	292.5	720.6	680.6	612.5									
8	8	8	2	256-QAM	3/4	156	173.3	324	360	702	780	206.5	195	175.5	412.9	390	351	864.7	816.7	735									
9	9	9	2	256-QAM	5/6	N/A	N/A	360	400	780	866.7	229.4	216.7	195	458.8	433.3	390	960.8	907.4	816.7									
10	10	10	2	1024-QAM	3/4	N/A	N/A	540	600	1170	1299.3	258.1	243.8	219.4	516.2	487.5	438.8	1080.9	1020.8	918.8									
11	11	11	2	1024-QAM	5/6	N/A	N/A	810	900	1755	1948.5	387.1	365.7	329.1	774.3	727.5	658.2	1621.4	1531.2	1378.2									

OFDMA (IEEE 802.11ax)																						
MCS Index		Spatial Stream	Modulation	Coding	26-tone RU			52-tone RU			106-tone RU			242-tone RU			484-tone RU			996-tone RU		
HE					0.8us GI	1.6us GI	3.2us GI	0.8us GI	1.6us GI	3.2us GI	0.8us GI	1.6us GI	3.2us GI	0.8us GI	1.6us GI	3.2us GI	0.8us GI	1.6us GI	3.2us GI	0.8us GI	1.6us GI	3.2us GI
0	1	BPSK	1/2	0.9	0.8	0.8	1.8	1.7	1.5	3.8	3.5	3.2	8.6	8.1	7.3	17.2	16.3	14.6	36	34	30.6	
1	1	QPSK	1/2	1.8	1.7	1.5	3.5	3.3	3	7.5	7.1	6.4	17.2	16.3	14.6	34.4	32.5	29.3	72.1	68.1	61.3	
2	1	QPSK	3/4	2.6	2.5	2.3	5.3	5.3	4.5	11.3	10.6	9.6	25.8	24.4	21.9	51.6	48.8	43.9	108.1	102.1	91.9	
3	1	16-QAM	1/2	3.3	3.3	3	7.1	6.7	6	15	14.2	12.8	34.4	32.5	29.3	68.8	65	58.5	144.1	136.1	122.5	
4	1	16-QAM	3/4	5.3	5	4.5	10.6	10	9	22.5	21.3	19.1	51.6	48.8	43.9	103.2	97.5	87.8	216.2	204.2	183.8	
5	1	64-QAM	2/3	7.1	6.7	6	14.1	13.3	12	30	28.3	25.5	68.8	65	58.5	137.6	130	117	288.2	272.2	245	
6	1	64-QAM	3/4	7.9	7.5	6.8	15.9	15	13.5	33.8	31.9	28.7	77.4	73.1	65.8	154.9	146.3	131.6	324.3	306.3	275.6	
7	1	64-QAM	5/6	8.8	8.3	7.5	17.6	16.7	15	37.5	35.4	31.9	86	81.3	73.1	172.1	162.5	146.3	360.3	340.3	306.3	
8	1	256-QAM	3/4	10.6	10	9	21.2	20	18	45	42.5	38.3	103.2	97.5	87.8	206.5	195	175.5	432.4	408.3	367.5	
9	1	256-QAM	5/6	11.8	11.1	10	3.5	22.2	20	50	47.2	42.5	114.7	108.3	97.5	229.4	216.7	195	480.8	453.7	408.3	
10	1	1024-QAM	3/4	13.2	12.5	11.3	26.5	25	22.5	56.3	53.1	47.8	129	121.9	109.7	258.1	243.8	219.4	540.4	510.4	459.4	
11	1	1024-QAM	5/6	14.7	13.9	12.5	29.2	27.8	25	62.5	59	53	143.4	135.4	121.9	286.8	270.8	243.8	600.8	567.8	510.4	
0	2	BPSK	1/2	1.8	1.7	1.5	3.5	3.3	3	7.5	7.1	6.4	17.2	16.3	14.6	34.4	32.5	29.3	72.1	68.1	61.3	
1	2	QPSK	1/2	3.5	3.3	3	7.1	6.7	6	15	14.2	12.8	34.4	32.5	29.3	68.8	65	58.5	144.1	136.1	122.5	
2	2	QPSK	3/4	5.3	5	4.5	10.6	10	9	22.5	21.3	19.1	51.6	48.8	43.9	103.2	97.5	87.8	216.2	204.2	183.8	
3	2	16-QAM	1/2	7.1	6.7	6	14.1	13.3	12	30	28.3	25.5	68.8	65	58.5	137.6	130	117	288.2	272.2	245	
4	2	16-QAM	3/4	10.6	10	9	21.2	20	18	45	42.5	38.3	103.2	97.5	87.8	206.5	195	175.5	432.4	408.3	367.5	
5	2	64-QAM	2/3	14.1	13.3	12	28.2	26.7	24	60	56.7	51	137.6	130	117	275.3	260	234	576.5	544.4	490	
6	2	64-QAM	3/4	15.9	15	13.5	31.8	30	27	67.5	63.8	57.4	154.9	146.3	131.6	309.7	292.5	263.3	648.5	612.5	551.3	
7	2	256-QAM	5/6	17.6	16.7	15	35.3	33.3	30	75	70.8	63.8	172.1	162.5	146.3	344.1	325	292.5	720.6	680.6	612.5	
8	2	256-QAM	3/4	21.2	20	18	42.4	40	36	90	85	76	206.5	195	175.5	412.9	390	351	864.7	816.7	735	
9	2	256-QAM	5/6	23.5	22.2	20	47.1	44.4	40	100	94.4	85	229.4	216.7	195	458.8	433.3	390	960.8	907.4	816.7	
10	2	1024-QAM	3/4	26.5	25	22.5	52.9	50	45	112.5	106.3	95.6	258.1	243.8	219.4	516.2	487.5	438.8	1080.9	1020.8	918.8	
11	2	1024-QAM	5/6	29.4	27.8	25	58.8	55.6	50	125	118.1	106.3	286.8	270.8	243.8	573.5	541.7	487.5	1201	1134.3	1020.8	

802.11ax/ac/n Spatial Streams

2 (2x2 MU-MIMO)

Bluetooth Data Rates Supported

1, 2, 3 Mbps

Bluetooth Modulation

GFSK @ 1 Mbps
Pi/4-DQPSK @ 2 Mbps
8-DPSK @ 3 Mbps

Bluetooth LE Data Rates Supported

1, 2 Mbps, 500 Kbps (S=2), 125 Kbps (S=8)

Bluetooth LE Modulation

GFSK @ 1, 2 Mbps
GFSK @ 125, 500 Kbps

Regulatory Certifications

United States (FCC)
EU - Member countries of European Union (ETSI)
Great Britain (UKCA)
Canada (ISED)
Australia/New Zealand (RCM)
Japan (MIC)

2.4 GHz Frequency Bands

EU: 2.4 GHz to 2.483 GHz
FCC/ISED: 2.4 GHz to 2.473 GHz
UKCA: 2.4 GHz to 2.483 GHz
MIC: 2.4 GHz to 2.483 GHz
RCM: 2.4 GHz to 2.483 GHz

Feature	Description	
5 GHz Frequency Bands	EU	UKCA
	5.15 GHz to 5.35 GHz	5.15 GHz to 5.35 GHz
	5.47 GHz to 5.725 GHz	5.47 GHz to 5.730 GHz
	5.725 GHz to 5.85 GHz	5.725 GHz to 5.850 GHz
	FCC	MIC
	5.15 GHz to 5.35 GHz	5.15 GHz to 5.35 GHz
	5.47 GHz to 5.725 GHz	5.47 GHz to 5.725 GHz
	5.725 GHz to 5.85 GHz	
	ISED	RCM
	5.15 GHz to 5.35 GHz	5.15 GHz to 5.35 GHz
	5.47 GHz to 5.725 GHz	5.47 GHz to 5.725 GHz
	5.725 GHz to 5.85 GHz	5.725 GHz to 5.85 GHz
6 GHz Frequency Bands	FCC / ISCED	UKCA
	UNII-5, 5.925 GHz to 6.415 GHz	UNII-5, 5.945 GHz to 6.425 GHz
	UNII-6, 6.435 GHz to 6.515 GHz	MIC
	UNII-7, 6.535 GHz to 6.875 GHz	UNII-5, 5.945 GHz to 6.425 GHz
	UNII-8, 6.895 GHz to 7.115 GHz	RCM
	EU	UNII-5, 5.945 GHz to 6.425 GHz
	UNII-5, 5.945 GHz to 6.425 GHz	
Transmit Power	802.11a	
	6 Mbps	16.5 dBm (44.66 mW)
	54 Mbps	16 dBm (39.81 mW)
<i>Note: Transmit power on each channel varies per individual country regulations. All values are nominal with +/-2 dBm tolerance at room temperature.</i>	802.11b	
	1 Mbps	17 dBm (50.11 mW)
	11 Mbps	17 dBm (50.11 mW)
<i>Tolerance could be up to +/-2.5 dBm across operating temperature.</i>	802.11g	
	6 Mbps	16.5 dBm (44.66 mW)
	54 Mbps	16 dBm (39.81 mW)
	802.11n (2.4 GHz)	
	HT20; MCS0-4, MCS8-12	16 dBm (39.81 mW)
	HT20; MCS5-7, MCS13-15	15 dBm (31.62 mW)
<i>Note:</i>	802.11ax (2.4 GHz)	
	HE20; MCS0-4	16 dBm (39.81 mW)
HT20/VHT20/HE20 – 20 MHz-wide channels	HE20; MCS5-7	15 dBm (31.62 mW)
HT40/VHT40/HE40 – 40 MHz-wide channels	HE20; MCS8-9	12.5 dBm (17.78 mW)
HT80/VHT80/HE80 – 80 MHz-wide channels	HE20; MCS10-11	10.5 dBm (11.22 mW)
	802.11n (5 GHz)	
	HT20; MCS0-4, MCS8-12	16.5 dBm (44.66 mW)
	HT20; MCS5-7, MCS13-15	16 dBm (39.81 mW)
	HT40; MCS0-4, MCS8-12	16 dBm (39.81 mW)
	HT40; MCS5-7, MCS13-15	15 dBm (31.62 mW)
	802.11ac (5 GHz)	
	VHT20; MCS0-4	16.5 dBm (44.66 mW)
	VHT20; MCS5-7	16 dBm (39.81 mW)
	VHT20; MCS8	14 dBm (25.12 mW)
	VHT40; MCS0-4	16 dBm (39.81 mW)
	VHT40; MCS5-7	15 dBm (31.62 mW)
	VHT40; MCS8-9	12 dBm (15.85 mW)
	VHT80; MCS0-4	16 dBm (39.81 mW)
	VHT80; MCS5-7	15 dBm (31.62 mW)
	VHT80; MCS8-9	12 dBm (15.85 mW)

Feature	Description
	802.11ax (5 GHz)
	HE20; MCS0-4 16.5 dBm (44.66 mW)
	HE20; MCS5-7 16 dBm (39.81 mW)
	HE20; MCS8-9 14 dBm (25.12 mW)
	HE20; MC10-11 13 dBm (19.95 mW)
	HE40; MCS0-4 16 dBm (39.81 mW)
	HE40; MCS5-7 15 dBm (31.62 mW)
	HE40; MCS8-9 12 dBm (15.85 mW)
	HE40; MC10-11 11.5 dBm (14.13 mW)
	HE80; MCS0-4 16 dBm (39.81 mW)
	HE80; MCS5-7 15 dBm (31.62 mW)
	HE80; MCS8-9 12 dBm (15.85 mW)
	HE80; MCS10-11 11 dBm (12.59 mW)
	802.11ax (6 Hz, UNII-5 / 6)
	11a; 6M-24M 15.5 dBm (35.48 mW)
	HE20; MCS0-6 15.5 dBm (35.48 mW)
	HE20; MCS7 15 dBm (31.62 mW)
	HE20; MCS8 14.5 dBm (28.18 mW)
	HE20; MCS9-11 12 dBm (15.85 mW)
	HE40; MCS0-6 15.5 dBm (35.48 mW)
	HE40; MCS7 14 dBm (25.12 mW)
	HE40; MCS8 12.5 dBm (17.78 mW)
	HE40; MCS9 12 dBm (15.85 mW)
	HE40; MCS10-11 11 dBm (12.59 mW)
	HE80; MCS0-6 15 dBm (31.62 mW)
	HE80; MCS7 14 dBm (25.12 mW)
	HE80; MCS8 12 dBm (15.85 mW)
	HE80; MCS9 11 dBm (12.59 mW)
	HE80; MCS10-11 10 dBm (10 mW)
	802.11ax (6 Hz, UNII-7 / 8)
	11a; 6M-24M 15 dBm (31.62 mW)
	HE20; MCS0-6 15 dBm (31.62 mW)
	HE20; MCS7 13 dBm (19.95 mW)
	HE20; MCS8 12 dBm (15.85 mW)
	HE20; MCS9-11 10.5 dBm (11.22 mW)
	HE40; MCS0-6 15 dBm (31.62 mW)
	HE40; MCS7 12 dBm (15.85 mW)
	HE40; MCS8 11 dBm (12.59 mW)
	HE40; MCS9 10 dBm (10 mW)
	HE40; MCS10-11 8.5 dBm (7.08 mW)
	HE80; MCS0-6 14.5 dBm (28.18 mW)
	HE80; MCS7 11 dBm (12.59 mW)
	HE80; MCS8 10 dBm (10 mW)
	HE80; MCS9-11 8.5 dBm (7.08 mW)
	Bluetooth
	1 Mbps (1DH1 3, 5) 7 dBm (5 mW), Maximum
	2 Mbps (2DH1, 3, 5) 3 dBm (1.99 mW), Maximum
	3 Mbps (3DH1, 3, 5) 3 dBm (1.99 mW), Maximum
	LE (1 Mbps, 2 Mbps) 7 dBm (5 mW), Maximum
	LE-LR (S=2, S=8) 7 dBm (5 mW), Maximum

Feature	Description
Typical Receiver Sensitivity (PER <= 10%)	802.11a:
	6 Mbps -92 dBm 54 Mbps -75 dBm
Note: All values nominal, +/-3 dBm.	802.11b:
	1 Mbps -96 dBm (PER < 8%) 11 Mbps -90 dBm (PER < 8%)
	802.11g:
	6 Mbps -93 dBm 54 Mbps -76 dBm
	802.11n (2.4 GHz)
	6.5 Mbps (MCS0; HT20) -93 dBm 65 Mbps (MCS7; HT20) -75 dBm
	802.11ax (2.4 GHz)
	7.3 Mbps (MCS0; HE20) -93 dBm
	121.9 Mbps (MCS11; HE20) -62 dBm
	7.3 Mbps (MCS0; HE20/RU242) -93 dBm
	802.11n (5 GHz)
	6.5 Mbps (MCS0; HT20) -93 dBm
	65 Mbps (MCS7; HT20) -73 dBm
	13.5Mbps (MCS0; HT40) -90 dBm
	135Mbps (MCS7; HT40) -71 dBm
	802.11ac (5 GHz)
	6.5 Mbps (MCS0; VHT20) -93 dBm
	78 Mbps (MCS8; VHT20) -70 dBm
	13.5 Mbps (MCS0; VHT40) -90 dBm
	180 Mbps (MCS9; VHT40) -65 dBm
	29.3 Mbps (MCS0; VHT80) -87 dBm
	390 Mbps (MCS9; VHT80) -62 dBm
	802.11ax (5 GHz)
	7.3 Mbps (MCS0; HE20) -90 dBm
	121.9 Mbps (MCS11; HE20) -60 dBm
	7.3 Mbps (MCS0; HE20/RU242) -90 dBm
	14.6 Mbps (MCS0; HE40) -88 dBm
	243.8 Mbps (MCS11; HE40) -58 dBm
	14.6 Mbps (MCS0; HE40/RU484) -88 dBm
	30.6 Mbps (MCS0; HE80) -87dBm
	510.4 Mbps (MCS11; HE80) -55 dBm
	30.6 Mbps (MCS0; HE80/RU996) -87 dBm
	802.11ax (6 GHz, UNII-5)
	6 Mbps -90 dBm
	24 Mbps -83 dBm
	7.3 Mbps (MCS0; HE20) -90 dBm
	121.9 Mbps (MCS11; HE20) -60 dBm
	7.3 Mbps (MCS0; HE20/RU242) -90 dBm
	14.6 Mbps (MCS0; HE40) -89 dBm
	243.8 Mbps (MCS11; HE40) -56 dBm
	14.6 Mbps (MCS0; HE40/RU484) -89 dBm
	30.6 Mbps (MCS0; HE80) -87 dBm
	510.4 Mbps (MCS11; HE80) -54 dBm
	30.6 Mbps (MCS0; HE80/RU996) -87 dBm

Feature	Description
	802.11ax (6 GHz, UNII-6) 6 Mbps -89 dBm 24 Mbps -82 dBm 7.3 Mbps (MCS0; HE20) -89 dBm 121.9 Mbps (MCS11; HE20) -59 dBm 7.3 Mbps (MCS0; HE20/RU242) -89 dBm 14.6 Mbps (MCS0; HE40) -88 dBm 243.8 Mbps (MCS11; HE40) -55 dBm 14.6 Mbps (MCS0; HE40/RU484) -88 dBm 30.6 Mbps (MCS0; HE80) -85 dBm 510.4 Mbps (MCS11; HE80) -54 dBm 30.6 Mbps (MCS0; HE80/RU996) -85 dBm
	802.11ax (6GHz, UNII-7) 6 Mbps -86 dBm 24 Mbps -81 dBm 7.3 Mbps (MCS0; HE20) -86 dBm 121.9 Mbps (MCS11; HE20) -58 dBm 7.3 Mbps (MCS0; HE20/RU242) -86 dBm 14.6 Mbps (MCS0; HE40) -85 dBm 243.8 Mbps (MCS11; HE40) -55 dBm 14.6 Mbps (MCS0; HE40/RU484) -85 dBm 30.6 Mbps (MCS0; HE80) -84 dBm 510.4 Mbps (MCS11; HE80) -52 dBm 30.6 Mbps (MCS0; HE80/RU996) -84 dBm
	802.11ax (6 GHz, UNII-8) 6 Mbps -85 dBm 24 Mbps -79 dBm 7.3 Mbps (MCS0; HE20) -85 dBm 121.9 Mbps (MCS11; HE20) -56 dBm 7.3 Mbps (MCS0; HE20/RU242) -85 dBm 14.6 Mbps (MCS0; HE40) -84 dBm 243.8 Mbps (MCS11; HE40) -53 dBm 14.6 Mbps (MCS0; HE40/RU484) -84 dBm 30.6 Mbps (MCS0; HE80) -83 dBm 510.4 Mbps (MCS11; HE80) -51 dBm 30.6 Mbps (MCS0; HE80/RU996) -83 dBm
	Bluetooth: 1 Mbps (1DH5) -91 dBm 2Mbps (2DH5) -93 dBm 3 Mbps (3DH5) -87 dBm LE-1 Mbps -95 dBm LE-2 Mbps -92 dBm LE-LR (S=2) -102 dBm LE-LR (S=8) -107 dBm
Operating Systems Supported	Linux Android
Security	- WPA, WPA2 (Enterprise) and WPA3 (Enterprise) support for powerful encryption and authentication - AES and TKIP in hardware for faster data encryption and IEEE 802.11i compatibility - Reference WLAN subsystem provides Wi-Fi Protected Setup (WPS)

Feature	Description
Compliance	EU
	EN 300 328
	EN 301 489-1
	EN 301 489-17
	EN 301 893
	EN 62368-1:2014
	EN 300 440
	EN 303 687
	2011/65/EU (RoHS)
	FCC
	47 CFR FCC Part 15.247
	47 CFR FCC Part 15.407
	47 CFR FCC Part 2.1091
	ISED Canada
	RSS-247
	RSS-248
	AS/NZS
	AS/NZS 4268:2017
	MIC
	ARIB STD-T66/RCR STD-33 (2.4 GHz)
	ARIB STD-T71 (5 GHz)
	Article 2 Paragraph 1 of Item 80 :
	LPI (ZR), 6 GHz
Certifications	Bluetooth® SIG Qualification D063147 
Warranty	One Year Warranty
<i>All specifications are subject to change without notice</i>	

5 WLAN Functional Description

5.1 Overview

The Sona IF573 series wireless module is designed based on the Infineon AIROC CYW55573MIWBGT Wi-Fi 6E chipset (dual-core 2x2 MIMO). It is optimized for high speed, reliability, and low-power embedded applications. It is integrated with tri-band WLAN (2.4/5/6 GHz) and Bluetooth Core 6.0. Its functionality is listed in [Table 4](#).

Table 4: WLAN functions

Feature	Description
WLAN	Enhanced MAC for supporting IEEE 802.11a/b/g/n/ac/ax features
MAC	- Transmission and reception of HE-SU and HE-ER-SU PPDU - Reception of HE-MU PPD -OFDMA/MU-MIMO frame - Transmission of HE-TB PPDU (Uplink MU OFDMA) - Transmission and reception of A-MPDUs/AMSDUs for very high throughput (VHT) - Support for power management schemes, including WMM power-save, programmable state machine (PSM) operation - Support for all ACK and Block-ACK policies as per standard - Interframe space timing support, including RIFS - Support for RTS/CTS and CTS-to-nowhere frame sequences for protecting frame exchanges - Timing synchronization function (TSF), network allocation vector (NAV) maintenance, and target beacon transmission time (TBTT) generation in hardware and capturing the TSF timer on an external time synchronization pulse - Hardware offload for cipher suites/encryption types WEP, TKIP(WPA), AES(WPA2), support for WPA3-SAE and key management - Support for coexistence with Bluetooth - RTS-CTS based BW signaling mechanism support
WLAN Security	- WLAN Encryption features supported include: - Temporal Key Integrity Protocol (TKIP)/Wired Equivalent Privacy (WEP) - Advanced Encryption Standard (AES)/Wi-Fi Multi-Media (WMM) - WLAN Authentication and Private Infrastructure (WPAI)
WLAN Channel	Channel frequency supported.

2.4 GHz / 20 MHz		5 GHz / 20 MHz		5 GHz / 40 MHz		5 GHz / 80 MHz	
Channel	Frequency (MHz)	Channel	Frequency (MHz)	Channel	Frequency (MHz)	Channel	Frequency (MHz)
1	2412	36	5180	38	5190	42	5210
2	2417	40	5200	46	5230	58	5290
3	2422	44	5220	54	5270	106	5530
4	2427	48	5240	62	5310	122	5610
5	2432	52	5260	102	5510	138	5690
6	2437	56	5280	110	5550	155	5775
7	2442	60	5300	118	5590		
8	2447	64	5320	126	5630		
9	2452	100	5500	134	5670		
10	2457	104	5520	142	5710		
11	2462	108	5540	151	5755		
12	2467	112	5560	159	5795		
13	2472	116	5580				
		120	5600				
		124	5620				
		128	5640				
		132	5660				
		136	5680				
		140	5700				
		144	5720				
		149	5745				
		153	5765				
		157	5785				
		161	5805				
		165	5825				

6 GHz / UNII-5					
20 MHz		40 MHz		80 MHz	
Channel	Frequency (MHz)	Channel	Frequency (MHz)	Channel	Frequency (MHz)
1	5955	3	5965	7	5985
5	5975	11	6005	23	6065
9	5995	19	6045	39	6145
13	6015	27	6085	55	6225
17	6035	35	6125	71	6305
21	6055	43	6165	87	6385
25	6075	51	6205		
29	6095	59	6245		
33	6115	67	6285		
37	6135	75	6325		
41	6155	83	6365		
45	6175	91	6405		
49	6195				
53	6215				
57	6235				
61	6255				
65	6275				
69	6295				
73	6315				
77	6335				
81	6355				
85	6375				
89	6395				
93	6415				

6 GHz / UNII-6					
20 MHz		40 MHz		80 MHz	
Channel	Frequency (MHz)	Channel	Frequency (MHz)	Channel	Frequency (MHz)
97	6435	99	6445	103	6465
101	6455	107	6485	119	6545
105	6475	115	6525		
109	6495				
113	6515				

6 GHz / UNII-7					
20 MHz		40 MHz		80 MHz	
Channel	Frequency (MHz)	Channel	Frequency (MHz)	Channel	Frequency (MHz)
117	6535	123	6565	135	6625
121	6555	131	6605	151	6705
125	6575	139	6645	167	6785
129	6595	147	6685	183	6865
133	6615	155	6725		
137	6635	163	6765		
141	6655	171	6805		
145	6675	179	6845		
149	6695	187	6885		
153	6715				
157	6735				
161	6755				
165	6775				
169	6795				
173	6815				
177	6835				
181	6855				
185	6875				

6 GHz / UNII-8					
20 MHz		40 MHz		80 MHz	
Channel	Frequency (MHz)	Channel	Frequency (MHz)	Channel	Frequency (MHz)
189	6895	195	6925	199	6945
193	6915	203	6965	215	7025
197	6935	211	7005		
201	6955	219	7045		
205	6975	227	7085		
209	6995				
213	7015				
217	7035				
221	7055				
225	7075				
229	7095				
233	7115				

6 Bluetooth Functional Description

The Sona IF573 series wireless module includes a fully integrated Bluetooth baseband/radio. Several features and functions are listed in [Table 5](#).

Table 5: Bluetooth functions

Feature	Description
Bluetooth Interface	- Voice interface: - Supported by PCM transports and bi-directional operations. - Sample rates 8k for NBS and 16k for WBS supported. - Sample width is limited to 16-bits. - Synchronization clock width of 1 or 3 (short or long) - Bit clocks of 128k, 256k, 512k, 1024k and 2024k, the only difference being the number of 16bit slots. - HFP samples can be taken from any available slot. Slot 0 is the default slot. - High-Speed UART interface
Bluetooth Core functionality	- Supports all Bluetooth 5.3 and 4.2 features - Dual-mode Bluetooth low energy - Bluetooth LE LE-2Mbps mode, LE-Long Range mode, Advertising Extensions, Slot Availability Masks - Extended inquiry response (EIR): Shortens the time to retrieve the device name, specific profile, and operating mode - Encryption pause resume (EPR): Enables the use of Bluetooth technology in a much more secure environment - Sniff subrating (SSR): Optimizes power consumption for low duty cycle asymmetric data flow, which subsequently extends battery life. - Secure simple pairing (SSP): Reduces the number of steps for connecting two devices, with minimal or no user interaction required. - Link supervision time out (LSTO): Additional commands added to HCI and link management protocol (LMP) for improved link time-out supervision. - QoS enhancements: Changes to data traffic control, which results in better link performance. Audio, human interface device (HID), bulk traffic. SCO, and enhanced SCO (eSCO) are improved with the erroneous data (ED) and packet boundary flag (PBF) enhancements.
Bluetooth Features	- Supports features of Bluetooth Core Specification version 5.2: - LE Isochronous Channels - LE Power Control - Supports features of Bluetooth Core Specification version 5.1: - Direction Finding (AoA/AoD) - Additional Advertising Channels - Periodic Advertising Sync Transfer (PAST) - GATT Caching - Supports features of Bluetooth Core Specification version 5.0: - LE 2Mbps - LE Long Range (LE-LR) - Stable Modulation Index for LE - LE Advertising Extension - Slot Availability Masks (SAM) - Channel Selection Algorithm - High Duty Cycle Non-Connectable Advertising - Supports features of Bluetooth Core Specification version 4.0 + EDR - Adaptive frequency hopping (AFH) - Quality of service (QoS) - Extended synchronous connections (eSCO) – Voice Connections - Fast connect (interlaced page and inquiry scans) - Secure simple pairing (SSP) - Sniff subrating (SSR)

Feature	Description
	- Encryption pause resume (EPR) - Extended inquiry response (EIR) - Link supervision timeout (LST) • Multipoint operation with up to seven active slaves - Maximum of seven simultaneous active ACL links - Maximum of three simultaneous active SCO and eSCO connections with scattement support • High-speed HCI UART transport support with low-power out-of-band BT_DEV_WAKE and BT_HOST_WAKE signaling.

7 Block Diagrams

7.1 M.2 1318 Solder-down

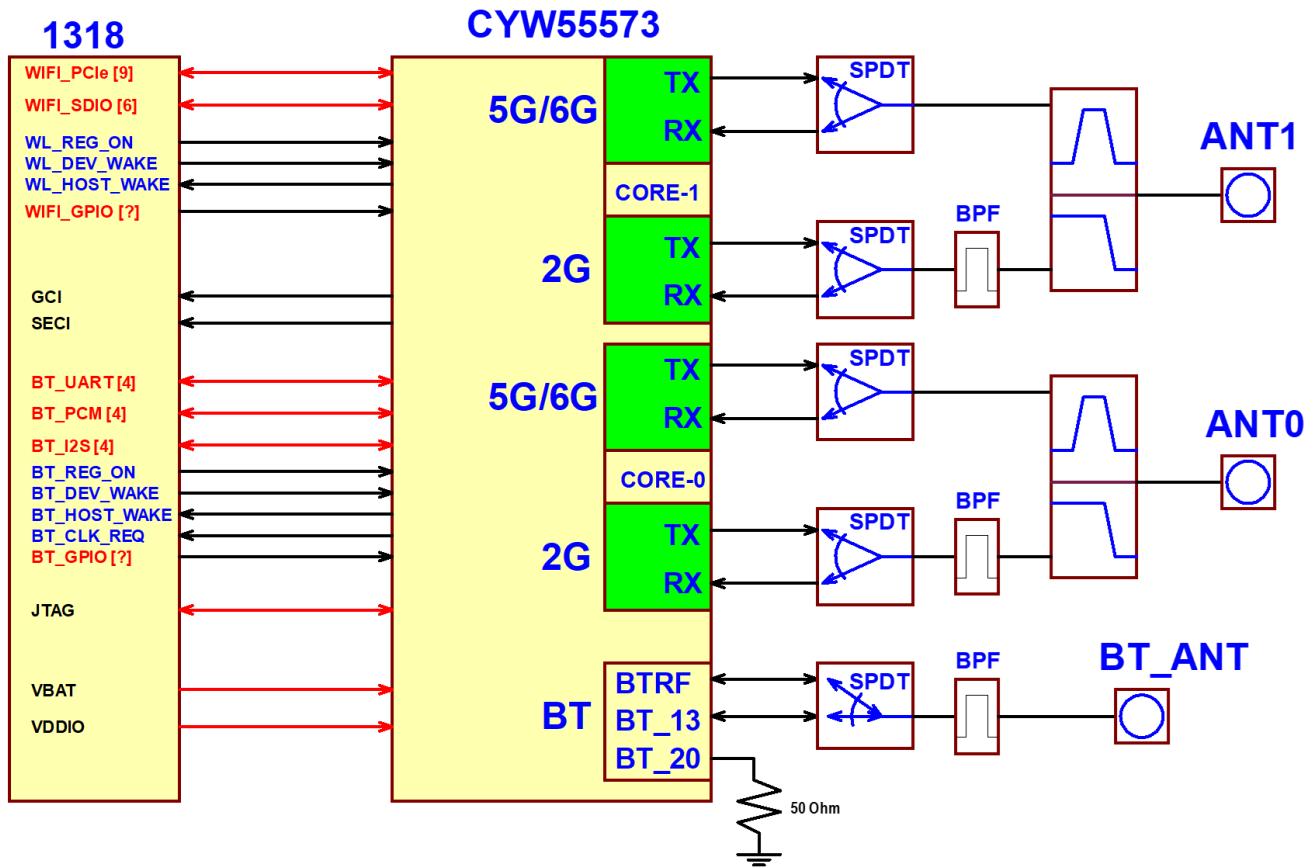


Figure 1: M.2 1318

7.2 M.2 2230 E-Key

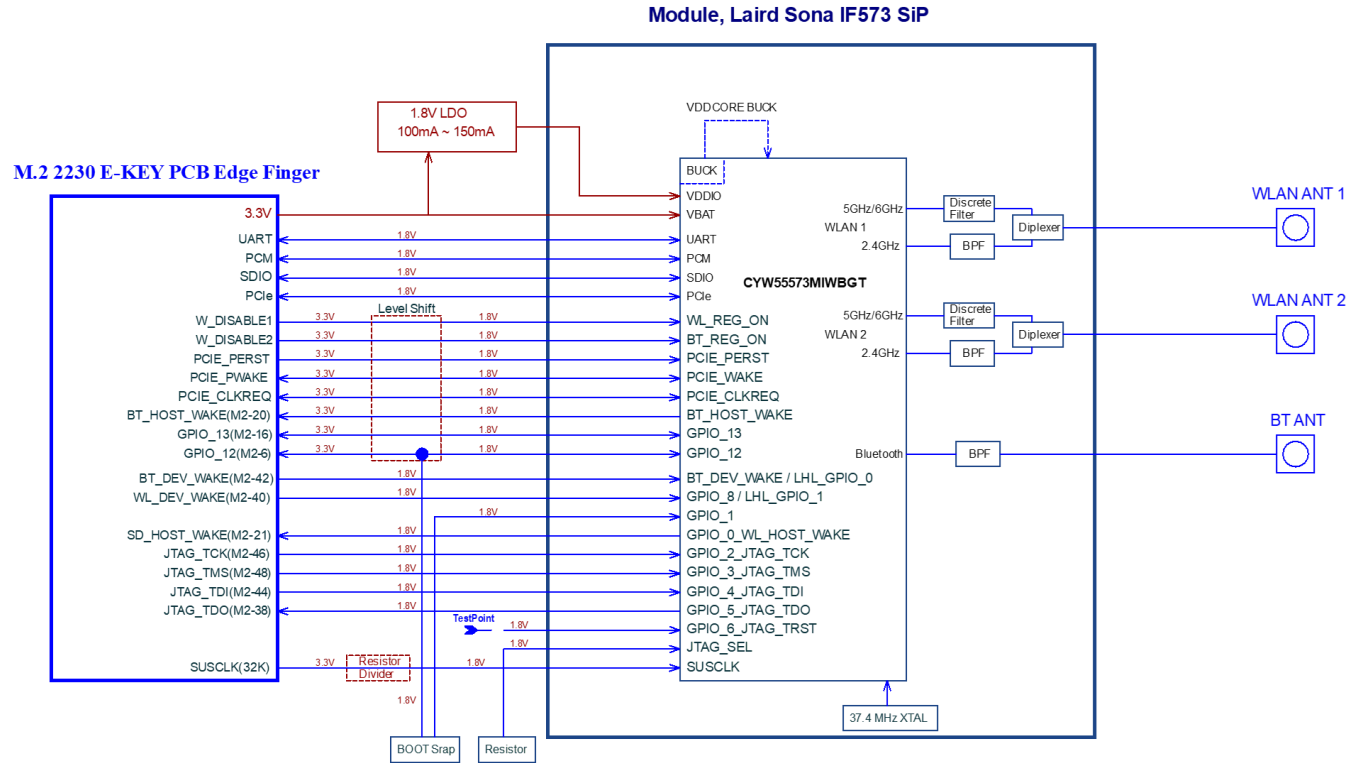


Figure 2: M.2 2230 E-Key

8 Electrical Characteristics

8.1 Absolute Maximum Ratings

Table 6 summarizes the absolute maximum ratings and Table 7 lists the recommended operating conditions for the Sona IF573 series wireless module. Absolute maximum ratings are those values beyond which damage to the device can occur. Functional operation under these conditions, or at any other condition beyond those indicated in the operational sections of this document, is not recommended.

Note: Maximum rating for signals follows the supply domain of the signals.

Table 6: Absolute maximum ratings

Symbol (Domain)	Description	Max Rating	Unit
VBAT	External DC power supply (M.2 1318)	+6.0	V
VDDIO	DC supply voltage for digital I/O (M.2 1318)	2.2	V
3V3	External 3.3V power supply (M.2 2230 E-Key)	4.0	V
Storage	Storage temperature	-40 to +125	°C
Antenna	Maximum RF input (reference to 50-Ω input)	+10	dBm
ESD	Electrostatic discharge tolerance	2000	V

8.2 Recommended Operating Conditions

Table 7: Recommended operating conditions

Symbol (Domain)	Parameter	Min	Typ	Max	Unit
VBAT	External DC power supply	3.13	3.3	3.47	V
VDDIO	DC supply voltage for digital I/O	1.71	1.8	1.89	V
T-ambient	Ambient temperature	-40	25	+85	°C

8.3 DC Electrical Characteristics

Table 8 list the general DC electrical characteristics over recommended operating conditions (unless otherwise specified).

Table 8: General DC electrical characteristics (For 1.8V operation VDDIO)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VIH	High Level Input Voltage	—	0.65 x VDDIO	—	—	V
VIL	Low Level Input Voltage	—	—	—	0.35 x VDDIO	V
VOH	Output high Voltage	—	VDDIO - 0.4	—	—	V
VOL	Output low Voltage	—	—	—	0.45	V

8.4 WLAN Radio Receiver Characteristics

Table 9, Table 10, and Table 11 summarize the Sona IF573 series wireless module receiver characteristics.

Table 9: WLAN receiver characteristics for 2.4 GHz single chain operation

Item	Parameter	Conditions	Min	Typ	Max	Unit
Frequency Range	Receive input frequency range	—	2.412	—	2.484	GHz
Modulation Type	Sensitivity					
	CCK, 1 Mbps	See Note ¹	—	-96	—	dBm
	CCK, 11 Mbps		—	-90	—	
	OFDM, 6 Mbps		—	-93	—	
	OFDM, 54 Mbps		—	-76	—	
	HT20, MCS0		—	-93	—	
	HT20, MCS7		—	-75	—	
	HE20, MCS0		—	-93	—	
	HE20, MCS11		—	-62	—	
ACI - OFDM	Adjacent channel rejection					
[Difference between interfering and desired signal (25 MHz apart)]	OFDM, 6 Mbps	See Note ¹	—	30	—	dB
	OFDM, 54 Mbps		—	15	—	
ACI - 11n MCS0-7	HT20, MCS0		—	30	—	
[Difference between interfering and desired signal (25 MHz apart)]	HT20, MCS7		—	10	—	
ACI - 11ax MCS0-11	HE20, MCS0		—	30	—	
[Difference between interfering and desired signal (25 MHz apart)]	HE20, MCS7		—	10	—	
	HE20, MCS11		—	TBD	—	

Table 10: WLAN receiver characteristics for 5 GHz single chain operation

Item	Parameter	Conditions	Min	Typ	Max	Unit
Frequency Range	Receive input frequency range	—	5.15	—	5.825	GHz
Modulation Type	Sensitivity					
	OFDM, 6 Mbps	See Note ¹	—	-92	—	dBm
	OFDM, 54 Mbps		—	-75	—	
	HT20, MCS0		—	-93	—	
	HT20, MCS7		—	-73	—	
	HT40, MCS0		—	-90	—	
	HT40, MCS7		—	-71	—	
	VHT20, MCS0		—	-93	—	
	VHT20, MCS8		—	-70	—	
	VHT40, MCS0		—	-90	—	
	VHT40, MCS9		—	-65	—	
	VHT80, MCS0		—	-87	—	
	VHT80, MCS9		—	-62	—	
	HE20, MCS0		—	-92	—	
	HE20, MCS11		—	-60	—	
	HE40, MCS0		—	-90	—	
	HE40, MCS11		—	-58	—	
	HE80, MCS0		—	-87	—	

Item	Parameter	Conditions	Min	Typ	Max	Unit
	HE80, MCS11		–	-55	–	
ACI – OFDM	Adjacent channel rejection					
[Difference between interfering and desired signal (20 MHz apart)]	OFDM, 6 Mbps	See Note ¹	–	25	–	dB
	OFDM, 54 Mbps		–	5	–	
ACI – MCS0-11	MCS0	See Note ¹	–	25	–	dB
[Difference between interfering and desired signal (20 MHz apart)]	MCS7		–	5	–	
	MCS11		–	TBD	–	
ACI – MCS0-11	MCS0	See Note ¹	–	24	–	dB
[Difference between interfering and desired signal (40 MHz apart)]	MCS7		–	5	–	
	MCS11		–	TBD	–	
ACI – MCS0-11	MCS0	See Note ¹	–	TBD	–	dB
[Difference between interfering and desired signal (80 MHz apart)]	MCS7		–	TBD	–	
	MCS11		–	TBD	–	

Table 11: WLAN receiver characteristics for 6 GHz single chain operation

Item	Parameter	Conditions	Typical (Sensitivity)				Unit
			UNII-5	UNII-6	UNII-7	UNII-8	
Frequency Range	Receive input frequency range	—	5950 - 6415	6435 - 6515	6535 - 6875	6895 - 7115	MHz
Modulation Type	OFDM, 6Mbps	See Note ¹	-92	-91	-90	-88	dBm
	OFDM, 24Mbps		-83	-82	-81	-79	
	HE20, MCS0		-92	-91	-90	-89	
	HE20, MCS7		-74	-73	-72	-70	
	HE20, MCS8		-69	-68	-67	-66	
	HE20, MCS9		-68	-67	-66	-64	
	HE20, MCS11		-60	-59	-58	-56	
	HE40, MCS0		-90	-89	-88	-86	
	HE40, MCS7		-71	-70	-69	-67	
	HE40, MCS8		-67	-66	-65	-63	
	HE40, MCS9		-65	-64	-63	-61	
	HE40, MCS11		-56	-55	-55	-53	
	HE80, MCS0		-87	-85	-84	-83	
	HE80, MCS7		-68	-67	-65	-64	
	HE80, MCS8		-64	-63	-62	-60	
	HE80, MCS9		-62	-61	-60	-58	
	HE80, MCS11		-54	-54	-52	-51	
ACI - OFDM [Difference between interfering and desired signal (20 MHz apart)]	6 Mbps	See Note ¹	25	25	25	25	dB
ACI - MCS0-11 [Difference between interfering and desired signal (20 MHz apart)]	MCS0	See Note ¹	25	25	25	25	
	MCS7		5	5	5	5	
	MCS9		TBD	TBD	TBD	TBD	
	MCS11		TBD	TBD	TBD	TBD	
ACI - MCS0-11 [Difference between interfering and desired signal (40 MHz apart)]	MCS0	See Note ¹	24	24	24	24	
	MCS7		5	5	5	5	
	MCS9		TBD	TBD	TBD	TBD	
	MCS11		TBD	TBD	TBD	TBD	

Note 1: Performance data are measured in single chain operation.

8.5 WLAN Transmitter Characteristics

Table 12 through Table 21 summarize the Sona IF573 series wireless module transmitter characteristics.

Table 12: WLAN transmitter characteristics for 2.4 GHz operation (VBAT = 3.3V, VDDIO = 1.8V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Ftx	Transmit output frequency range	—	2.402	—	2.484	GHz
Pout	Output power	See Note ²	—	—	—	—
	11b mask compliant	1-11Mbps	—	17	—	dBm
	11g mask compliant	6-48Mbps	—	16.5	—	
	11g EVM compliant	54Mbps	—	16	—	
	11n HT20 mask compliant	MCS0-4	—	16	—	
	11n HT20 EVM compliant	MCS5-7	—	15	—	
	11ax HE20 mask compliant	MCS0-4	—	16	—	
	11ax HE20 EVM compliant	MCS5-7	—	15	—	
	11ax HE20 EVM compliant	MCS8-9	—	12.5	—	
	11ax HE20 EVM compliant	MCS10-11	—	10.5	—	
ATx	Transmit power accuracy at 25 °C	—	-2.0	—	+2.0	dB

Table 13: WLAN current consumption on 2.4 GHz (VBAT = 3.3V, VDDIO = 1.8V, BT_REG_ON = Low)

Modulation	Data Rate	Spatial Stream	Output Power (dBm)	VBAT Current Consumption (mA)	VIO Current Consumption (mA)
CCK	1 Mbps	1	19	272	5.6
BPSK	6 Mbps	1	18.5	261	3.6
64-QAM	HT20 MCS7	1	17	244	4.1
64-QAM	HT20 MCS15	2	17	439	5.0
256-QAM	HE20 MCS9	2	14.5	393	5.4
1024-QAM	HE20 MCS11	2	12.5	358	4.9

Table 14: WLAN transmitter characteristics for 5 GHz operation (VBAT=3.3V, VDDIO=1.8V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Ftx	Transmit output frequency range	—	5.15	—	5.925	GHz
Pout	Output power	See Note ²	—	—	—	—
	11a mask compliant	6-36Mbps	—	16.5	—	dBm
	11a EVM compliant	48-54Mbps	—	16	—	
	11n HT20 mask compliant	MCS0-4	—	16.5	—	
	11n HT20 EVM compliant	MCS5-7	—	16	—	
	11n HT40 mask compliant	MCS0-4	—	16	—	
	11n HT40 EVM compliant	MCS5-7	—	15	—	
	11ac VHT20 mask compliant	MCS0-4	—	16.5	—	
	11ac VHT20 EVM compliant	MCS5-7	—	16	—	
	11ac VHT20 EVM compliant	MCS8	—	14	—	
	11ac VHT40 mask compliant	MCS0-4	—	16	—	
	11ac VHT40 EVM compliant	MCS5-7	—	15	—	
	11ac VHT40 EVM compliant	MCS8-9	—	12	—	
	11ac VHT80 mask compliant	MCS0-4	—	16	—	
	11ac VHT80 EVM compliant	MCS5-7	—	15	—	
	11ac VHT80 EVM compliant	MCS8-9	—	12	—	
	11ax HE20 mask compliant	MCS0-4	—	16.5	—	
	11ax HE20 EVM compliant	MCS5-7	—	16	—	
	11ax HE20 EVM compliant	MCS8-9	—	14	—	
	11ax HE20 EVM compliant	MCS10-11	—	13	—	
	11ax HE40 mask compliant	MCS0-4	—	16	—	
	11ax HE40 EVM compliant	MCS5-7	—	15	—	
	11ax HE40 EVM compliant	MCS8-9	—	12	—	
	11ax HE40 EVM compliant	MCS10-11	—	11.5	—	
	11ax HE80 mask compliant	MCS0-4	—	16	—	
	11ax HE80 EVM compliant	MCS5-7	—	15	—	
	11ax HE80 EVM compliant	MCS8-9	—	12	—	
	11ax HE80 EVM compliant	MCS10-11	—	11	—	
ATx	Transmit power accuracy at 25 °C	—	-2.0	—	+2.0	dB

Table 15: WLAN current consumption on 5 GHz (VBAT = 3.3V, VDDIO = 1.8V, BT_REG_ON = Low)

Modulation	Bandwidth (MHz)	Data Rate	Spatial Stream	Output Power (dBm)	VBAT Current Consumption (mA)	VIO Current Consumption (mA)
BPSK	20	6 Mbps	1	18.5	401	3.6
64-QAM	20	54 Mbps	1	18	384	3.3
BPSK	20	MCS0	2	18.5	715	6.3
64-QAM	20	MCS7	2	18	720	5.8
256-QAM	20	MCS9	2	16	655	6.9
1024-QAM	20	MCS11	2	15	631	7.2
BPSK	40	MCS0	2	18	715	5.0
64-QAM	40	MCS7	2	17	700	4.5
256-QAM	40	MCS9	2	14	604	5.5
1024-QAM	40	MCS11	2	13.5	595	5.9
BPSK	80	MCS0	2	18	761	4.0
64-QAM	80	MCS7	2	17	730	3.7
256-QAM	80	MCS9	2	14	656	4.3
1024-QAM	80	MCS11	2	13	635	4.6

Table 16: WLAN transmitter characteristics for UNII-5 and UNII-6 operation (VBAT = 3.3V, VDDIO = 1.8V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Ftx	Transmit output frequency range	—	5.925	—	6.53	GHz
Pout	Output power	See Note ²	—	—	—	—
	11a mask compliant	6-24Mbps	—	15.5	—	dBm
	11ax HE20 mask compliant	MCS0-6	—	15.5	—	
	11ax HE20 EVM compliant	MCS7	—	15	—	
	11ax HE20 EVM compliant	MCS8	—	14.5	—	
	11ax HE20 EVM compliant	MCS9-11	—	12	—	
	11ax HE40 mask compliant	MCS0-6	—	15.5	—	
	11ax HE40 EVM compliant	MCS7	—	14	—	
	11ax HE40 EVM compliant	MCS8	—	12.5	—	
	11ax HE40 EVM compliant	MCS9	—	12	—	
	11ax HE40 EVM compliant	MCS10-11	—	11	—	
	11ax HE80 mask compliant	MCS0-6	—	15	—	
	11ax HE80 EVM compliant	MCS7	—	14	—	
	11ax HE80 EVM compliant	MCS8	—	12	—	
	11ax HE80 EVM compliant	MCS9	—	11	—	
	11ax HE80 EVM compliant	MCS10-11	—	10	—	
ATx	Transmit power accuracy at 25 °C	—	-2.0	—	+2.0	dB

Table 17: WLAN current consumption on UNII-5 band (VBAT = 3.3V, VDDIO = 1.8V, BT_REG_ON = Low)

Modulation	Bandwidth (MHz)	Data Rate	Spatial Stream	Output Power (dBm)	VBAT Current Consumption (mA)	VIO Current Consumption (mA)
BPSK	20	6 Mbps	1	17.5	326	4.3
64-QAM	20	24 Mbps	1	17.5	336	3.6
BPSK	20	MCS0	2	17.5	631	6.5
64-QAM	20	MCS7	2	17	645	5.8
256-QAM	20	MCS9	2	14	548	5.1
1024-QAM	20	MCS11	2	14	536	4.8
BPSK	40	MCS0	2	17.5	638	4.9
64-QAM	40	MCS7	2	16	587	4.5
256-QAM	40	MCS9	2	14	534	4.1
1024-QAM	40	MCS11	2	13	518	3.8
BPSK	80	MCS0	2	17	691	4.1
64-QAM	80	MCS7	2	16	659	3.8
256-QAM	80	MCS9	2	13	571	4.5
1024-QAM	80	MCS11	2	12	558	4.2

Table 18: WLAN current consumption on UNII-6 band (VBAT = 3.3V, VDDIO = 1.8V, BT_REG_ON = Low)

Modulation	Bandwidth (MHz)	Data Rate	Spatial Stream	Output Power (dBm)	VBAT Current Consumption (mA)	VIO Current Consumption (mA)
BPSK	20	6 Mbps	1	17.5	341	4.4
64-QAM	20	24 Mbps	1	17.5	343	3.6
BPSK	20	MCS0	2	17.5	631	6.3
64-QAM	20	MCS7	2	17	637	5.9
256-QAM	20	MCS9	2	14	535	5.3
1024-QAM	20	MCS11	2	14	534	4.9
BPSK	40	MCS0	2	17.5	634	5.1
64-QAM	40	MCS7	2	16	581	4.6
256-QAM	40	MCS9	2	14	530	5.8
1024-QAM	40	MCS11	2	13	511	5.4
BPSK	80	MCS0	2	17	695	4.1
64-QAM	80	MCS7	2	16	666	5.0
256-QAM	80	MCS9	2	13	578	4.6
1024-QAM	80	MCS11	2	12	555	4.2

Table 19: WLAN transmitter characteristics for UNII-7 and UNII-8 operation (VBAT = 3.3V, VDDIO = 1.8V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Ftx	Transmit output frequency range	—	6.53	—	7.125	GHz
Pout	Output power	See Note ²	—	—	—	—
	11a mask compliant	6-24Mbps	—	15	—	dBm
	11ax HE20 mask compliant	MCS0-6	—	15	—	
	11ax HE20 EVM compliant	MCS7	—	13	—	
	11ax HE20 EVM compliant	MCS8	—	12	—	
	11ax HE20 EVM compliant	MCS9-11	—	10.5	—	
	11ax HE40 mask compliant	MCS0-6	—	15	—	
	11ax HE40 EVM compliant	MCS7	—	12	—	
	11ax HE40 EVM compliant	MCS8	—	11	—	
	11ax HE40 EVM compliant	MCS9	—	10	—	
	11ax HE40 EVM compliant	MCS10-11	—	8.5	—	
	11ax HE80 mask compliant	MCS0-6	—	14.5	—	
	11ax HE80 EVM compliant	MCS7	—	11	—	
	11ax HE80 EVM compliant	MCS8	—	10	—	
	11ax HE80 EVM compliant	MCS9-11	—	8.5	—	
ATx	Transmit power accuracy at 25 °C	—	-2.0	—	+2.0	dB

Table 20: WLAN current consumption on UNII-7 band (VBAT = 3.3V, VDDIO = 1.8V, BT_REG_ON = Low)

Modulation	Bandwidth (MHz)	Data Rate	Spatial Stream	Output Power (dBm)	VBAT Current Consumption (mA)	VIO Current Consumption (mA)
BPSK	20	6 Mbps	1	17	321	4.4
64-QAM	20	24 Mbps	1	17	322	3.7
BPSK	20	MCS0	2	17	615	6.4
64-QAM	20	MCS7	2	15	576	5.9
256-QAM	20	MCS9	2	12.5	518	5.3
1024-QAM	20	MCS11	2	12.5	504	4.9
BPSK	40	MCS0	2	17	643	5.1
64-QAM	40	MCS7	2	14	552	4.7
256-QAM	40	MCS9	2	12	512	4.3
1024-QAM	40	MCS11	2	10.5	483	5.4
BPSK	80	MCS0	2	16.5	681	4.2
64-QAM	80	MCS7	2	13	590	5.0
256-QAM	80	MCS9	2	12	571	4.5
1024-QAM	80	MCS11	2	10.5	540	4.7

Table 21: WLAN current consumption on UNII-8 band (VBAT = 3.3V, VDDIO = 1.8V, BT_REG_ON = Low)

Modulation	Bandwidth (MHz)	Data Rate	Spatial Stream	Output Power (dBm)	VBAT Current Consumption (mA)	VIO Current Consumption (mA)
BPSK	20	6 Mbps	1	17	335	4.4
64-QAM	20	24 Mbps	1	17	333	3.7
BPSK	20	MCS0	2	17	630	6.3
64-QAM	20	MCS7	2	15	585	5.8
256-QAM	20	MCS9	2	12.5	521	5.2
1024-QAM	20	MCS11	2	12.5	526	6.7
BPSK	40	MCS0	2	17	637	5.0
64-QAM	40	MCS7	2	14	544	4.6
256-QAM	40	MCS9	2	12	516	4.4
1024-QAM	40	MCS11	2	10.5	480	5.5
BPSK	80	MCS0	2	16.5	661	4.1
64-QAM	80	MCS7	2	13	582	4.9
256-QAM	80	MCS9	2	12	569	4.5
1024-QAM	80	MCS11	2	10.5	541	4.7

Note 2: Final TX power values on each channel are limited by regulatory requirements.

9 Bluetooth Radio Characteristics

Table 22 through Table 26 describe the performance of the Bluetooth transmitter and receiver and the current consumption at 25°C.

Table 22: BR / EDR transmitter performance (VBAT = 3.3V, VDDIO = 1.8V)

Test Parameter		Min	Typ	Max	BT Spec.	Unit
Maximum RF Output Power	GFSK	—	—	7	0 ~ +20	dBm
	$\pi/4$ -DQPSK	—	3	—		
	8-DPSK	—	3	—		
Frequency Range		2.4	—	2.4835	$2.4 \leq f \leq 2.4835$	GHz
20 dB Bandwidth		—	914.5	—	≤ 1000	KHz
Δf_{1avg} Maximum Modulation		140	154	175	$140 < \Delta f_{1avg} < 175$	KHz
Δf_{2max} Minimum Modulation		115	147	—	≥ 115	KHz
$\Delta f_{2avg}/\Delta f_{1avg}$		—	0.95	—	≥ 0.80	—
Initial Carrier Frequency		—	± 25	± 75	$\leq \pm 75$	KHz
Frequency Drift (DH1 packet)		—	± 8	± 25	± 25	KHz
Frequency Drift (DH3 packet)		—	± 8	± 40	± 40	KHz
Frequency Drift (DH5 packet)		—	± 8	± 40	± 40	KHz
Drift rate		—	5	20	20	KHz/50us
EDR ω_i		—	—	± 75	$\leq \pm 75$	KHz
EDR ω_0		—	—	± 10	$\leq \pm 10$	KHz
EDR ($\omega_i + \omega_0$)		—	—	± 75	$\leq \pm 75$	KHz
RMS DEVM for $\pi/4$ -DQPSK		—	—	≤ 0.2	≤ 0.2	—
RMS DEVM for 8-DPSK		—	—	≤ 0.13	≤ 0.13	—
Peak DEVM for $\pi/4$ -DQPSK		—	—	≤ 0.35	≤ 0.35	—
Peak DEVM for 8-DPSK		—	—	≤ 0.25	≤ 0.25	—
99% DEVM for $\pi/4$ -DQPSK		—	—	≤ 0.30	≤ 0.30	—
99% DEVM for 8-DPSK		—	—	≤ 0.20	≤ 0.20	—
EDR In-Band Spurious Emission	IM-NI ≥ 2.5 MHz	—	-43	-40	< -40	dBm
	1.5 MHz $<$ IM-NI $<$ 2.5 MHz	—	-31	-20	≤ -20	dBm
	1.0 MHz $<$ IM-NI $<$ 1.5 MHz	—	-38	-26	≤ -26	dBm

Table 23: Basic Rate receiver performance (VBAT = 3.3V, VDDIO = 1.8V)

Test Parameter		Min	Typ	Max	Bluetooth Spec.	Unit
Sensitivity (1DH5)	BER ≤ 0.1%	—	-91	—	≤ -70	dBm
Maximum Input	BER ≤ 0.1%	—	—	-20	≥ -20	dBm
Interference Performance	Co-Channel	—	8.5	11	11	dB
	C/I 1 MHz adjacent channel	—	-1.4	0	0	dB
	C/I 2 MHz adjacent channel	—	-41	-30	-30	dB
	C/I ≥ 3 MHz adjacent channel	—	-42.5	-40	-40	dB
	C/I image channel	—	-31.5	-9	-9	dB
	C/I 1-MHz adjacent to image channel	—	-44.5	-20	-20	dB

Table 24: Enhanced Data Rate receiver performance (VBAT = 3.3V, VDDIO = 1.8V)

Test Parameter		Min	Typ	Max	Bluetooth Spec.	Unit
Sensitivity (BER ≤ 0.01%)	π/4-DQPSK	—	-93	—	≤ -70	dBm
	8-DPSK	—	-87	—	≤ -70	dBm
Maximum Input (BER ≤ 0.1%)	π/4-DQPSK	—	—	-20	≥ -20	dBm
	8-DPSK	—	—	-20	≥ -20	dBm
C/I Co-Channel (BER ≤ 0.1%)	π/4-DQPSK	—	10.5	13	≤ ±13	dB
	8-DPSK	—	18	21	≤ ±21	dB
C/I 1 MHz adjacent Channel	π/4-DQPSK	—	-6.5	0	≤ 0	dB
	8-DPSK	—	-1	5	≤ 5	dB
C/I 2 MHz adjacent Channel	π/4-DQPSK	—	-38.5	-30	≤ -30	dB
	8-DPSK	—	-36.5	-25	≤ -25	dB
C/I ≥ 3 MHz adjacent Channel	π/4-DQPSK	—	-42.5	-40	≤ -40	dB
	8-DPSK	—	-41.5	-33	≤ -33	dB
C/I image channel	π/4-DQPSK	—	-30	-7	≤ -7	dB
	8-DPSK	—	-22.5	0	≤ 0	dB
C/I 1 MHz adjacent to image channel	π/4-DQPSK	—	-47.5	-20	≤ -20	dB
	8-DPSK	—	-41.5	-13	≤ -13	dB
Out-of-Band Blocking Performance (CW) BER ≤ 0.1%	30-2000MHz	—	-10	—	—	dBm
	2-2.399GHz	—	-27	—	—	dBm
	2.484-3GHz	—	-27	—	—	dBm
	3-12.75GHz	—	-10	—	—	dBm

Table 25: BLE RF Specifications (VBAT = 3.3V, VDDIO = 1.8V)

Parameter	Conditions		Min	Typ	Max	Unit
Frequency range	—		2402	—	2480	MHz
Rx sensitivity ¹	GFSK, PER ≤ 30.8%	1 Mbps	—	-95	—	dBm
		2 Mbps	—	-92	—	dBm
		500 Kbps	—	-102	—	dBm
		125 Kbps	—	-107	—	dBm
Tx power ²	—		—	—	7	dBm
Δf1 average	1 Mbps		225	255	275.5	KHz
	2 Mbps		450	500	550	KHz
	125 Kbps		225	255	275	KHz
Δf2 average	1 Mbps		185	230	—	KHz
Δf2 maximum ³	2 Mbps		370	450	—	KHz
Δf1 average (Stable Modulation)	1 Mbps		247.5	250	252.5	KHz
	2 Mbps		495	500	550	KHz
	125 Kbps		247.5	250	252.5	KHz
$\frac{\Delta f2 \text{ avg}}{\Delta f1 \text{ avg}}$ ratio	1 Mbps		0.8	1.0	—	%
	2 Mbps		0.8	1.0	—	%

Table 26: Bluetooth transmitter current consumption (VBAT = 3.3V, VDDIO = 1.8V, WL_REG_ON = OFF)

Operation Mode	Data Rate	VBAT Current Consumption (mA)	VIO Current Consumption (mA)
Basic Data Rate	1DH5	18.9	0.76
Enhanced Data Rate	2DH5	18.4	0.77
	3DH5	18.3	0.77
Low-Energy	1 Mbps	20.3	0.76
	2 Mbps	13.4	0.71
	500 Kbps	17.9	0.75
	125 Kbps	23.6	0.78

Notes:

[1] Dirty Tx is Off.

[2] The Bluetooth LE TX power cannot exceed 10 dBm EIRP specification limit. The front-end losses and antenna gain/loss must be factored in so as not to exceed the limit.

[3] At least 99.9% of all Δf2 maximum frequency values recorded over 10 packets must be greater than 185 KHz.

10 Crystal Oscillator Requirement

Table 27: Crystal Oscillator Specification

32.768 KHz Oscillator	
Frequency Accuracy	200 ppm
Duty Cycle	30% – 70%
Input Signal Amplitude	200-3300 mV, peak-peak
Signal Type	Square or Sine Wave
Clock Jitter	< 10,000 ppm

IMPORTANT: A 32.768 KHz crystal is required for the module to be functional. The module will not boot without this crystal.

11 Host Interface Specifications

11.1 SDIO Specifications

The Sona IF573 series wireless module SDIO host interface pins are powered from the VDDIO voltage supply, which is set internally at 1.8V on the M.2 module. The SDIO electrical specifications are identical for the 1-bit SDIO and 4-bit SDIO modes.

Note: The SDIO host signals must be 1.8V at all times as defined by the M.2 standard.

11.1.1 Default Speed, High-Speed Modes

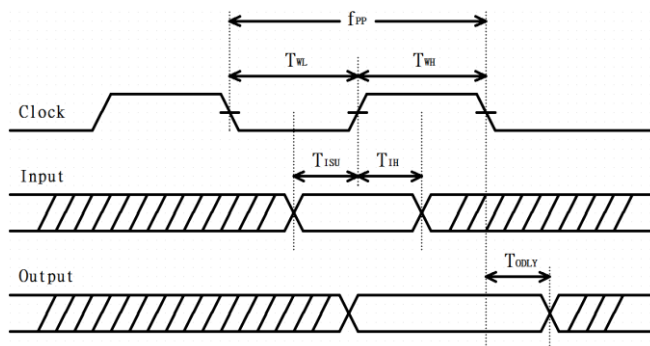


Figure 3: SDIO protocol timing diagram - Default mode (1.8V)

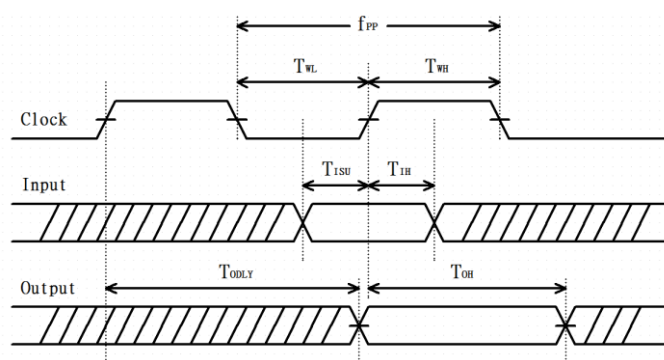


Figure 4: SDIO protocol timing diagram - High-Speed mode (1.8V)

Note: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Table 28: SDIO timing requirements

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
f _{PP}	Clock Frequency	Default Speed	0	-	25	MHz
		High-Speed	0	-	50	
TWL	Clock low time	Default Speed	10	-	-	ns
		High-Speed	7	-	-	
TWH	Clock high time	Default Speed	10	-	-	ns
		High-Speed	7	-	-	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
TISU	Input Setup time	Default Speed	5	-	-	ns
		High-Speed	6	-	-	
TIH	Input Hold time	Default Speed	5	-	-	ns
		High-Speed	2	-	-	
TODLY	Output delay time	Default Speed	-	-	14	ns
	CL≤40pF (1 card)	High-Speed	-	-	14	
TOH	Output hold time	High-Speed	0	-	-	ns

1.1.1 SDR12, SDR25, SDR50 Modes (up to 100 MHz) (1.8V)

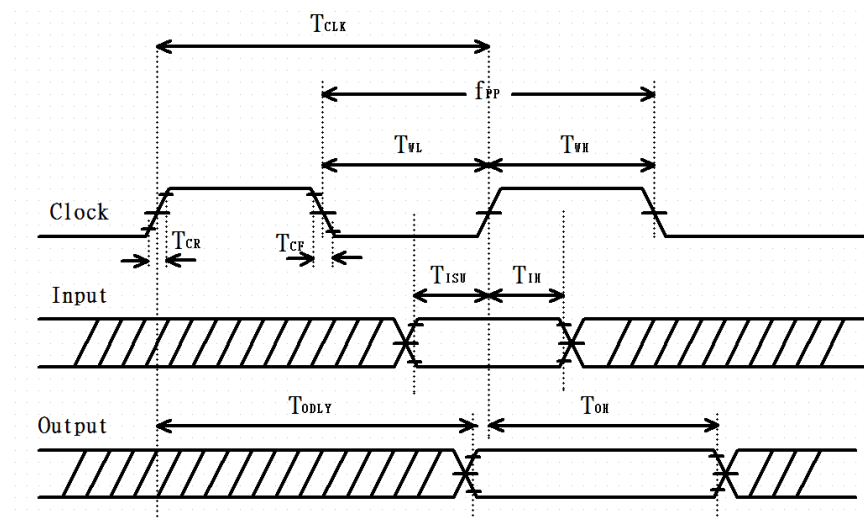


Figure 5: SDIO protocol timing Diagram – SDR12, SDR25, SDR50 modes (up to 100 MHz) (1.8V)

Note: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Table 29: SDIO timing requirements - SDR12, SDR25, SDR50 modes (up to 100 MHz) (1.8V)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
f _{PP}	Clock Frequency	SDR12/25/50	25	-	100	MHz
TISU	Input setup time	SDR12/25/50	3	--	-	ns
TIH	Input Hold time	SDR12/25/50	0.8	-	-	ns
TCLK	Clock Time	SDR12/25/50	10	-	40	ns
TCR, TCF	Raise time, Fall time TCR, TCF < 2ns (max) at 100MHz CCARD=10pF	SDR12/25/50	-	-	0.2*TCLK	ns
TODLY	Output delay time CL≤30pF	SDR12/25/50	-	-	7.5	ns
TOH	Output hold time CL=15pF	SDR12/25/50	1.5	-	-	ns

11.1.2 SDR104 Mode (208 MHz) (1.8V)

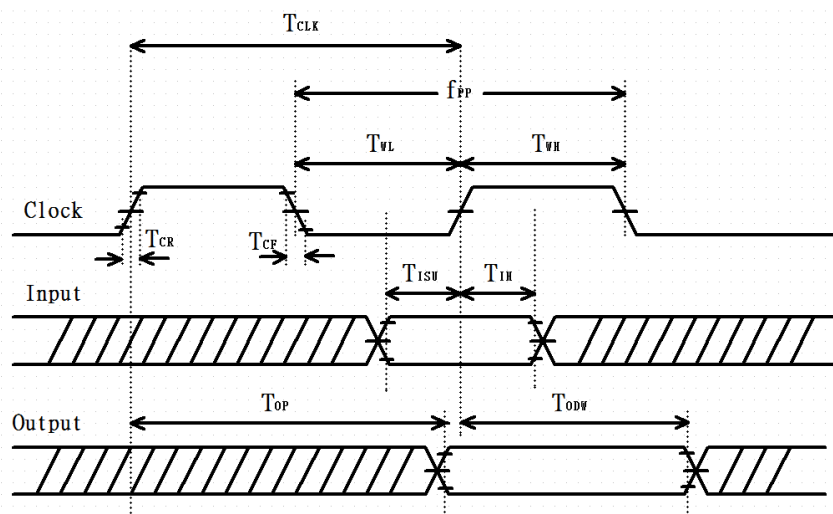


Figure 6: SDIO protocol timing Diagram - SDR104 mode (up to 208 MHz) (1.8V)

Note: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Table 30: SDIO timing requirements - SDR104 mode (up to 208MHz) (1.8V)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
fPP	Clock Frequency	SDR104	0	-	208	MHz
TISU	Input setup time	SDR104	1.4	--	-	ns
TIH	Input Hold time	SDR104	0.8	-	-	ns
TCLK	Clock Time	SDR104	4.8	-	-	ns
TCR, TCF	Raise time, Fall time TCR, TCF < 0.96ns (max) at 208MHz CCARD=10pF	SDR104	-	-	0.2*TCLK	ns
TOP	Card Output phase	SDR104	0	-	10	ns
TODW	Output timing pf variable data window	SDR12/25/50	2.88	-	-	ns

11.2 PCI Express Interface

The Sona IF573 series wireless module supports the PCIe interface, which provides high-performance serial I/O interconnects and is also protocol compliant and electrically compatible with the PCI Express Base Specification v3.0 running at Gen2 speeds.

Organization of the PCIe core is in logical layers: Transaction Layer, Data Link Layer, and Physical Layer, as shown in Figure 7. A configuration or link management block is provided for enumerating the PCIe configuration space and supporting generation and reception of System Management Messages by communicating with PCIe layers.

Each layer is partitioned into dedicated transmit and receive units that allow point-to-point communication between the host and Sona IF573 device. The transmit side processes outbound packets whereas the receive side processes inbound packets. Packets are formed and generated in the Transaction and Data Link Layer for transmission onto the high-speed links and onto the receiving device. A header is added at the beginning to indicate the packet type and any other optional fields.

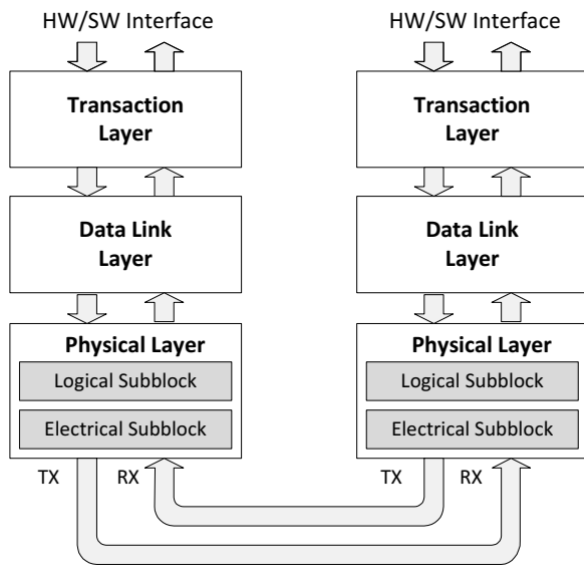


Figure 7: PCI Express Layer Model

11.3 PCM Interface Specifications

11.3.1 PCM Interface

The Sona IF573 series wireless module supports a PCM interface. The PCM interface on the Sona IF573 series wireless module can connect to linear PCM codec devices in Master/Slave mode. In Master mode, the Sona IF573 generates the BT_PCM_CLK and BT_PCM_SYNC signals, and in Slave mode, these signals are provided by another master on the PCM interface and are input to the Sona IF573 module.

The configuration of the PCM interface may be adjusted by the host through the use of vendor-specific HCI commands.

11.3.2 PCM Interface Timing

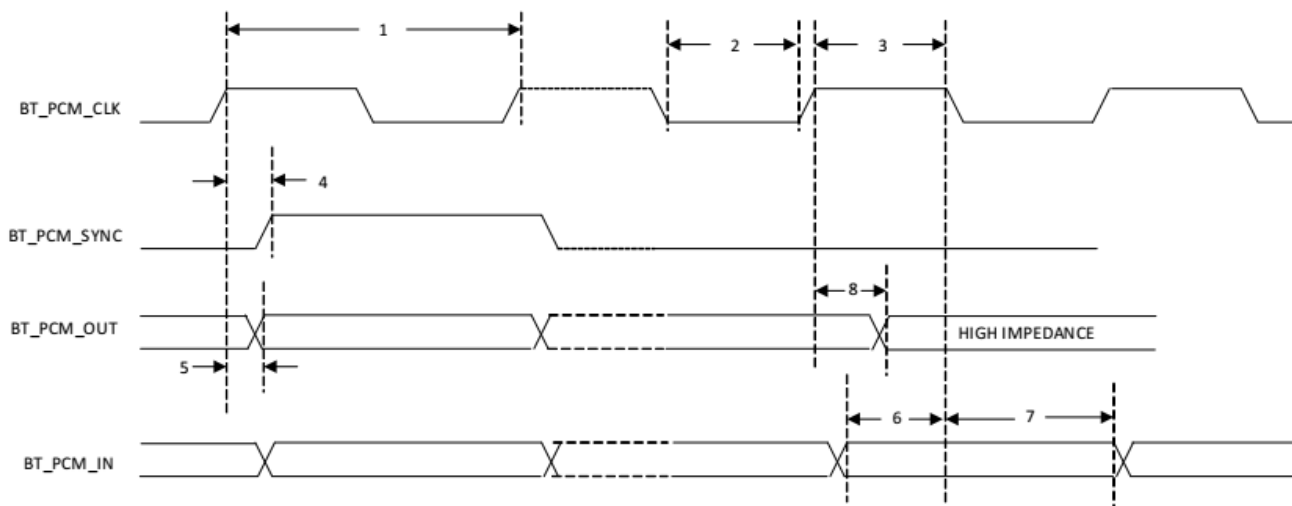


Figure 8: PCM timing specification – Short Frames Sync, Master Mode

Table 31: PCM timing specification – Short Frames Sync, Master Mode

Reference	Characteristics	Min.	Typ.	Max.	Unit
1	PCM bit clock frequency	-	-	12.0	MHz
2	PCM bit clock LOW	41.0	-	-	ns
3	PCM bit clock HIGH	41.0	-	-	ns
4	BT_PCM_SYNC delay	0	-	25.0	ns
5	BT_PCM_OUT delay	0	-	25.0	ns
6	BT_PCM_IN setup	8.0	-	-	ns
7	BT_PCM_IN hold	8.0	-	-	ns
8	Delay from rising edge of BT_PCM_CLK during last bit period to BT_PCM_OUT becoming high impedance	0	-	25.0	ns

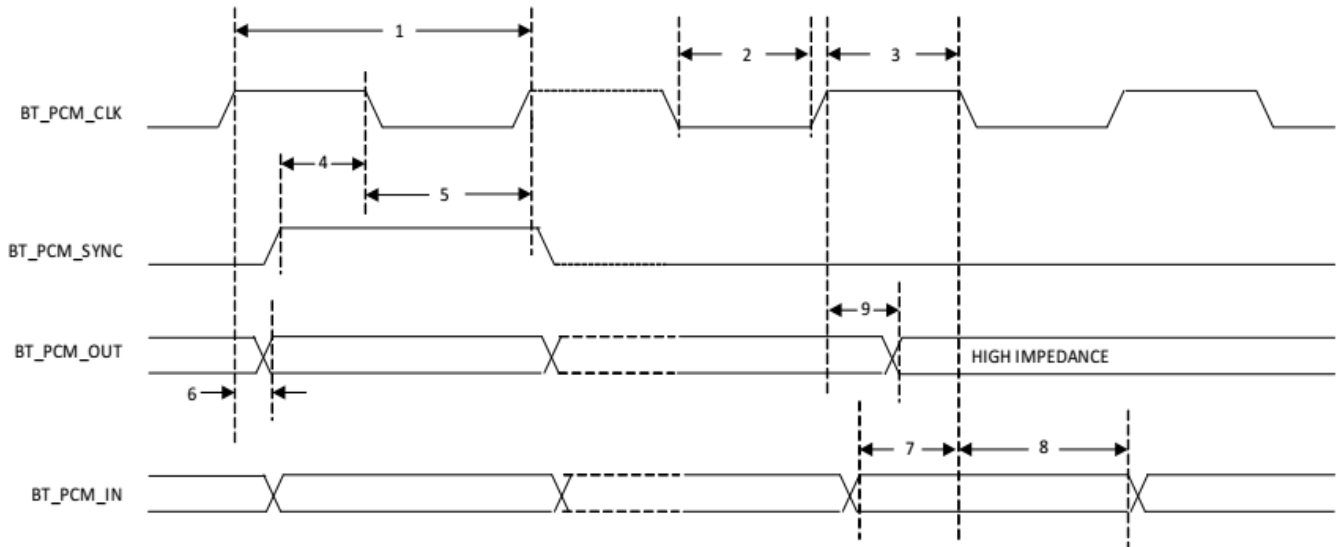


Figure 9: PCM timing specification – Short Frame Sync, Slave Mode

Table 32: PCM timing specification – Short Frame Sync, Slave Mode

Reference	Characteristics	Min.	Typ.	Max.	Unit
1	PCM bit clock frequency	-	-	12.0	MHz
2	PCM bit clock LOW	41.0	-	-	ns
3	PCM bit clock HIGH	41.0	-	-	ns
4	BT_PCM_SYNC setup	8.0	-	-	ns
5	BT_PCM_SYNC hold	8.0	-	-	ns
6	BT_PCM_OUT delay	0	-	25.0	ns
7	BT_PCM_IN setup	8.0	-	-	ns
8	BT_PCM_IN hold	8.0	-	-	ns
9	Delay from rising edge of BT_PCM_CLK during last bit period to BT_PCM_OUT becoming high impedance	0	-	25.0	ns

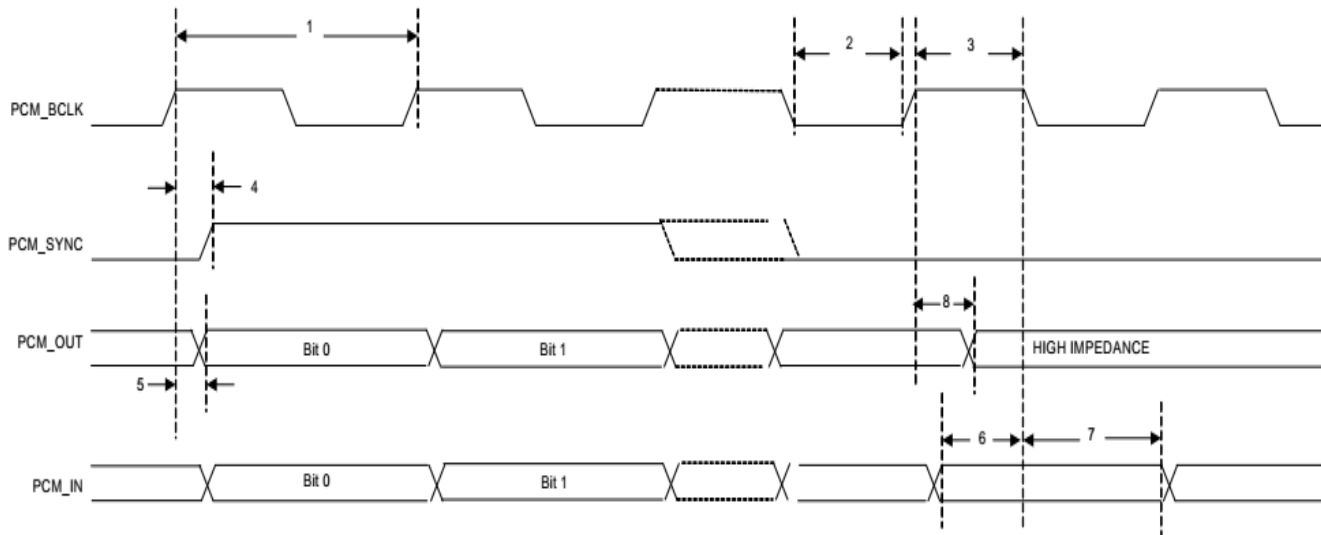


Figure 10: PCM timing specification - Long Frame Sync, Master Mode

Table 33: PCM timing specification - Long Frame Sync, Master Mode

Reference	Characteristics	Min.	Typ.	Max.	Unit
1	PCM bit clock frequency	-	-	12.0	MHz
2	PCM bit clock LOW	41.0	-	-	ns
3	PCM bit clock HIGH	41.0	-	-	ns
4	BT_PCM_SYNC delay	0	-	25.0	ns
5	BT_PCM_OUT delay	0	-	25.0	ns
6	BT_PCM_IN setup	8.0	-	-	ns
7	BT_PCM_IN hold	8.0	-	-	ns
8	Delay from rising edge of BT_PCM_CLK during last bit period to BT_PCM_OUT becoming high impedance	0	-	25.0	ns

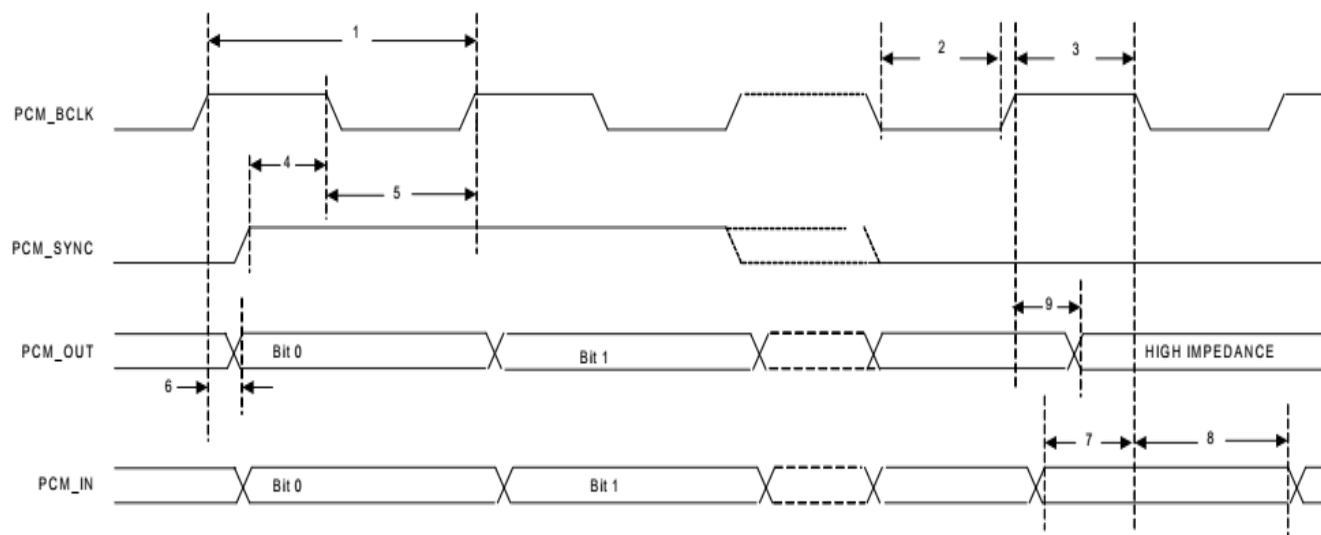


Figure 11: PCM timing specification - Long Frame Sync, Slave Mode

Table 34: PCM timing specification – Long Frame Sync, Slave Mode

Reference	Characteristics	Min.	Typ.	Max.	Unit
1	PCM bit clock frequency	-	-	12.0	MHz
2	PCM bit clock LOW	41.0	-	-	ns
3	PCM bit clock HIGH	41.0	-	-	ns
4	BT_PCM_SYNC setup	8.0	-	-	ns
5	BT_PCM_SYNC hold	8.0	-	-	ns
6	BT_PCM_OUT delay	0	-	25.0	ns
7	BT_PCM_IN setup	8.0	-	-	ns
8	BT_PCM_IN hold	8.0	-	-	ns
9	Delay from rising edge of BT_PCM_CLK during last bit period to BT_PCM_OUT becoming high impedance	0	-	25.0	ns

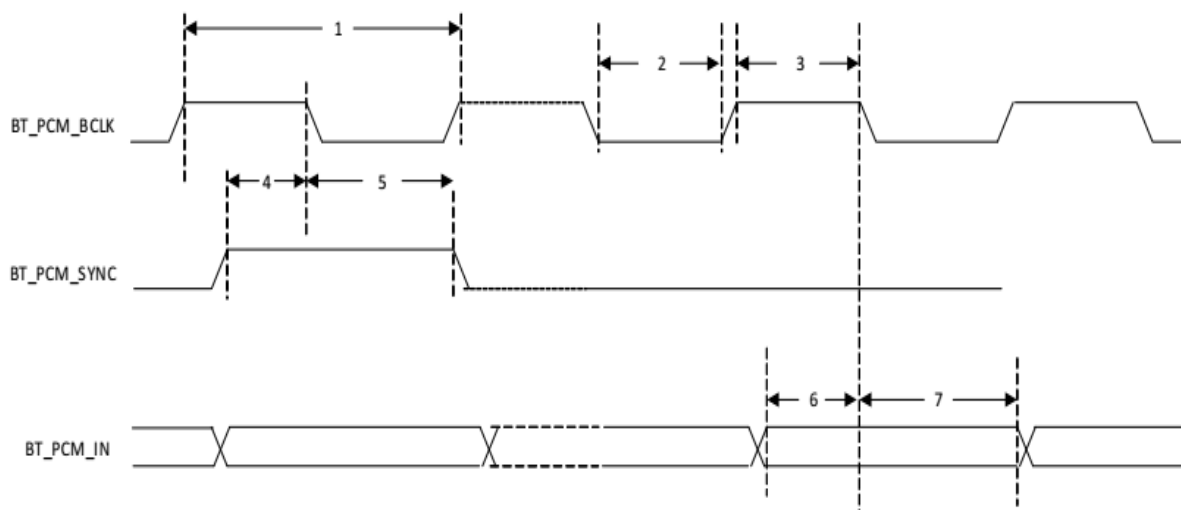


Figure 12: PCM timing specification – Short Frame Sync, Receive Only, Burst Mode

Table 35: PCM timing specification – Short Frame Sync, Receive Only, Burst Mode

Reference	Characteristics	Min.	Typ.	Max.	Unit
1	PCM bit clock frequency	-	-	24.0	MHz
2	PCM bit clock LOW	20.8	-	-	ns
3	PCM bit clock HIGH	20.8	-	-	ns
4	BT_PCM_SYNC setup	8.0	-	-	ns
5	BT_PCM_SYNC hold	8.0	-	-	ns
6	BT_PCM_IN setup	8.0	-	-	ns
7	BT_PCM_IN hold	8.0	-	-	ns

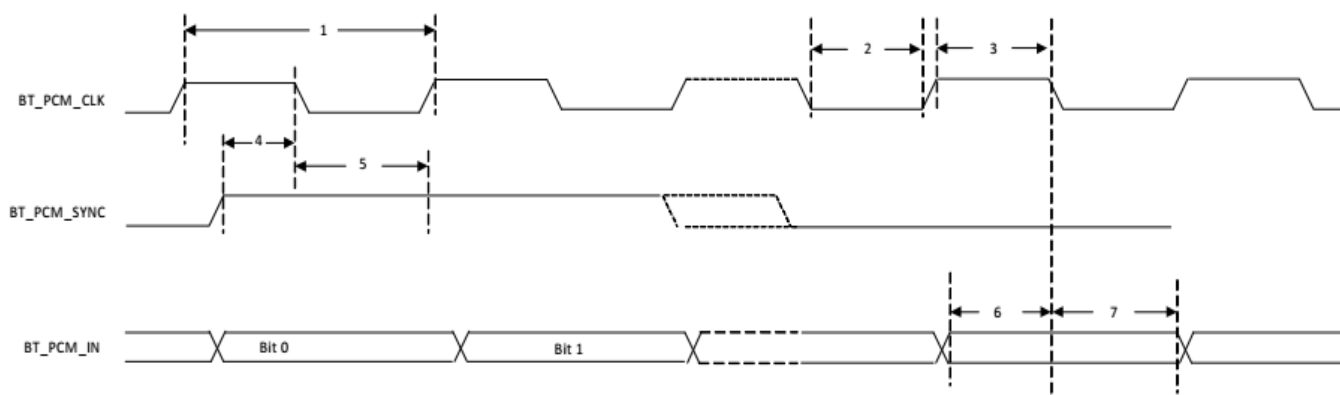


Figure 13: PCM timing specification – Long Frame Sync, Receive Only, Burst Mode

Table 36: PCM timing specification – Long Frame Sync, Receive Only, Burst Mode

Reference	Characteristics	Min.	Typ.	Max.	Unit
1	PCM bit clock frequency	-	-	24.0	MHz
2	PCM bit clock LOW	20.8	-	-	ns
3	PCM bit clock HIGH	20.8	-	-	ns
4	BT_PCM_SYNC setup	8.0	-	-	ns
5	BT_PCM_SYNC hold	8.0	-	-	ns
6	BT_PCM_IN setup	8.0	-	-	ns
7	BT_PCM_IN hold	8.0	-	-	ns

11.4 JTAG Interface

The Sona IF573 supports the JTAG interface for use with proprietary debug and characterization test tools during board bring-up.

Note: The JTAG interface is disabled by default and not exposed on the M.2 2230 E-Key interface.

12 Power-Up Sequence and Timing

Sona IF573 has two signals that allow the host to control power consumption by enabling or disabling the Bluetooth, WLAN, and internal regulator block.

12.1 Description of Control Signals

- **WL_REG_ON:** Used to power up the WLAN. When this pin is high, the internal regulators are enabled and the WLAN section is out of reset. When this pin is low the WLAN section is in reset. This signal is connected to the W_DISABLE1# pin on the M.2 interface.
- **BT_REG_ON:** Used to power up the Bluetooth section. If both the BT_REG_ON and WL_REG_ON pins are low, the regulators are disabled. When this pin is low and WL_REG_ON is high, the Bluetooth section is in reset. This signal is connected to the W_DISABLE2# pin on the M.2 interface.
- **M.2 1318** - VBAT and VDDIO should not rise 10% - 90% faster than 40 microseconds.
- **M.2 1318** - VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

12.2 Control Signal Timing Diagrams

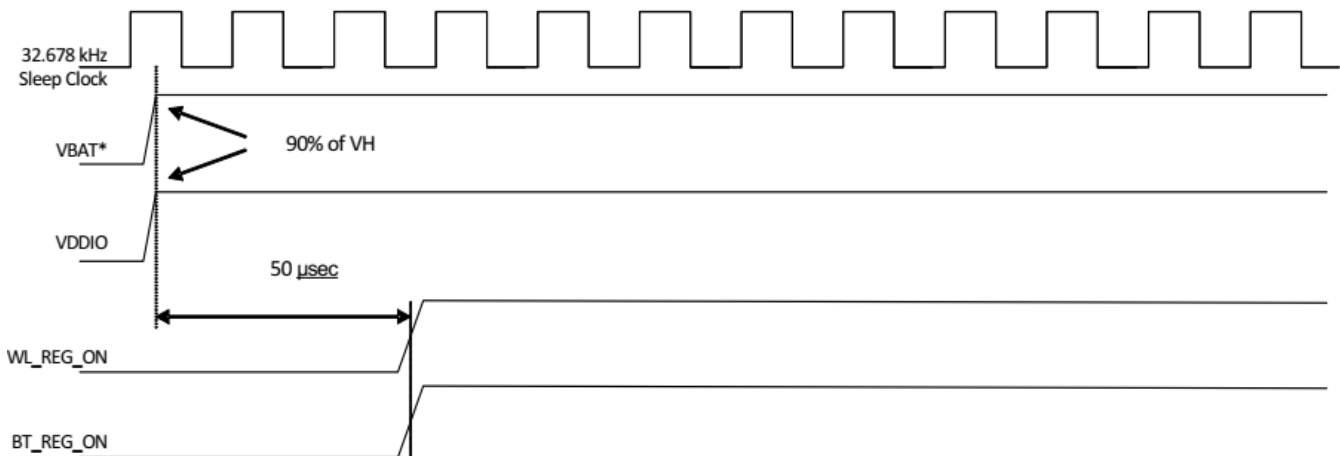


Figure 14: WL_REG_ON = ON, BT_REG_ON = ON

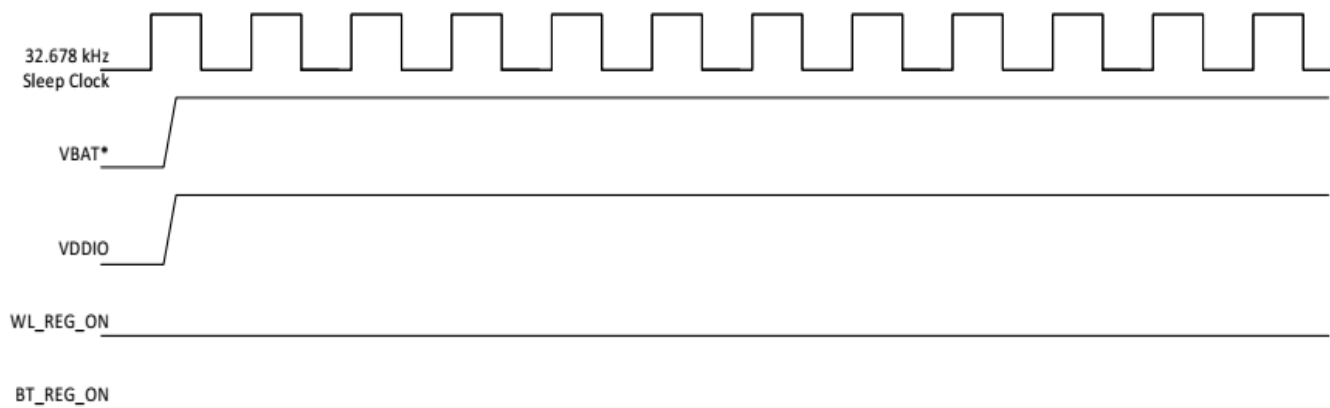


Figure 15: $WL_REG_ON = OFF$, $BT_REG_ON = OFF$

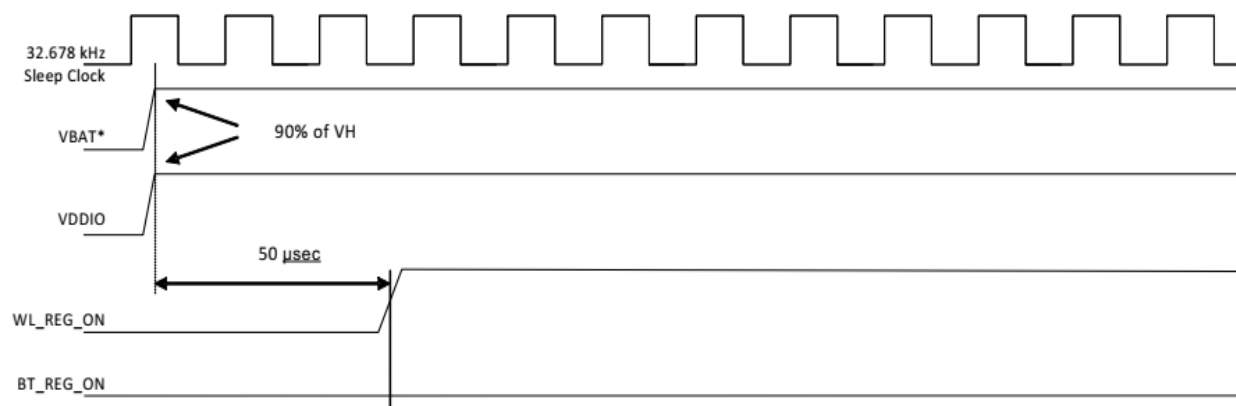


Figure 16: $WL_REG_ON = ON$, $BT_REG_ON = OFF$

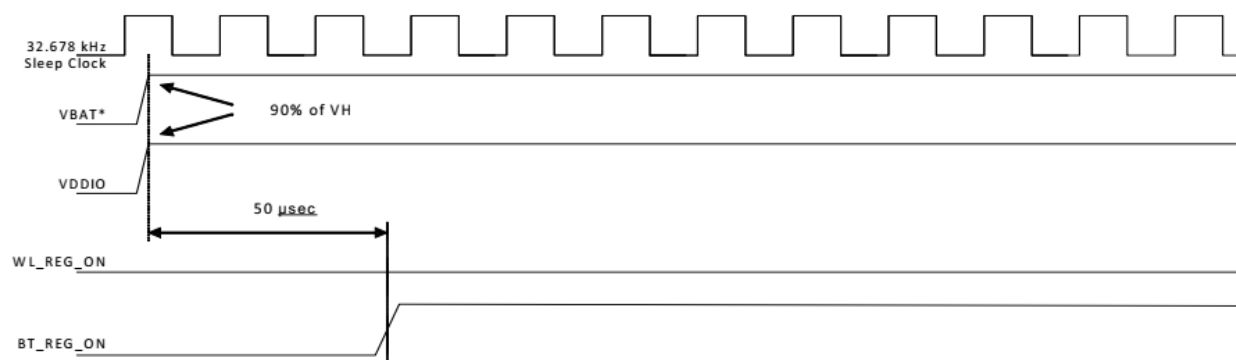


Figure 17: $WL_REG_ON = OFF$, $BT_REG_ON = ON$

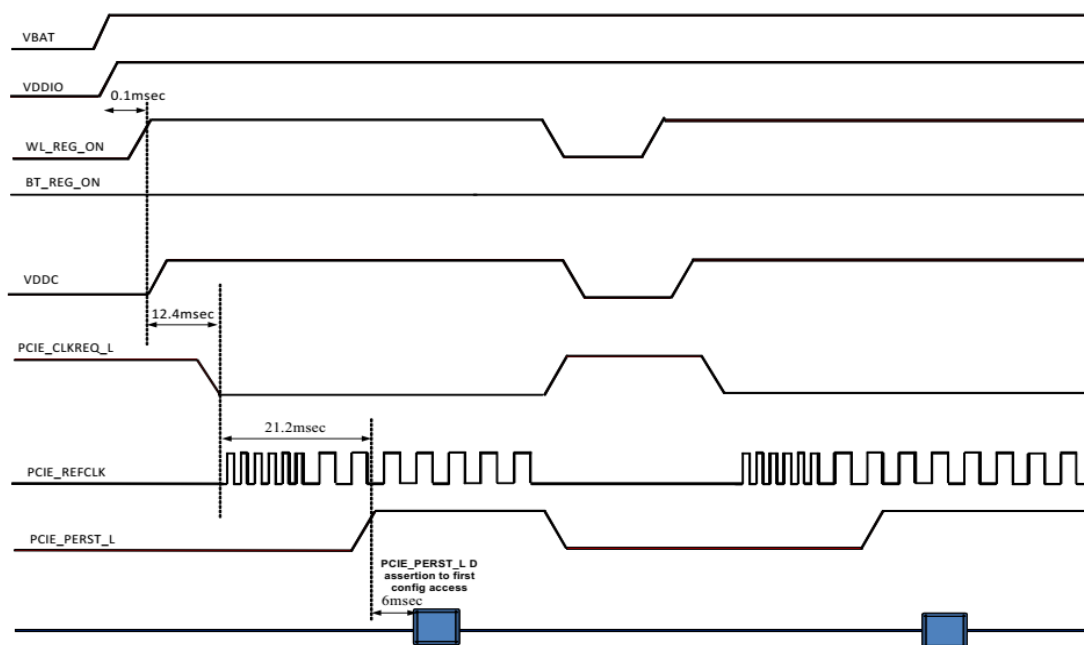


Figure 18: WLAN Power-Up Sequence for PCIe Host

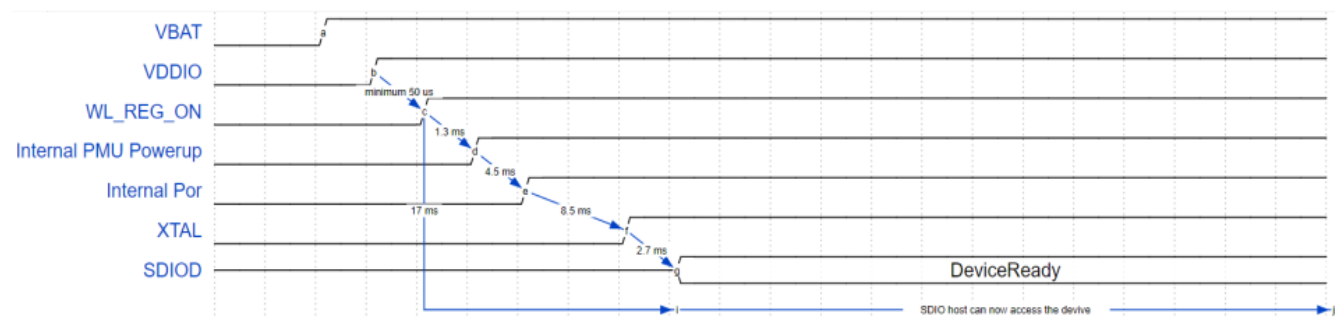


Figure 19: WLAN Boot-Up Sequence for SDIO Host

13 Pin Definitions

13.1 M.2 1318 Solder-down

Table 37: M.2 1318 pin definitions

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
1	UIM_POWER_SRC/GPIO1	-	-	NA	-
2	UIM_POWER_SNK	-	-	NA	-
3	UIM_SWP	-	-	NA	-
4	3.3V	PWR	3.3V	Power Supply Input	-
5	3.3V	PWR	3.3V	Power Supply Input	-
6	GND	-	-	Ground	GND
7	RESERVED	-	-	NA	-
8	ALERT	-	-	NA	-
9	I2C_CLK	-	-	NA	-
10	I2C_DATA	-	-	NA	-
11	COEX_RXD	I	VDDIO	WLAN_JTAG_TMS	NC
12	COEX_TXD	I	VDDIO	WLAN_JTAG_TCK	NC
13	COEX3	I	VDDIO	WLAN_JTAG_TDI	NC
14	SYSCLK/GNSS_0	-	-	NA	-
15	TX_BLANKING/GNSS_1	-	-	NA	-
16	RESERVED	-	-	NA	-
17	GND	-	-	Ground	GND
18	RESERVED	I	VDDIO	- SDIO mode: WL_DEV_WAKE - PCIe mode: Reserved	NC
19	RESERVED	O	VDDIO	WLAN_JTAG_TDO	NC
20	GND	-	-	Ground	GND
21	RESERVED	I	VDDIO	Reserved	NC
22	RESERVED	I	VDDIO	- PCIe mode: WL_DEV_WAKE - SDIO mode: Reserved	NC
23	GND	-	-	Ground	GND
24	GPIO_1	I	VDDIO	WLAN Interface Select - Pull to VDDIO for PCIe - Pull to GND for SDIO	-
25	RESERVED	I	VDDIO	JTAG_SEL Reserved Must be pulled to GND for normal operation	GND
26	GND	-	-	Ground	GND
27	SUSCLK(32kHz)	I	VDDIO	External Sleep Clock (32.768 kHz) This clock must be provided	-
28	W_DISABLE1#	I	VDDIO	This pin controls the internal WL_REG_ON signal and has an internal 50K pull-down. This pin must be driven/pulled high to enable WLAN Recommend controlling this signal via host GPIO for optimal power control.	NC

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
29	PEWAKE#	O	VDDIO	PCI power management event output. Used to request a change in the device or system power state. The assertion and de-assertion of this signal are asynchronous to the PCIe reference clock.	NC
30	CLKREQ#	O	VDDIO	PCIe clock request signal which indicates when the REFCLK to the PCIe interface can be gated. 1 = the clock can be gated. 0 = the clock is required.	NC
31	PERST#	I	VDDIO	PCIe System Reset	NC
32	GND	-	-	Ground	GND
33	REFCLKn0	I	-	PCIE Differential Pair Clock Source (100 MHz) Negative Input.	NC
34	REFCLKp0	I	-	PCIE Differential Pair Clock Source (100 MHz) Positive Input.	NC
35	GND	-	-	Ground	GND
36	PETn0	O	-	PCIE Transmitter Differential Pair Negative Output	NC
37	PETp0	O	-	PCIE Transmitter Differential Pair Positive Output	NC
38	GND	-	-	Ground	GND
39	PERn0	I	-	PCIE Receiver Differential Pair Negative Input	NC
40	PERp0	I	-	PCIE Receiver Differential Pair Positive Input	NC
41	GND	-	-	Ground	GND
42	VENDOR DEFINED	PWR	VDDIO	1.8V IO Supply for all digital I/O	-
43	VENDOR DEFINED	-	-	NA	-
44	VENDOR DEFINED	-	-	NA	-
45	SDIO RESET#	-	-	NA	-
46	SDIO WAKE#	O	VDDIO	WL_HOST_WAKE Reserved	NC
47	SDIO DATA3	I/O	VDDIO	SDIO Data line 3	NC
48	SDIO DATA2	I/O	VDDIO	SDIO Data line 2	NC
49	SDIO DATA1	I/O	VDDIO	SDIO Data line 1	NC
50	SDIO DATA0	I/O	VDDIO	SDIO Data line 0	NC
51	SDIO CMD	I/O	VDDIO	SDIO command line	NC
52	SDIO CLK	I	VDDIO	SDIO Clock Input	NC
53	UART WAKE#	O	VDDIO	BT_HOST_WAKE Reserved	NC
54	UART CTS	I	VDDIO	BT UART CTS Hardware handshake is required	-
55	UART_Tx	O	VDDIO	BT UART Transmit	-
56	UART_Rx	I	VDDIO	BT UART Receive	-
57	UART_RTS	O	VDDIO	BT UART RTS Hardware handshake is required	-

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
58	PCMFR1	I/O	VDDIO	BT_PCM Sync. Master mode: Generated by radio Slave mode: Generated by external host	NC
59	PCMIN	I	VDDIO	BT_PCM data input.	NC
60	PCMOUT	O	VDDIO	BT_PCM data output	NC
61	PCMCLK	I/O	VDDIO	BT_PCM Clock Master mode: Generated by radio Slave mode: Generated by external host	NC
62	GND	-	-	Ground	GND
63	W_DISABLE2#	I	VDDIO	This pin controls the internal BT_REG_ON signal and has an internal 50K pull-down. This pin must be controlled by host GPIO	NC
64	LED_2#	I/O	VDDIO	Reserved	NC
65	LED_1#	I/O	VDDIO	BT Interface Select/GPIO_12 This pin must be pulled high	-
66	RESERVED	I	VDDIO	BT_DEV_WAKE Reserved	NC
67	RESERVED	I	VDDIO	WLAN_JTAG_TRST Reserved	NC
68	GND	-	-	Ground	GND
69	USB_D-	-	-	NA	NC
70	USB_D+	-	-	NA	NC
71	GND	-	-	Ground	GND
72	3.3V	PWR	3.3V	Power Supply Input	-
73	3.3V	PWR	3.3V	Power Supply Input	-
74~ 78	GND	-	-	Ground	GND
79	BT_S	-	-	Bluetooth RF for trace antenna variant Unused for MHF4 antenna connector variant	-
80~ 85	GND	-	-	Ground	GND
86	WL_C0	-	-	WLAN RF Antenna 0 for trace antenna variant Unused for MHF4 antenna connector variant	
87~ 93	GND	-	-	Ground	GND
94	WL_C1	-	-	WLAN RF Antenna 1 for trace antenna variant Unused for MHF4 antenna connector variant	
95~ 96	GND	-	-	Ground	GND
G1~ G12	GND	-	-	Ground	GND

13.2 M.2 2230 E-Key

Table 38: M.2 2230 E-Key pin definitions

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
1	GND	-	-	Ground	GND
2	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.13V to 3.6V	-
3	USB_D+	-	-	NA	NC
4	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.13V to 3.6V	-
5	USB_D-	-	-	NA	NC
6	LED1#	I/O	3.3V	GPIO_12 Reserved	NC
7	GND	-	-	Ground	GND
8	PCM_CLK	I/O	1.8V	PCM clock. Can be master (Output) or slave (Input)	NC
9	SDIO CLK	I	1.8V	SDIO clock input	NC
10	PCM_SYNC	I/O	1.8V	PCM Sync. Can be master (Output) or slave (Input)	NC
11	SDIO CMD	I/O	1.8V	SDIO command line	NC
12	PCM_OUT	O	1.8V	PCM data output.	NC
13	SDIO DATA0	I/O	1.8V	SDIO data lin0	NC
14	PCM_IN	I	1.8V	PCM data input.	NC
15	SDIO DATA1	I/O	1.8V	SDIO data lin1	NC
16	LED2#	I/O	3.3V	GPIO_13 Reserved	NC
17	SDIO DATA2	I/O	1.8V	SDIO data lin2	NC
18	GND	-	-	Ground	GND
19	SDIO DATA3	I/O	1.8V	SDIO data lin3	NC
20	UART WAKE#	O	3.3V	BT_HOST_WAKE Reserved	NC
21	SDIO WAKE#	O	1.8V	WL_HOST_WAKE Reserved	NC
22	UART_TXD	O	1.8V	BT UART Transmit	NC
23	SDIO RESET#	-	-	NC	NC
32	UART_RXD	I	1.8V	BT UART Receive	NC
33	GND	-	-	Ground	GND
34	UART_RTS	O	1.8V	BT UART RTS Hardware handshake is required	NC
35	PERp0	I	-	PCIE Receiver Differential Pair Positive Input	NC
36	UART_CTS	I	1.8V	BT UART CTS Hardware handshake is required	NC
37	PERn0	I	-	PCIE Receiver Differential Pair Negative Input	NC
38	VENDER DEFINED38	O	1.8V	WLAN_JTAG_TDO Reserved	NC

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
39	GND	-	-	Ground	GND
40	VENDER DEFINED40	I	1.8V	WL_DEV_WAKE Reserved	NC
41	PETp0	O	-	PCIE Transmitter Differential Pair Positive Output	NC
42	VENDER DEFINED42	I	1.8V	BT_DEV_WAKE Reserved	NC
43	PETn0	O	-	PCIE Transmitter Differential Pair Negative Output	NC
44	COEX3	I	1.8V	WLAN_JTAG_TDI Reserved	NC
45	GND	-	-	Ground	GND
46	COEX2	I	1.8V	WLAN_JTAG_TCK Reserved	NC
47	REFCLKp0	I	-	PCIE Differential Pair Clock Source (100 MHz) Positive Input.	NC
48	COEX1	I	1.8V	WLAN_JTAG_TMS Reserved	NC
49	REFCLKn0	I	-	PCIE Differential Pair Clock Source (100 MHz) Negative Input.	NC
50	SUSCLK	I	3.3V	External Sleep Clock (32.768 kHz) This clock must be provided	-
51	GND	-	-	Ground	GND
52	PERST0#	I	3.3V	PCIe System Reset	NC
53	CLKREQ0#	O	3.3V	PCIe clock request signal which indicates when the REFCLK to the PCIe interface can be gated.	NC
54	W_DISABLE2#	I	3.3V	This pin controls the internal BT_REG_ON signal and has a 10K pull-up on the M.2 2230 module. This pin must be controlled by host GPIO	NC
55	PEWAKE0#	O	3.3V	PCI power management event output. Used to request a change in the device or system power state. The assertion and deassertion of this signal is asynchronous to the PCIe reference clock.	NC
56	W_DISABLE1#	I	3.3 V	This pin controls the internal WL_REG_ON signal and has a 10K pull-up on the M.2 2230 module. This pin must be controlled by host GPIO	NC
57	GND	-	-	Ground	GND
58	I2C DATA	-	-	NC	NC
59	RESERVED	-	-	NC	NC
60	I2C CLK	-	-	NC	NC
61	RESERVED	-	-	NC	NC
62	ALERT #	-	-	NC	NC
63	GND	-	-	Ground	GND
64	RESERVED	-	-	NC	NC
65	RESERVED	-	-	NC	NC
66	UIM_SWP	-	-	NC	NC
67	RESERVED	-	-	NC	NC

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
68	UIM_POWER_SNK	-	-	NC	NC
69	GND	-	-	Ground	GND
70	UIM_POWER_SRC	-	-	NC	NC
71	RESERVED	-	-	NC	NC
72	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.13V to 3.6V	--
73	RESERVED	-	-	NC	NC
74	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.13V to 3.6V	--
75	GND	-	-	Ground	GND

Note The transmit/receive differential pairs of the PCIe bus include "PERp0", "PERn0", "PETp0" and "PETn0", which have a built-in decoupling capacitor.

14 Host Platform Implementation Details

14.1 M.2 1318 WLAN Interface Selection

The Sona IF573 M.2 1318 module must be configured for either PCIe or SDIO WLAN interface. Configuration is done with resistor strapping as specified in [Table 39](#).

Table 39: Wi-Fi host interface configuration table

WLAN/Bluetooth Interface	GPIO_1 (Pin24)	LED_1# (Pin 65)
PCIe / UART	H	H
SDIO / UART	L	H

Note: The M.2 2230 E-Key module strapping is implemented on the M.2 carrier board.

14.2 Bluetooth Interface Requirements

The CYW55573 Bluetooth CPU core requires the UART_CTS input to be held low at the point the BT_REG_ON (W_DISABLE2#) signal goes high to enable secure firmware download. In addition, the HCI interface uses the standard H4 protocol which requires four-wire hardware handshaking.

This requires that the host implement GPIO control over BT_REG_ON/W_DISABLE2# and implement full RTS/CTS handshaking.

14.3 Low Power Clock

The Sona IF573 requires a 32KHz clock on the SUSCLK input. This clock drives various internal state machines and must be provided by the host even if low power operation is not needed.

14.4 M.2 1318 WL_DEV_WAKE Mapping

The WL_DEV_WAKE feature is mapped to different pins on the M.2 1318 module depending on the WLAN interface selection. See [Table 40](#) for details.

Table 40: M.2 1318 WL_DEV_WAKE Mapping

WLAN Interface	M.2 1318 Pin	Internal GPIO
PCIe	22	GPIO_8
SDIO	18	LHL_GPIO1

Note: This feature is subject to software support and not currently implemented.

15 Mechanical Specifications

15.1 M.2 1318

Module dimensions of Sona IF573 M.2 1318 package is 18 x 13 x 1.9 mm. Detailed drawings are shown in [Figure 20](#)

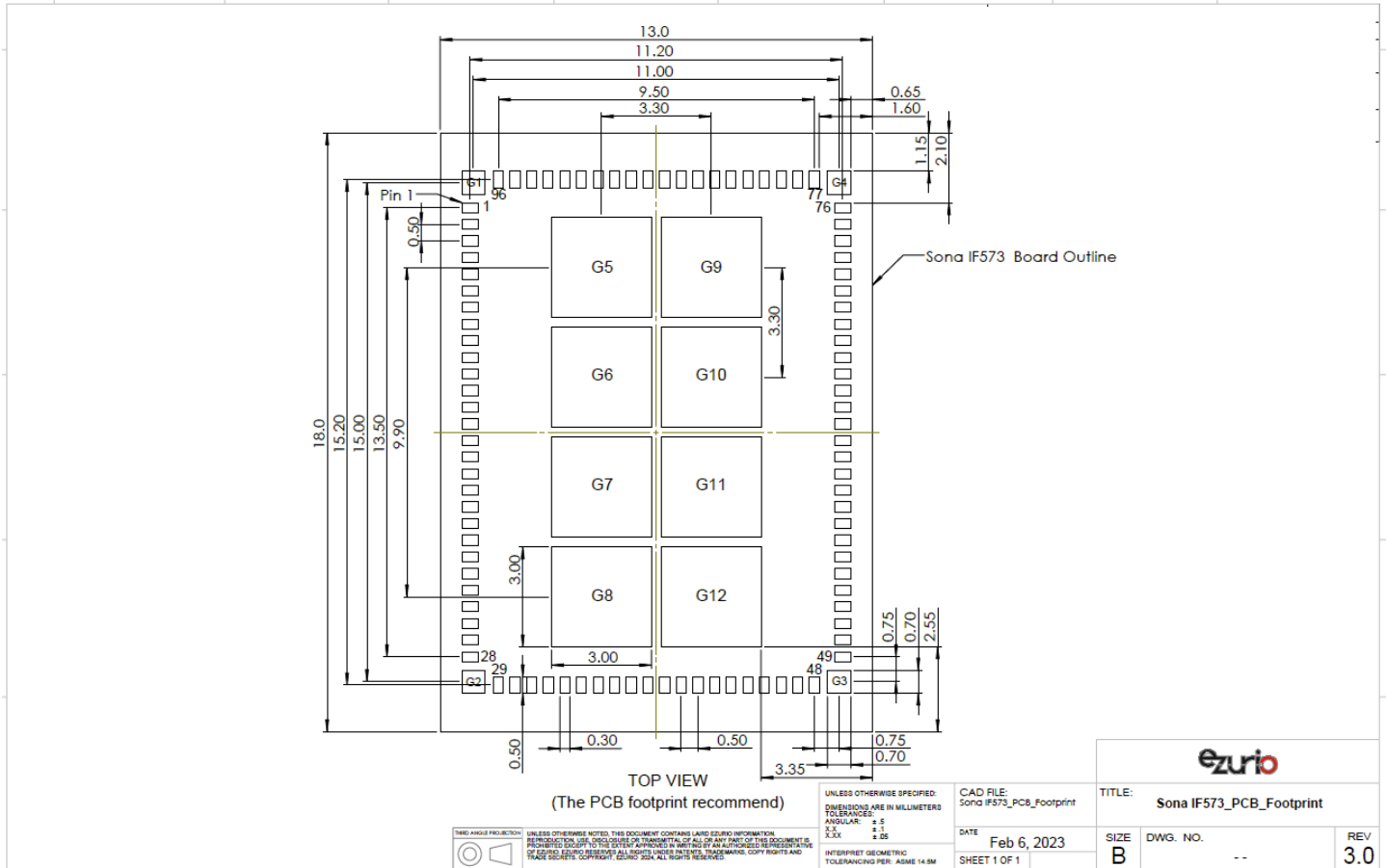


Figure 20: M.2 1318

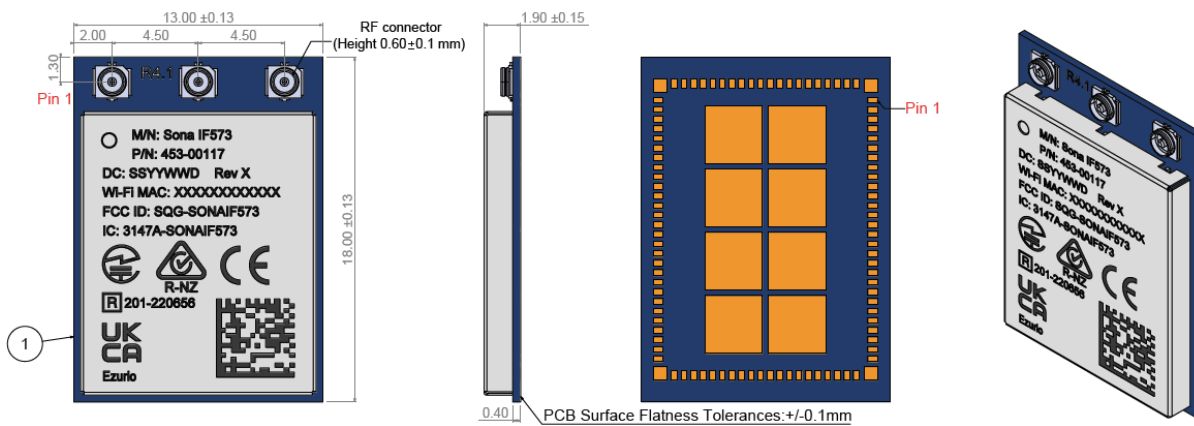


Figure 21: M.2 1318 (MHF4 variant) - Top View

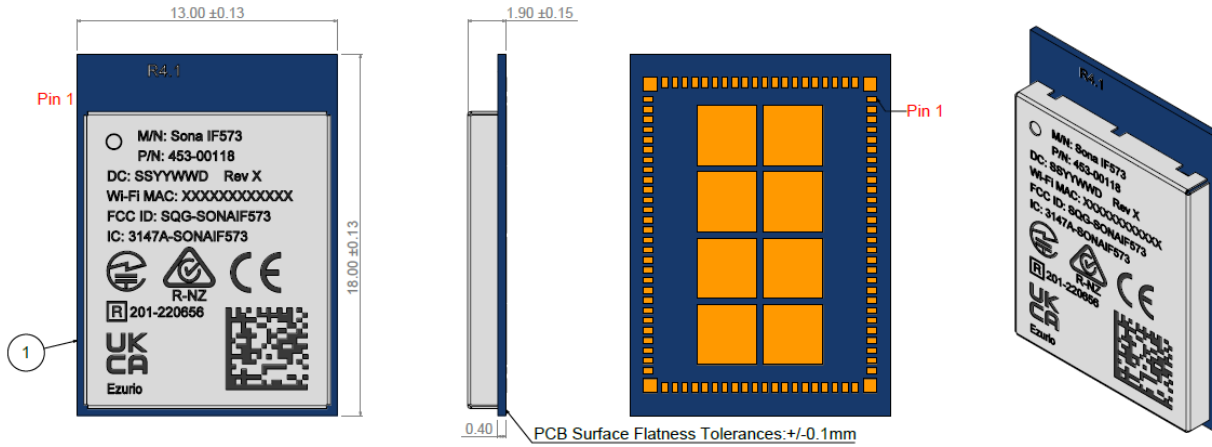


Figure 22: M.2 1318 (trace antenna variant) - Top View

15.2 M.2 2230 E-Key

Module dimensions of Sona IF573 M.2 2230 E-Key module is 22 x 30 x 2.7 mm. Detailed drawings are shown in Figure 23.

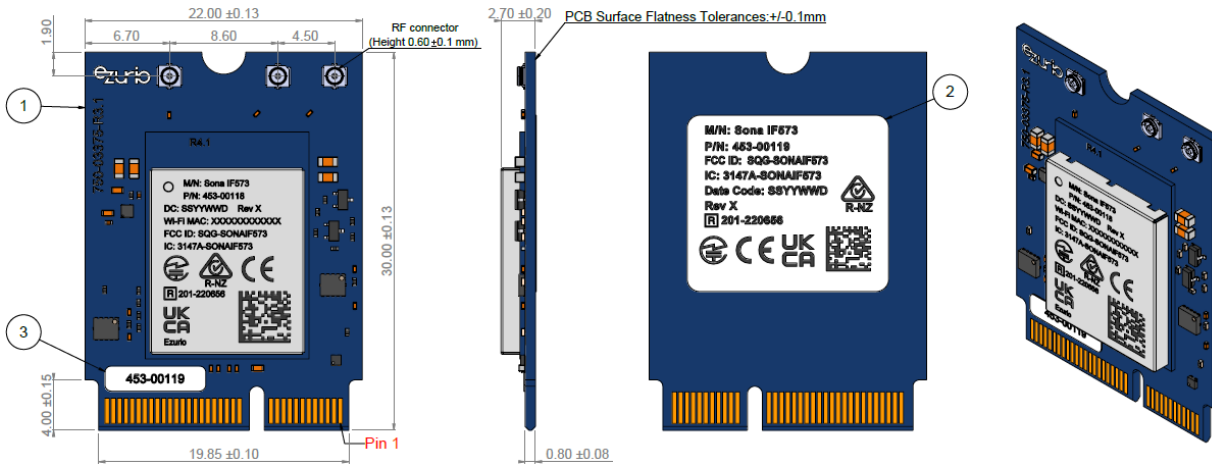


Figure 23: Sona IF573 M.2 2230

Note: The Wi-Fi MAC address is located on the product label.
The last digit of Wi-Fi MAC address is assigned to either 0, 2, 4, 6, 8, A, C, E.
The BT MAC address is the Wi-Fi MAC address plus 1.

15.3 M.2 2230 E-Key Mounting

The Sona IF573 M.2 2230 E-Key module connects to the host via a standard PCI EXPRESS M2 connector.

Kyocera's 6411 series provides 1.8mm, 2.3mm and 3.2mm connector heights. JAE's SM3 series provides 1.2mm, 2.15mm, 3.1mm and 4.1mm connector heights.

The Sona IF573 M.2 2230 E-Key module is a single-sided component module so we recommend the connectors listed in Table 41.

Table 41: Recommended M.2 2230 E-Key Connectors

M.2 Key-E Connector	Connector Height
KYOCERA 24-6411-067-101-894E	2.3 mm
JAE SM3ZS067U310AERxxxx	3.1 mm

The corresponding standoff are listed in Table 42.

Table 42: Recommended M.2 E-Key Standoffs

M.2 Key-E Connector	Stand-off
KYOCERA 24-6411-067-101-894E	EMI STOP F50M16-041525P1D4M
JAE SM3ZS067U310AERxxxx	JAE SM3ZS067U310-NUT1-Rxxxx

Detailed layout and stencil opening are show in Figure 24.

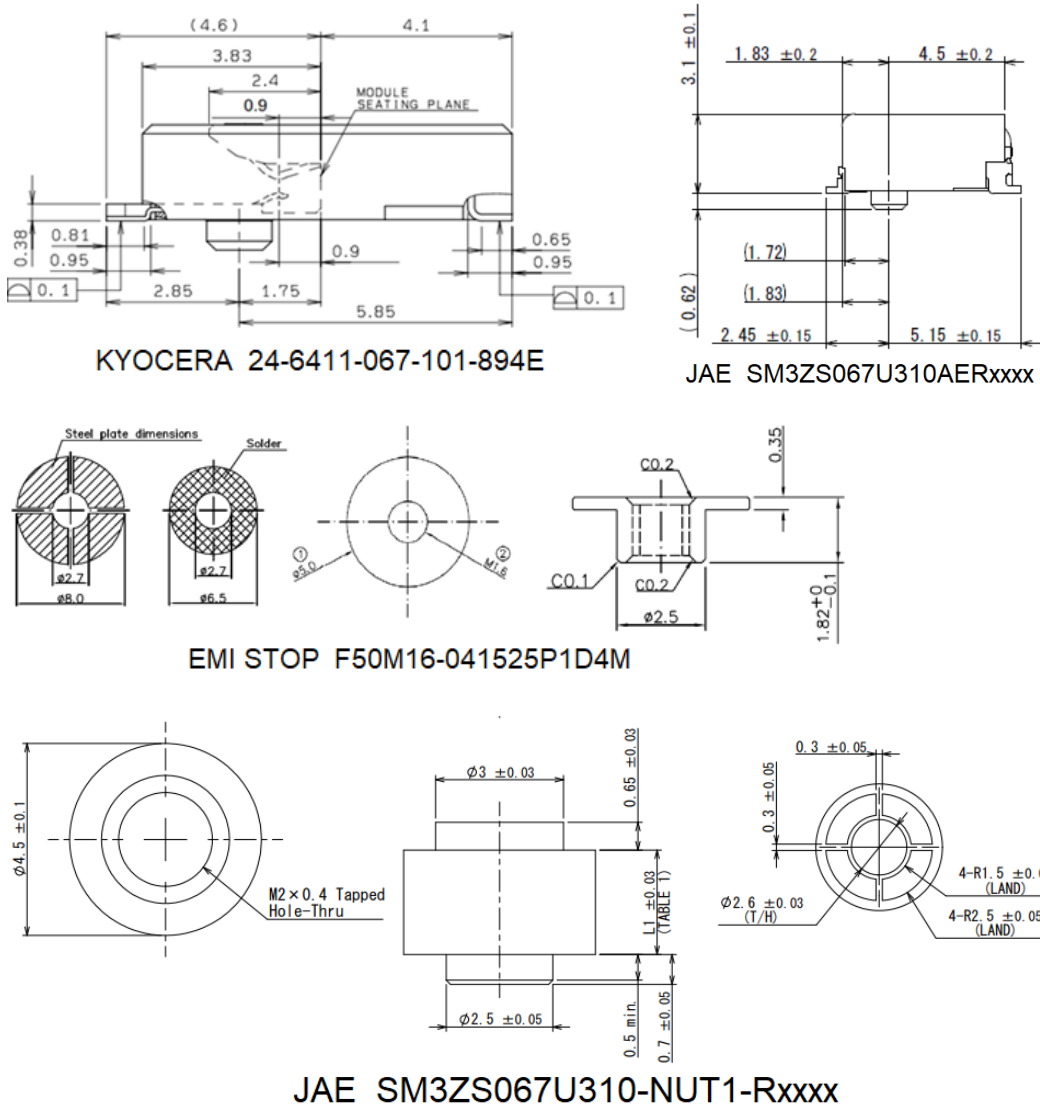


Figure 24: M.2 2230 E-Key connector/standoff mounting

16 RF Layout Design Guidelines

The following is a list of RF layout design guidelines and recommendation when installing a Ezurio radio into your device.

- Do not run antenna cables directly above or directly below the radio.
- Do not place any parts or run any high-speed digital lines below the radio.
- Ensure that there is the maximum allowable spacing separating the antenna connectors on the Ezurio radio from the antenna. In addition, do not place antennas directly above or directly below the radio.
- Ezurio recommends the use of a double-shielded cable for the connection between the radio and the antenna elements.

- Be sure to put a 10uF/16V/0603 capacitor on EACH 3.3V power pin. Place the capacitor as close as possible to the pin to ensure correct PMU operation.
- Use proper electro-static-discharge (ESD) procedures when installing the Ezurio radio module. To avoid negatively impacting Tx power and receiver sensitivity, do not cover the antennas with metallic objects or components.

16.1 RF Antenna Connector Configuration

Antenna connectors for the SMT and M.2 2230 modules are designated as shown in

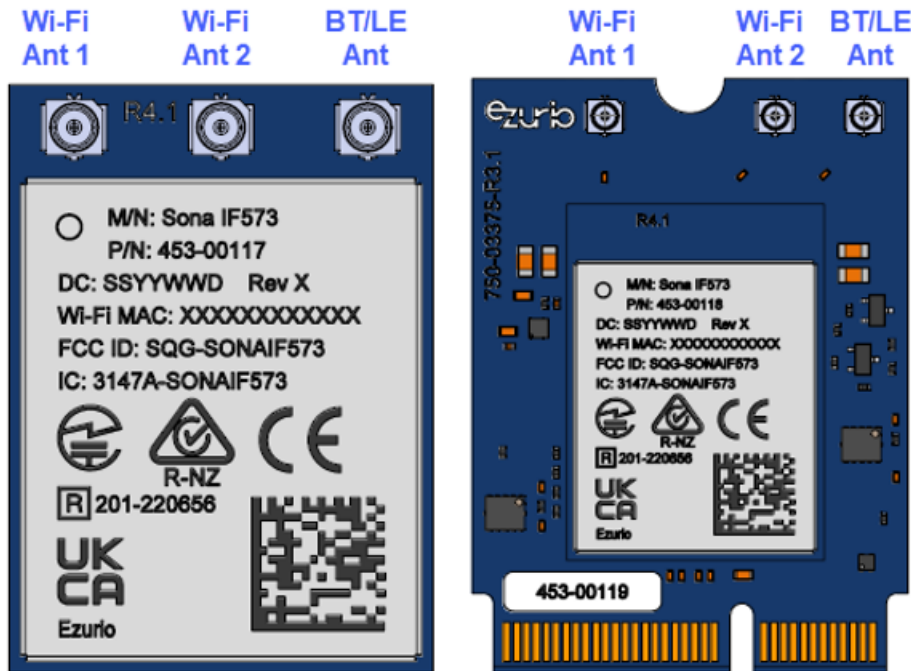


Figure 25: RF Antenna Configuration

17 Application Notes

17.1 Introduction

Ezurio's surface mount modules are designed to conform to all major manufacturing guidelines. This application note is intended to provide additional guidance beyond the information that is presented in the user manual. This application note is considered a living document and will be updated as new information is presented.

The modules are designed to meet the needs of several commercial and industrial applications. They are easy to manufacture and conform to current automated manufacturing processes.

17.2 Shipping and Labelling

17.2.1 M.2 1218 Solder-Down

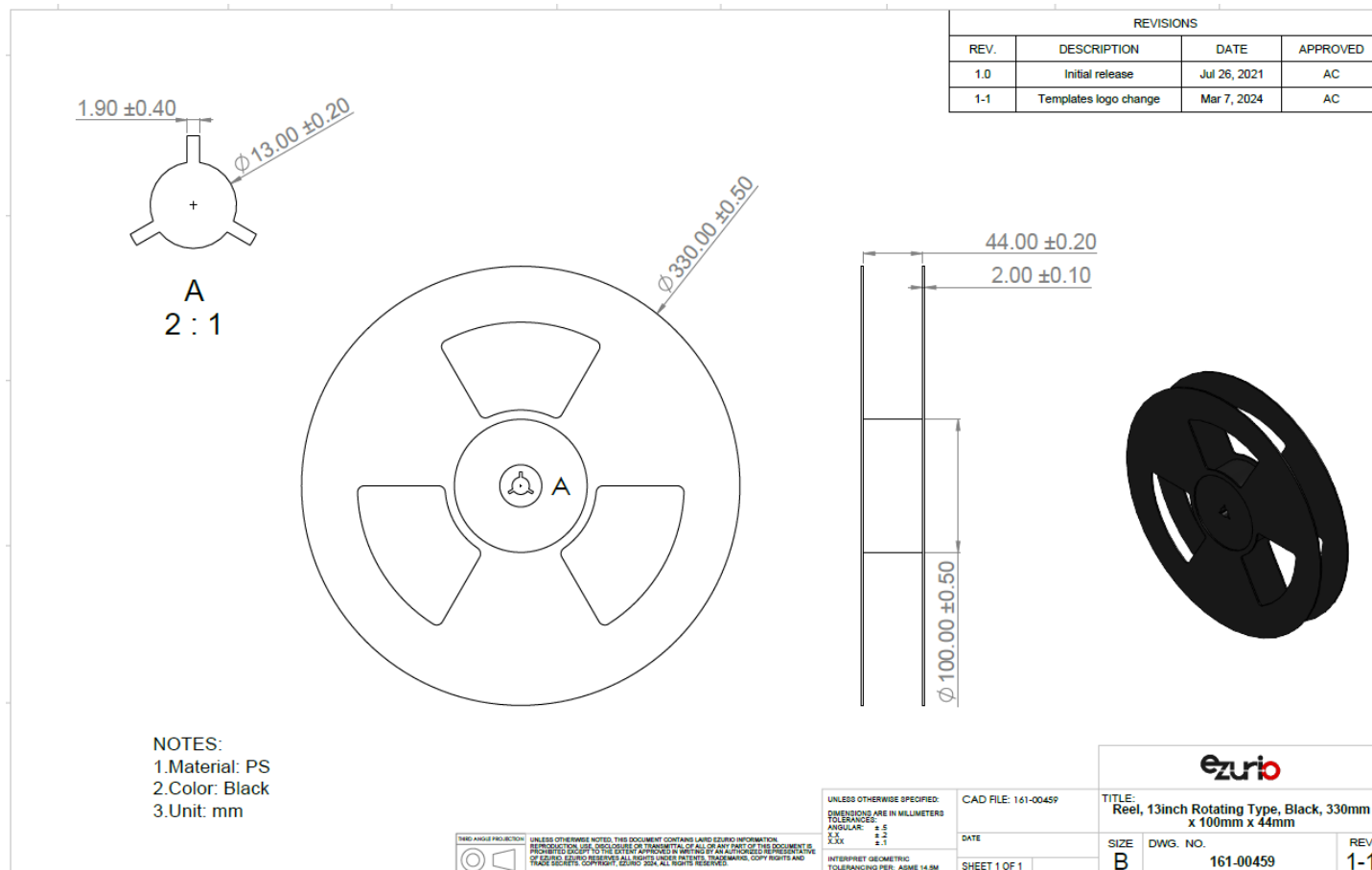
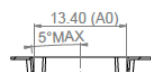
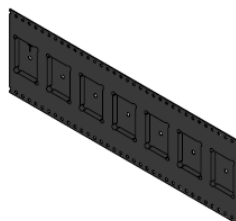


Figure 26: Sona IF573 Reel specifications, 161-00459: Sona IF573 Reel specifications, 161-00459

REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
1-0	Initial release	Oct 11, 2022	AC
1-1	Rebrand	Jun 24, 2024	AC



1. Material: Conductive polystyrene, Black
2. The camber shall follow EIA-481-E Regulation.
3. The design of this carrier tape will accord with EIA-481-E or IEC-60286-3, unless otherwise specified
4. Surface resistivity of carrier tape should be $10^4 \sim 10^9 \Omega/\text{square}$ where otherwise humidity is under $12 \pm 3\%$ and the temperature is in between $23^\circ \pm 3^\circ$



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DIMENSIONS ARE IN MILLIMETER
TOLERANCES:
ANGULAR: $\pm$
XX $\pm$
XXX $\pm$
INTERPRET GEOMETRIC
TOLERANCING PER: ASME Y14.5M

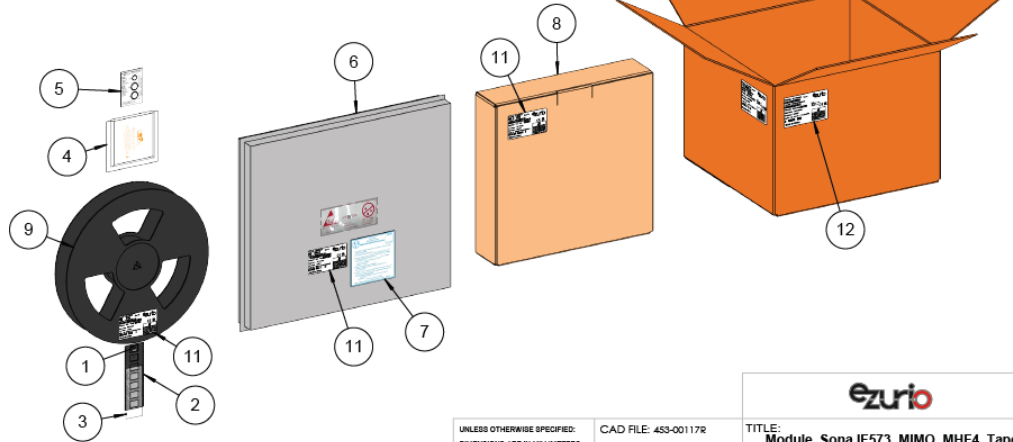
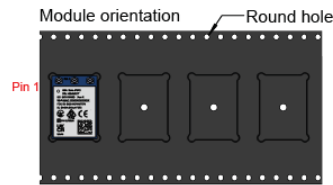
CAD FILE: 161-00543
DATE
SHEET 1 OF 1

		
TITLE: Carrier Tape, Conductive Polystyrene, Black, 13.4mm x 18.4mm x 2.4mm		
SIZE B	DWG. NO. 161-00543	REV 1-1

There are 1,000 Sona IF573 modules taped in a reel (and packaged in a pizza box) and three boxes per carton (3,000 modules per carton). Reel, boxes, and carton are labeled with the appropriate labels. See [Figure 28](#) for more information.

ITEM NO.	PART NUMBER	REV.	DESCRIPTION	QTY.
1	453-00117	2-0	Module, Sona IF573, MIMO, MHF4	1000
2	161-00543	1-1	Carrier Tape, Conductive Polystyrene, Black, 13.4mm x 18.4mm x 2.4mm	1
3	161-00528	1-1	Cover Tape, Anti-static Polyester, 37.5mm x 0.05mm	1
4	161-00506	1-1	Desiccant, Silica Gel, 66g, 110mm x 120mm	1
5	161-00510	1-1	Humidity Indicator Card, Minimum 60% RH, Three Spot Indication, 75mm x 50mm, J-STD-033 Rev D	1
6	161-00544	1-1	Bag, ESD and Moisture Barrier, Silver, 420mm x 475mm x 0.15mm	1
7	160-02008	1-2	Label, Blank Moisture Sensitivity Level, 4in x 4in	1
8	161-00507	1-1	Box, Single-Wall Corrugated E Flute, 362mm x 344mm x 83mm	1
9	161-00459	1-1	Reel, 13inch Rotating Type, Black, 330mm x 100mm x 44mm	1
10	161-00508	1-1	Carton, AB Flute, 365mm x 383mm x 279mm	1
11	160-02371	1-1	Label, Product Identifier, Sona IF573, 89mm x 51mm	3
12	160-02372	1-1	Label, Carton Product Identifier, Sona IF573, 101mm x 64mm	2

REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
1-0	Initial release	Oct 19, 2022	AC
2-0	Rebrand	Jun 26, 2024	AC



Notes:

- Put the Module in the carrier tape and cover the tape.
- Put the Reel, Desiccant and Humidity Indicator Card in the ESD bag.
- Put the packed ESD bag (vacuum) in the box.
- Put the box in the carton.
- Module packaging quantity:
Per Reel: 1000 PCS



Unit: mm
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TOLERANCES:
ANGULARS: ±0.1°
X.XX: ±0.05
X.XXX: ±0.025
INTERPRET GEOMETRIC
TOLERANCING PER: ASME Y14.5M

CAD FILE: 453-00117R
DATE
SHEET 1 OF 1

ezurio		
TITLE: Module, Sona IF573, MIMO, MHF4, Tape and Reel		
SIZE B	DWG. NO. 453-00117R	REV 2-0

Figure 28: Sona IF573 packaging processes, 453-00117R

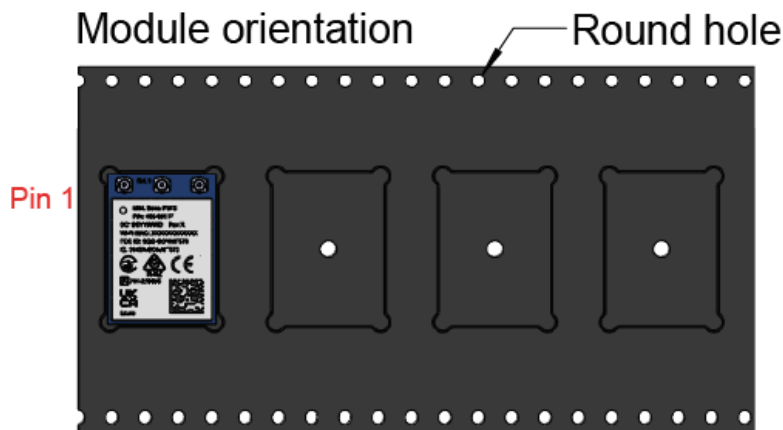


Figure 29: Module Orientation in Carrier Tape Cavity

The following labels are located on the antistatic bag.

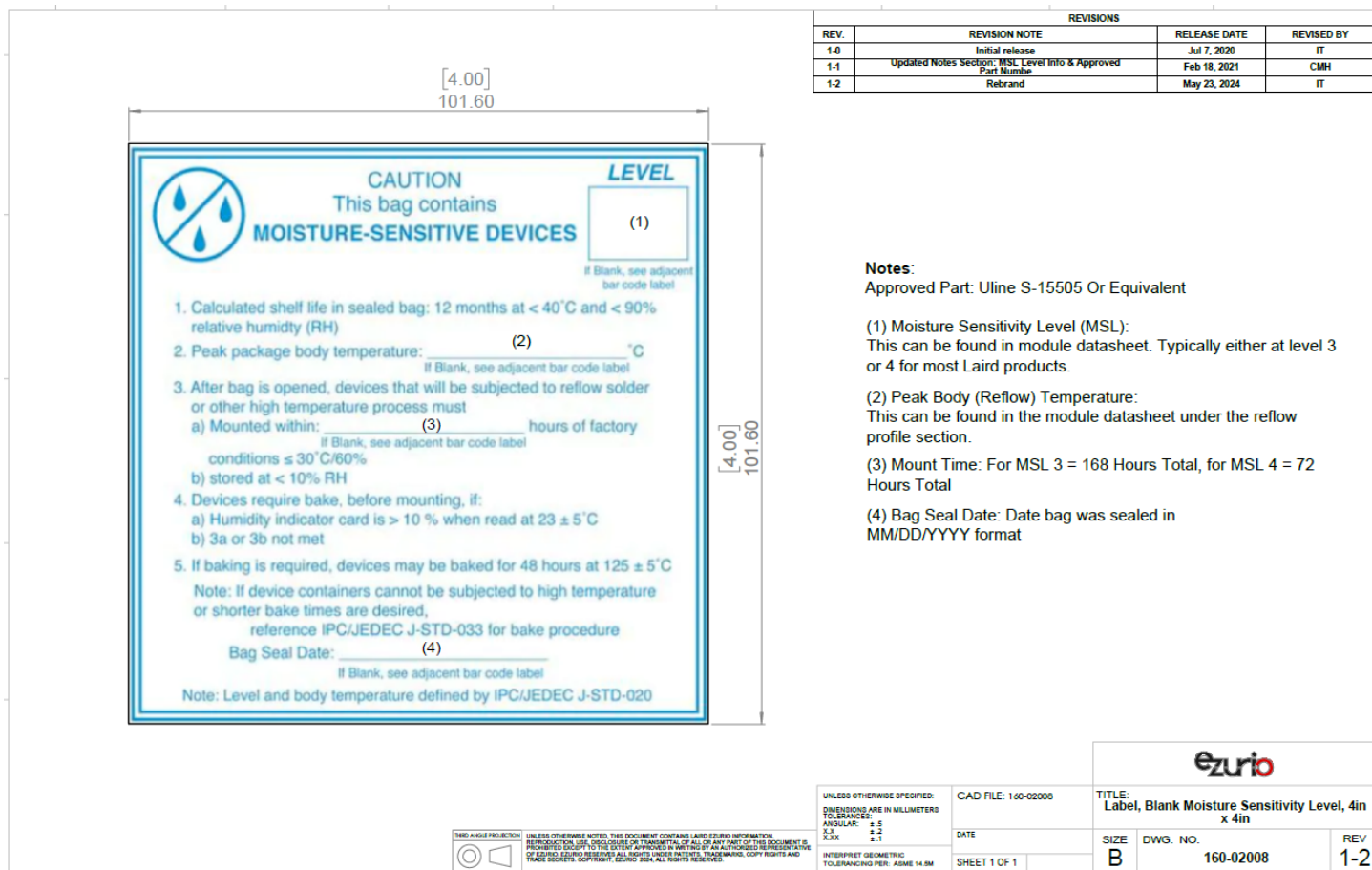
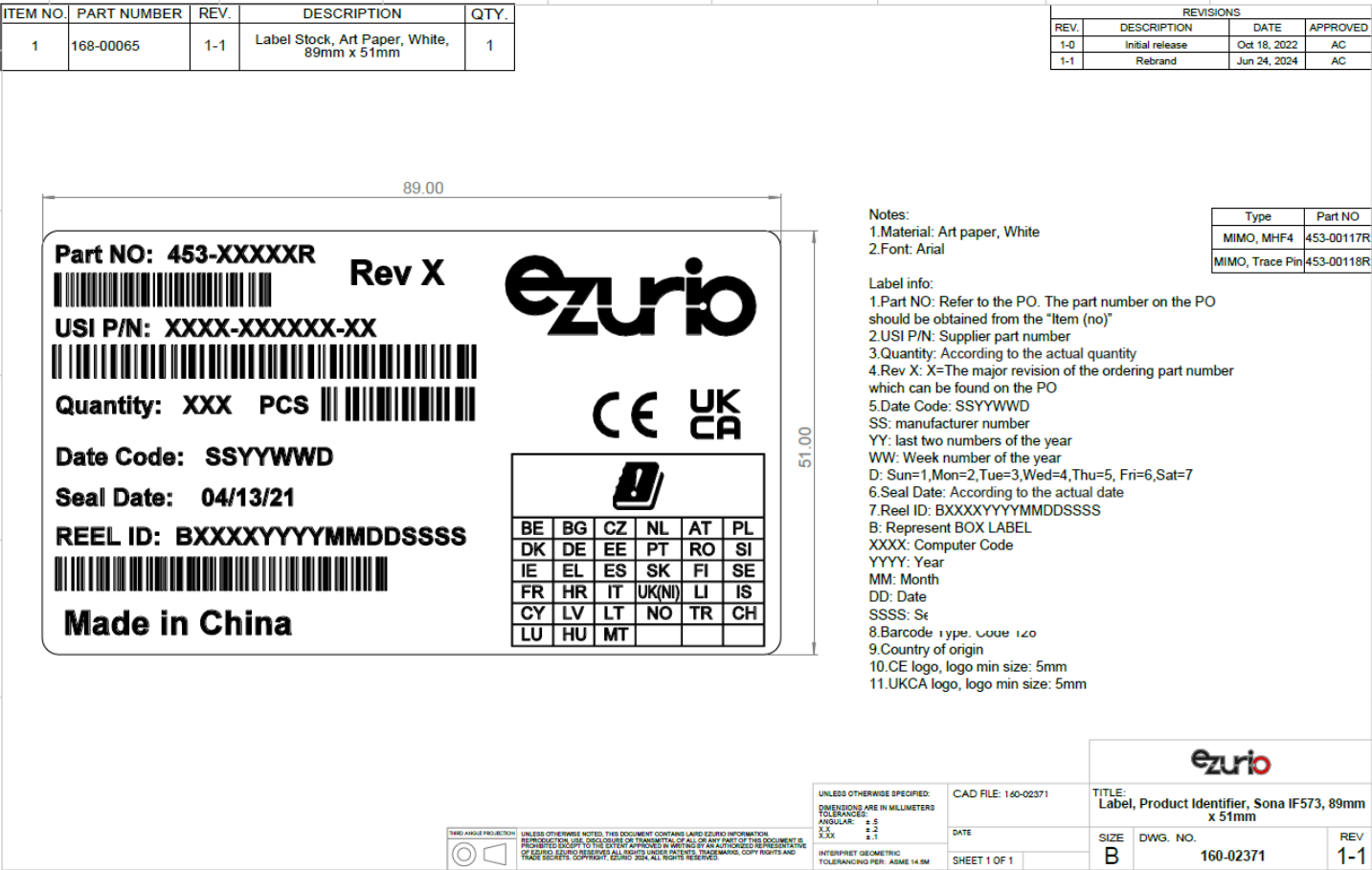
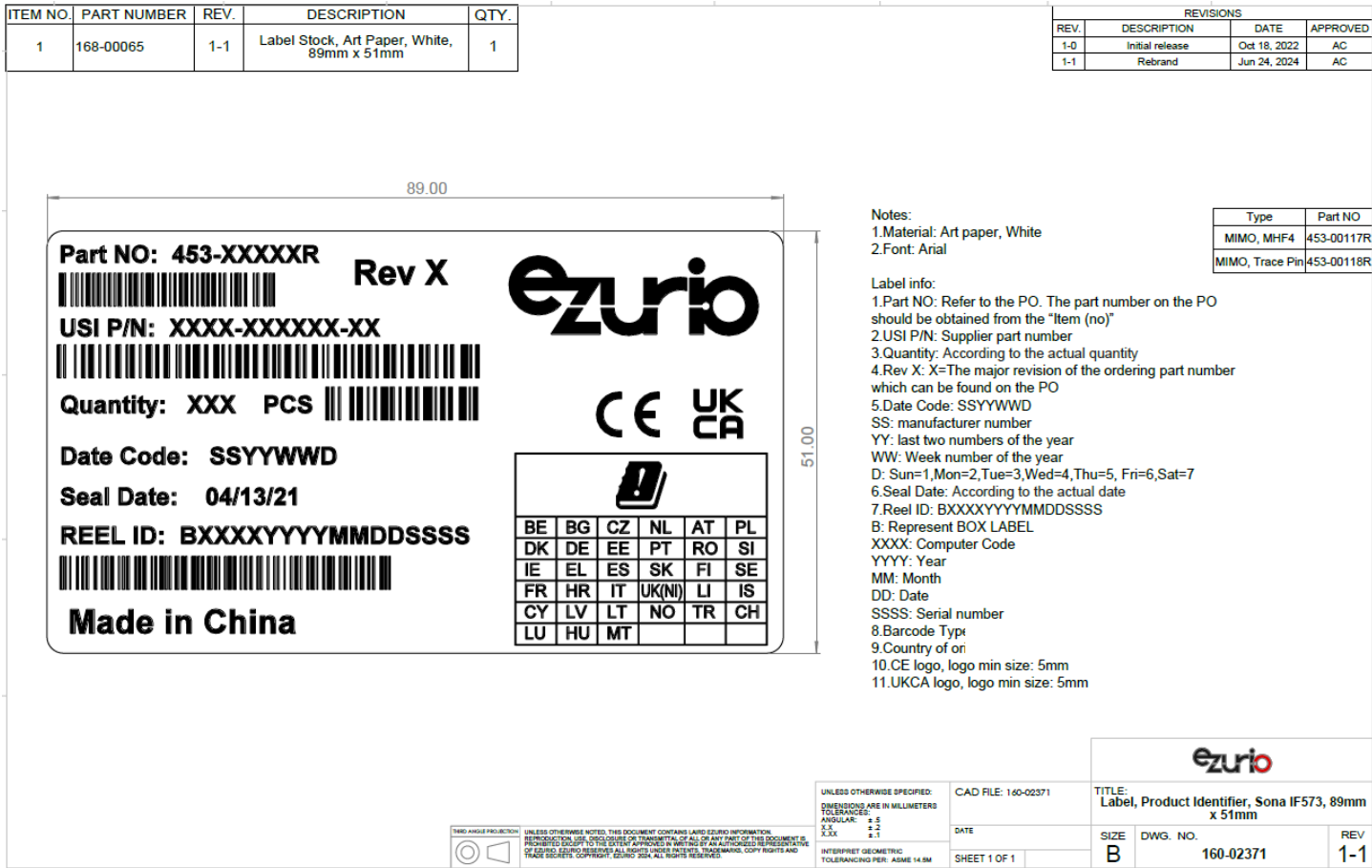


Figure 30: Sona IF573 Moisture Sensitivity Level Label, 160-02008



The following label is located on the pizza box.



ITEM NO.	PART NUMBER	REV.	DESCRIPTION	QTY.
1	168-00066	1-1	Label Stock, Art Paper, White, 101mm x 64mm	1

REVIEWS			
REV.	DESCRIPTION	DATE	APPROVED
1-0	Initial release	Oct 18, 2022	AC
1-1	Rebrand	Jun 24, 2024	AC

101.00

64.00

Part NO: 453-XXXXXR

Rev X

USI P/N: XXXX-XXXXXX-XX

Quantity: XXXX PCS

Date Code: SSYYWWD

Seal Date: 04/13/21

Carton NO: CXXXXYYYMMDDSSSS

Made in China

Ezurio

50 South Main Street

Suite 1100

Akron, OH 44308

BE	BG	CZ	NL	AT	PL
DK	DE	EE	PT	RO	SI
IE	EL	ES	SK	FI	SE
FR	HR	IT	UK(NI)	LI	IS
CY	LV	LT	NO	TR	CH
LU	HU	MT			

Notes:

1.Material: Art paper, White

2.Font: Arial

Label info:

1.Part NO: Refer to the PO. The part number on the PO should be obtained from the "Item (no)"

2.USI P/N: Supplier part number

3.Quantity: According to the actual quantity

4.Rev X: X=The major revision of the ordering part number which can be found on the PO

5.Date Code: SSYYWWD

SS: manufacturer number

YY: last two numbers of the year

WW: Week number of the year

D: Sun=1,Mon=2,Tue=3,Wed=4,Thu=5, Fri=6,Sat=7

6.Seal Date: According to the actual date

7.Carton NO: CXXXXYYYMMDDSSSS

C: Represent Carton LABEL

XXXX: Computer Code

YYYY: Yea

MM: Month

DD: Date

SSSS: Serial number

8.Barcode Type: Code 128

9.Country of origin

10.CE logo, logo min size: 5mm

11.UKCA logo, logo min size: 5mm

Type	Part NO
MIMO, MHF4	453-00117R
MIMO, Trace Pin	453-00118R

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES:
ANGULAR: ± 5
X.X ± 1
X.XX ± 1

CAD FILE: 160-02372

DATE

SHEET 1 OF 1

INTERPRET GEOMETRIC
TOLERANCING PER: ASME Y14.5M

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES:
ANGULAR: ± 5
X.X ± 1
X.XX ± 1

TITLE:	
Label, Carton Product Identifier, Sona IF573, 101mm x 64mm	
SIZE	DWG. NO.
B	160-02372

REV	1-1
REV	1-1

Figure 33: Sona IF573 Carton Product Identifier Label, 160-0273

1.1.2 M.2 2230 E-Key Module

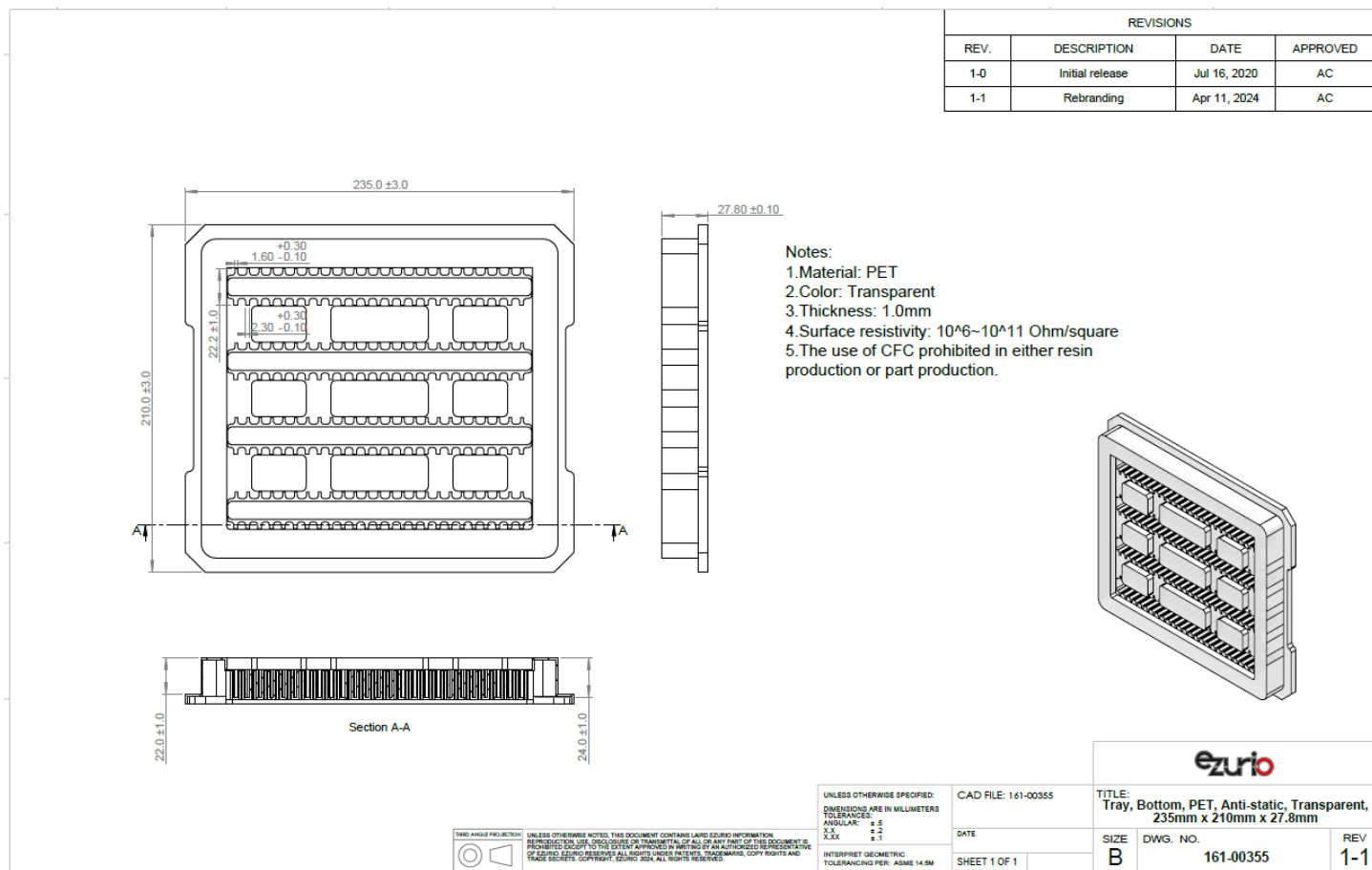
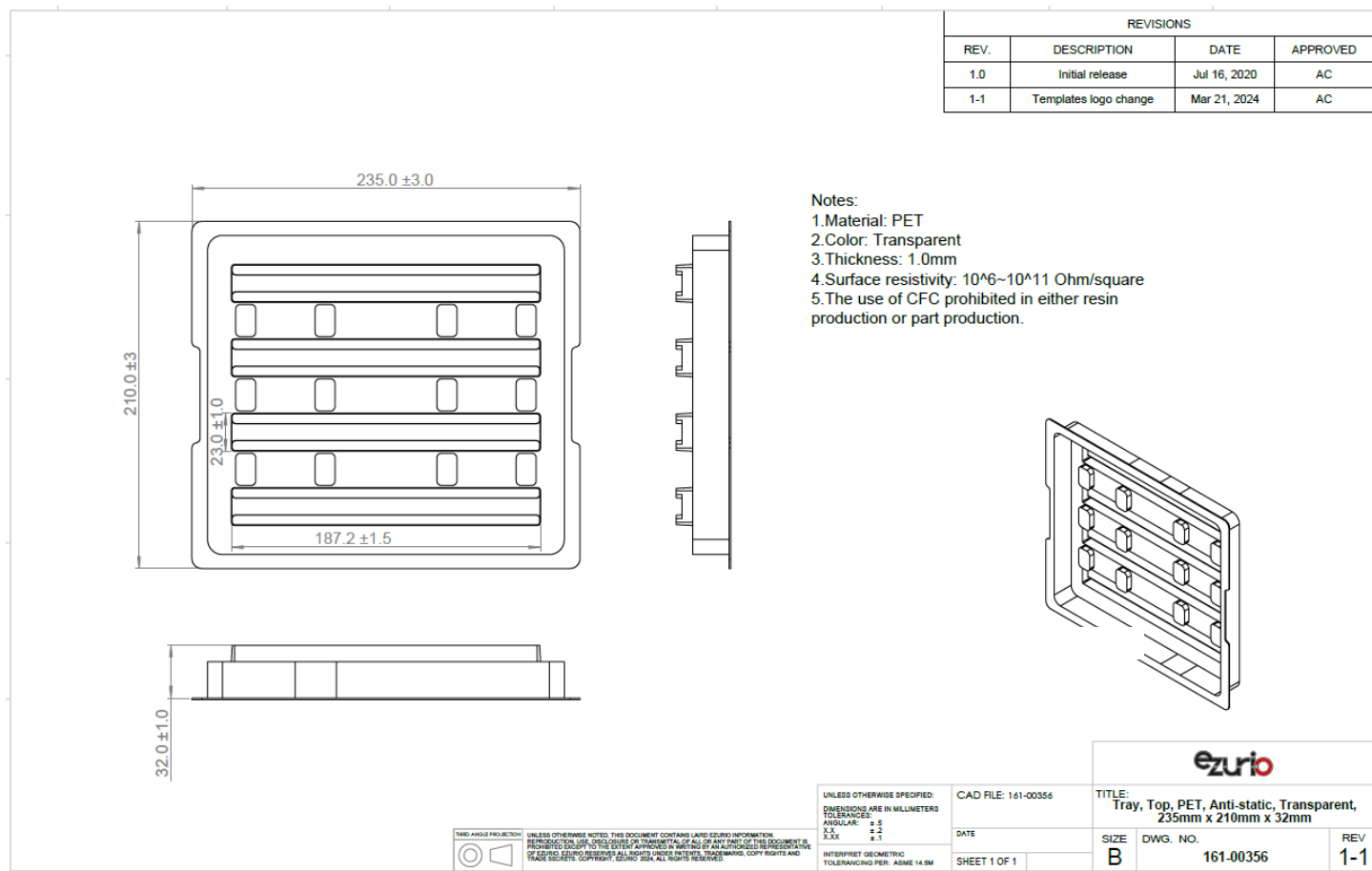


Figure 34: Sona IF573 M.2 2230 Shipping Tray, Bottom, 161-00355



ITEM NO.	PART NUMBER	REV.	DESCRIPTION	QTY.
1	453-00119	2-0	Module, Sona IF573, MIMO, M.2, Key E, SDIO, UART	600
2	161-00355	1-1	Tray, Bottom, PET, Anti-static, Transparent, 235mm x 210mm x 27.8mm	6
3	161-00356	1-1	Tray, Top, PET, Anti-static, Transparent, 235mm x 210mm x 32mm	6
4	161-00357	1-1	Box, Kraft, B Flute, 252mm x 217mm x 41mm	6
5	160-02373	1-1	Label, Box Product Identifier, Sona IF573, M.2, 89mm x 51mm	12
6	161-00361	1-1	Desiccant, Silica Gel, 10g, 58mm x 80mm	6
7	161-00358	1-1	Bag, ESD and Moisture Barrier, Silver, 270mm x 360mm x 0.09mm	6
8	161-00359	1-1	Carton, Kraft, AB Flute, 455mm x 268mm x 170mm	1
9	160-02374	1-1	Label, Carton Product Identifier, Sona IF573, M.2, 101mm x 64mm	2

REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
0-0	Initial release	Oct 26, 2022	AC
0-1	Rebrand	Jun 26, 2024	AC

Notes:
 1.Put the Module in the bottom tray.
 2.Cover the top tray.
 3.Put the packed tray and Desiccant in the ESD bag.
 4.Put the packed ESD bag (vacuum) in the box.
 5.Put six boxes in the carton.
 6.Module packaging quantity:
 Per Tray: 100 PCS
 Per Carton: 600PCS

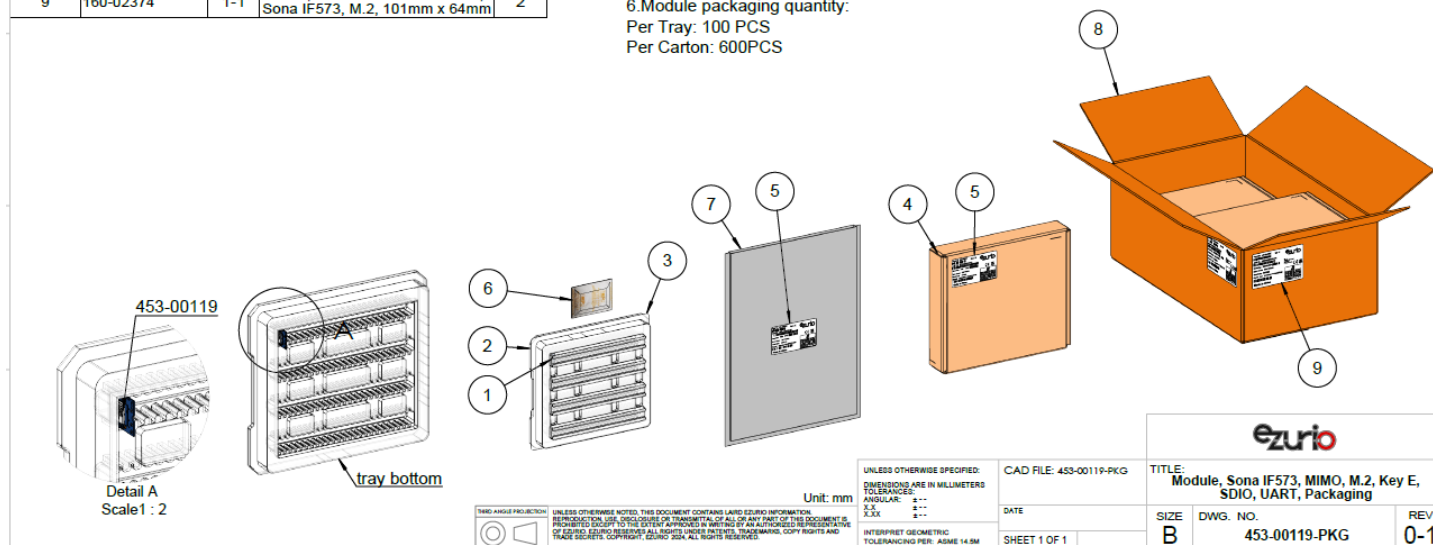


Figure 36: Sona IF573 M.2 2230 Packaging Process, 453-00119-PKG

The following label is placed on the bag and the inner box.

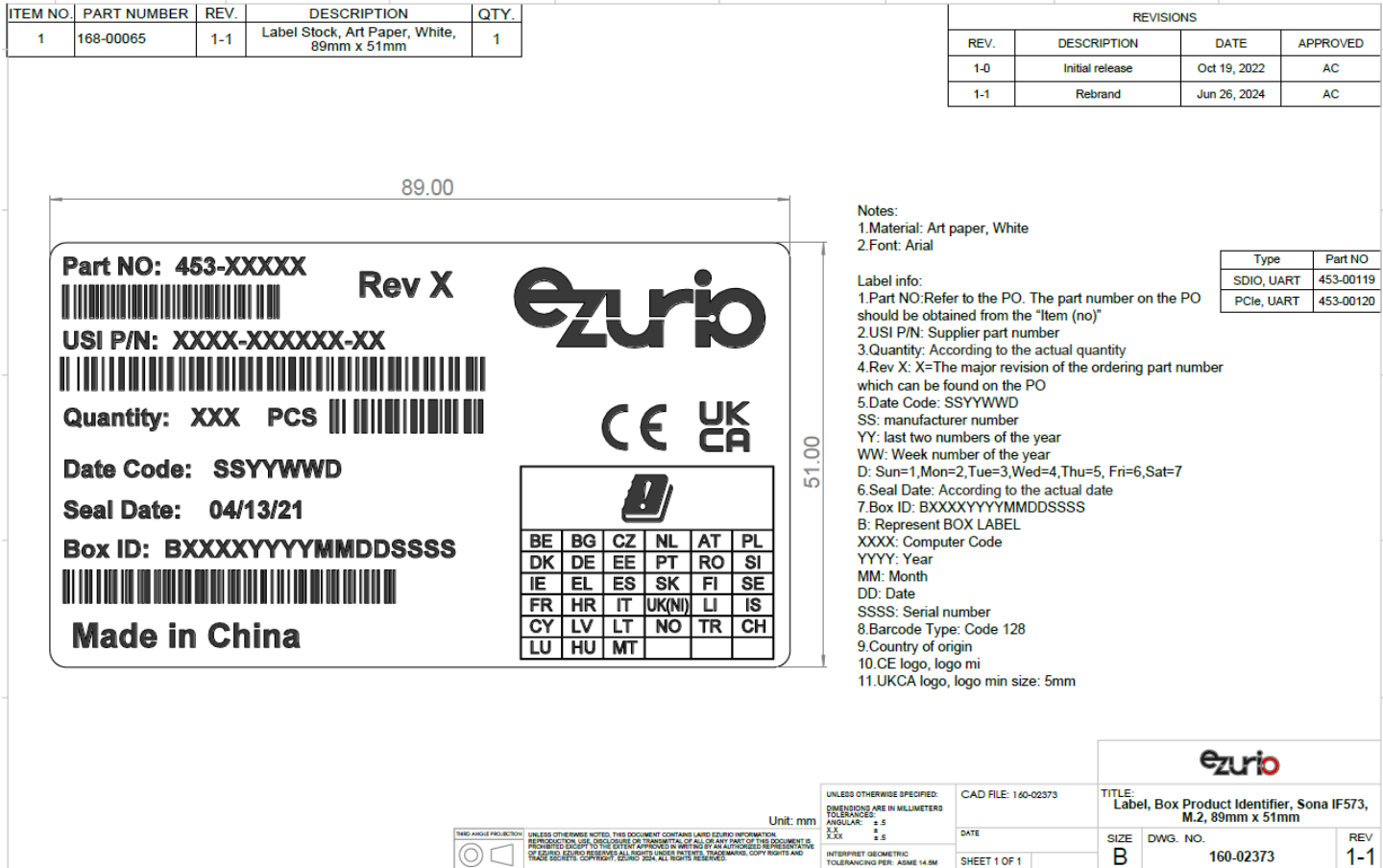


Figure 37: Sona IF573 M.2 2230 Bag and Box Product Identifier Label, 160-02373

The following label is located on the adjacent sides of the master carton.

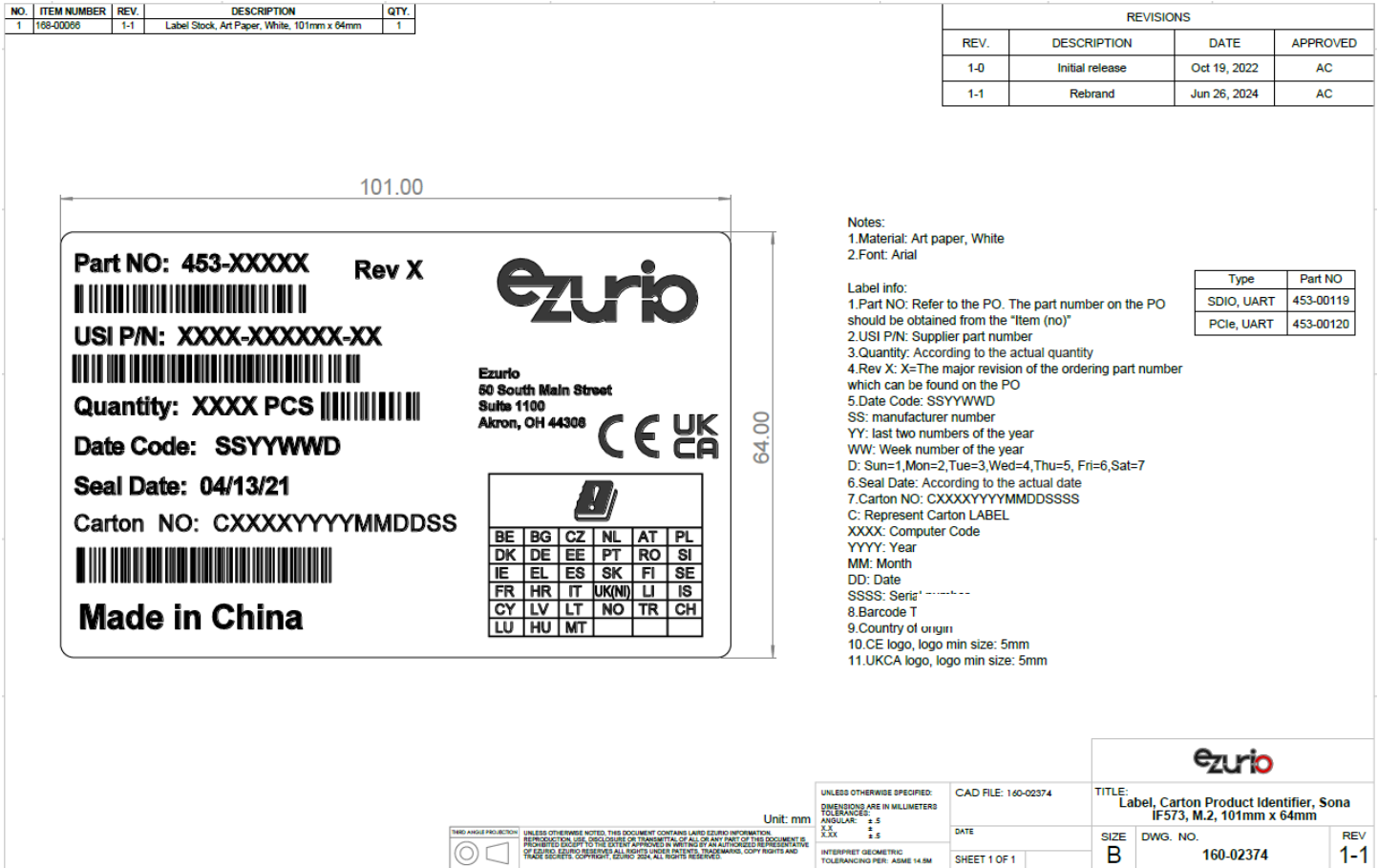


Figure 38: Sona IF573 M.2 2230 Carton Product Identifier Label, 160-02374

17.3 Required Storage Conditions

17.3.1 Prior to Opening the Dry Packing

The following are required storage conditions *prior* to opening the dry packing:

- Normal temperature: 5~40 °C
- Normal humidity: 80% (Relative humidity) or less
- Storage period: One year or less

Note: Humidity means relative humidity.

17.3.2 After Opening the Dry Packing

The following are required storage conditions *after* opening the dry packing (to prevent moisture absorption):

- Storage conditions for one-time soldering:
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: 72 hours or less after opening
- Storage conditions for two-time soldering
 - Storage conditions following opening and prior to performing the 1st reflow:
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: A hours or less after opening
 - Storage conditions following completion of the 1st reflow and prior to performing the 2nd reflow
 - Temperature: 5-25°C

- Humidity: 60% or less
- Period: B hours or less after completion of the 1st reflow

Note: Should keep A+B within 72 hours.

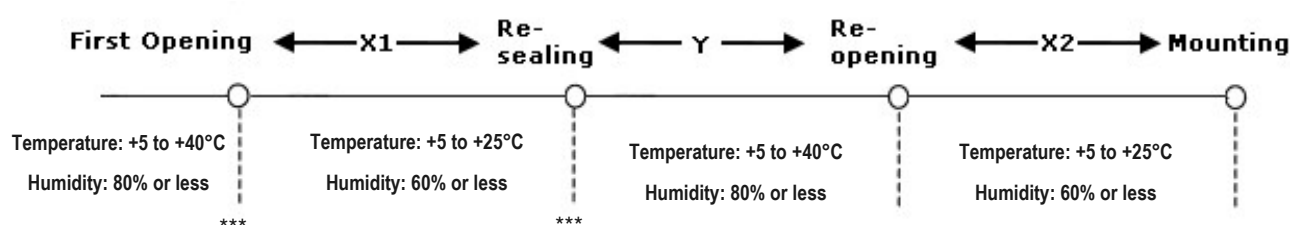
17.3.3 Temporary Storage Requirements after Opening

The following are temporary storage requirements after opening:

- Only re-store the devices once prior to soldering.
- Use a dry box or place desiccant (with a blue humidity indicator) with the devices and perform dry packing again using vacuumed heat-sealing.

The following indicate the required storage period, temperature, and humidity for this temporary storage:

- Storage temperature and humidity:



- Storage period:
 - X1+X2 – Refer to **After Opening the Dry Packing** storage requirements. Keep is X1+X2 within 72 hours.
 - Y – Keep within two weeks or less.

17.4 Baking Conditions

Baking conditions and processes for the module follow the J-STD-033 standard which includes the following:

- The calculated shelf life in a sealed bag is 12 months at <40°C and <80% relative humidity.
- Once the packaging is opened, the SiP must be mounted (per MSL4/Moisture Sensitivity Level 4) within 72 hours at <30 °C and <60% relative humidity.
- If the SiP is not mounted within 72 hours or if, when the dry pack is opened, the humidity indicator card displays >10% humidity, then the product must be baked for 48 hours at 125 °C (±5 °C).

18 Surface Mount Conditions

The following soldering conditions are recommended to ensure device quality.

18.1 Recommended Stencil Aperture

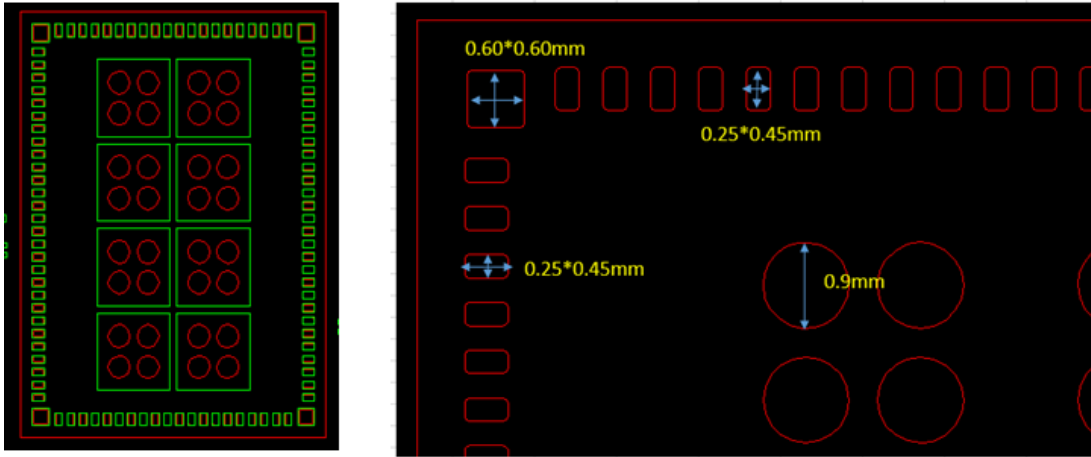


Figure 39: Sona IF573 M.2 1318 stencil aperture

Note: The stencil thickness is 0.12mm

18.2 Soldering

Note: When soldering, the stencil thickness should be 0.12 mm.

Convection reflow or IR/Convection reflow (one-time soldering or two-time soldering in air or nitrogen environment)

Measuring point – IC package surface

Temperature profile:

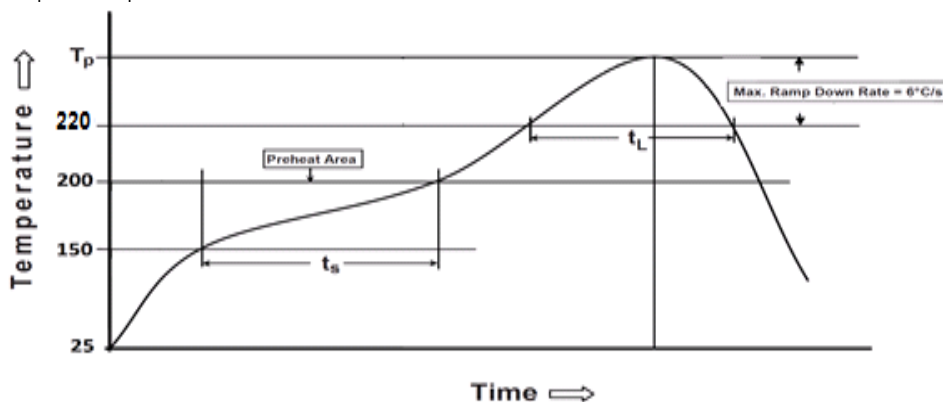


Figure 40: Temperature profile

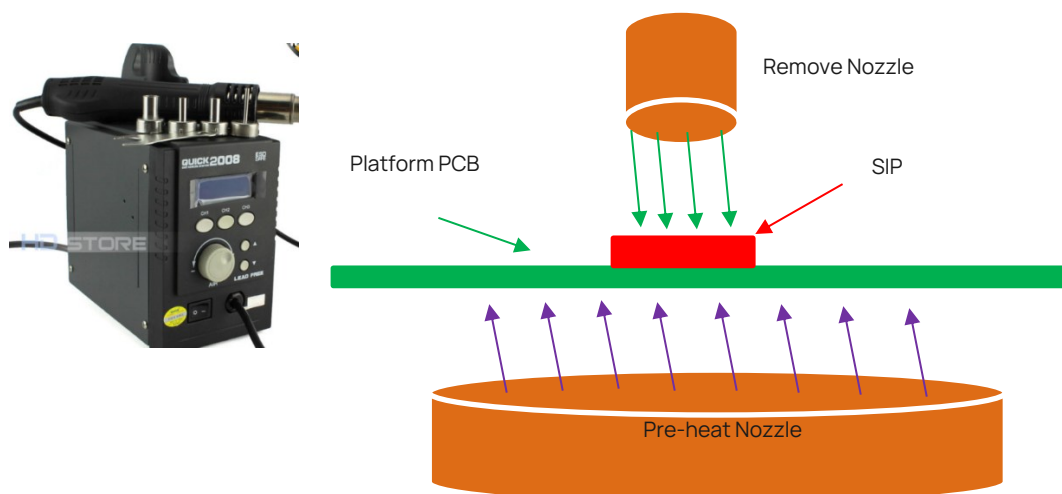
- Solder paste alloy: SAC305(Sn96.5 / Ag3.0 / Cu 0.5)
- Pre-heat temperature: 150°C ~ 200°C; Soak time: 60 second ~ 120 second
- Peak temperature: 235°C ~ 250°C
- Time above 220°C: 40 second ~ 90 second
- Optimal cooling rate < 3°C/second
- The oxygen concentration < 2000 ppm

18.2.1 Cautions When Removing the M.2 1318 from the Platform for RMA

- Bake the platform before removing the Sona IF573 module from the platform. Reference [Baking Conditions](#).
- Remove the Sona IF573 module by using a hot air gun. This process should be carried out by a skilled technician.

Recommended conditions:

- One-side component platform:
 - Set the hot plate at 280°C.
 - Put the platform on the hot plate for 8~10 seconds.
 - Remove the device from platform.
- Two-side components platform:
 - Use two hot air guns.
 - On the bottom, use a pre-heated nozzle (temp setting of 200~250°C) at a suitable distance from the platform PCB.
 - On the top, apply a remove nozzle (temp setting of 330°C). Heat until device can be removed from platform PCB.



- Remove the residue solder under the bottom side of device. (Note: Alternate module pictured as an example)



(Not accepted for RMA)

Figure 41: Example M.2 1318 with residue solder on the bottom



(Accepted for RMA analysis)

Figure 42: Sona IF573 module without residue solder

- Remove and clean the residue flux as needed.

1.1.3 Precautions for Use

- Opening/handling/removing must be done on an anti-ESD treated workbench. All workers must also have undergone anti-ESD treatment.
- The devices should be mounted within one year of the date of delivery.
- The Sona IF573 modules are MSL level 4 rated.

19 Reliability Test

The Sona IF573 modules were tested for reliability. Test items and the corresponding standards are shown in [Table 43](#).

19.1 Environmental and Mechanical

The following are the followed reliability test procedures.

Table 43: Sona IF573 M.2 1318 Solder-down Module Reliability Test Items and Standards

Test Item	Specification	Standard	Test Result
Step 1: Pre-conditioning	Pre-check: - Function check (Tools and SOP supplied by customers). - Mechanical check. Pre-conditioning: - Bake: 125°C for 24 hours. - Moisture Soak: 30°C/60% RH for 192 hours - Not shorter than 15 minutes and not longer than 4 hours after removal from the temperature/humidity chamber, subject the sample to 3 cycles of the reflow. Post-check: - Function check (Tools and SOP supplied by customers). - Mechanical check. - Perform inspections of short, open, delamination of DUTs by Optical Microscope (under 40X optical magnification). - X-RAY / CSAM (SAT) on any failed samples (Notify customers). - Cross-sections analysis based on X-RAY and CSAM results.	JESD22-A113	Pass
Step 2: Temperature Cycling Non-operating	- Dwell on -40°C for 15 minutes - Shock to 85°C within ramp rate 15 °C/minute - Dwell on 85°C for 15 minutes - Shock to -40°C within ramp rate 15 degree C/minute - Repeat step 1-4 and stop to check functions at 500/ 700 cycles	JESD22-A113	Pass
Vibration Non-operating Unpackaged device	- Vibration Wave Form: Sine Waveform - Vibration frequency / Displacement: 20-80 Hz/1.5mm - Vibration frequency / Acceleration: 80-2000 Hz/20g - Cycle Time: 4 min/cycle - Number of Cycles: 4 cycle/axis - Vibration Axes: X, Y and Z (Rotate each axis on vertical vibration table)	JEDEC 22-B103B (2016)	Pass
Mechanical Shock Non-operating Unpackaged device	- Pulse shape: Half-sine waveform - Impact acceleration: 1500 g - Pulse duration: 0.5 ms - Number of shocks: 30 shocks (5 shocks for each face) - Orientation: Bottom, top, left, right, front and rear faces	JEDEC 22-B110B.01 (2019)	Pass

Table 44: Sona IF573 M.2 2230 E-Key Module Reliability Test Item and Standards

Test Item	Specification	Standard	Test Result
Thermal Shock	1. Temperature: -40 ~ 85°C 2. Ramp time: Less than 10 seconds. 3. Dwell Time: 10 minutes 4. Number of Cycles: 500 times	*JESD22-A106 *IEC 60068-2-14 for dwell time and number of cycles	Pass
Vibration Non-operating Unpackaged device	1. Vibration Wave Form: Sine Waveform 2. Vibration frequency / Displacement: 20-80 Hz/1.5mm 3. Vibration frequency / Acceleration: 80-2000 Hz/20g 4. Cycle Time: 4 min/cycle 5. Number of Cycles: 4 cycle/axis 6. Vibration Axes : X, Y and Z (Rotate each axis on vertical vibration table)	JEDEC 22-B103B (2016)	Pass
Mechanical Shock Non-operating Unpackaged device	1. Pulse shape: Half-sine waveform 2. Impact acceleration: 1500 g 3. Pulse duration: 0.5 ms 4. Number of shocks: 30 shocks (5 shocks for each face) 5. Orientation: Bottom, top, left, right, front and rear faces	JEDEC 22-B110B.01 (2019)	Pass

19.2 Reliability Prediction

Test Item	Specification	Standard
Mean Time Between Failure (MTBF)	1. Normal Operating Temperature: 45 °C 2. High Temperature: 85 °C	Telcordia SR-332 Issue 4 (2016)

Ezurio Part Number	Environment	Test Result 45 °C (Hours)
453-00117R	Ground, Fixed, Uncontrolled	13,987,080.94
453-00117C	Ground, Mobile	10,659,368.74
453-00118R		
453-00118C		

Ezurio Part Number	Environment	Test Result 85 °C (Hours)
453-00117R	Ground, Fixed, Uncontrolled	2,751,512.41
453-00117C	Ground, Mobile	2,095,110.62
453-00118R		
453-00118C		

Ezurio Part Number	Environment	Test Result 45 °C (Hours)
453-00119	Ground, Fixed, Uncontrolled	8,861,616.79
453-00120	Ground, Mobile	6,713,673.22

Ezurio Part Number	Environment	Test Result 85 °C (Hours)
453-00119	Ground, Fixed, Uncontrolled	1,752,775.15
453-00120	Ground, Mobile	1,327,284.04

20 Regulatory

Note: For complete regulatory information, refer to the Sona IF573 Regulatory Information document which is also available from the [Sona IF573 product page](#).

The Sona IF573 holds current certifications in the following countries:

Country/Region	Regulatory ID
USA (FCC)	SQG-SONAIF573
EU	N/A
UKCA	N/A
Canada (ISED)	3147A-SONAIF573
Japan (MIC)	201-220656
Australia	N/A
New Zealand	N/A

20.1 Certified Antennas

The Sona IF573 module was tested with antennas listed in the following table. The OEM can choose a different manufacturer's antenna but must make sure it is of same type and that the gain is lesser than or equal to the antenna that is approved for use.

Manufacturer	Model	Ezurio Part Number	Type	Connector	Peak Gain (dBi)		
					2.4 GHz	5 GHz	6 GHz
Ezurio (Laird Connectivity)	FlexMIMO 6E	EFD2471A3S-10MH4L	PIFA	MHF4L	2.2	3.8	3.3
Ezurio (Laird Connectivity)	FlexPIFA 6E	EFB2471A3S-10MH4L	PIFA	MHF4L	2.2	3.9	3.8
Ezurio (Laird Connectivity)	Mini NanoBlade Flex 6 GHz	EMF2471A3S-10MH4L	PCB Dipole	MHF4L	2.4	4.4	5.2
Joymax Inc.	Dipole 6E	TWX-100BRSAX-2001 / TWX-100BRS3B	Dipole	RP-SMA	2	4.0	4.0

21 Bluetooth Qualification process

21.1 Overview

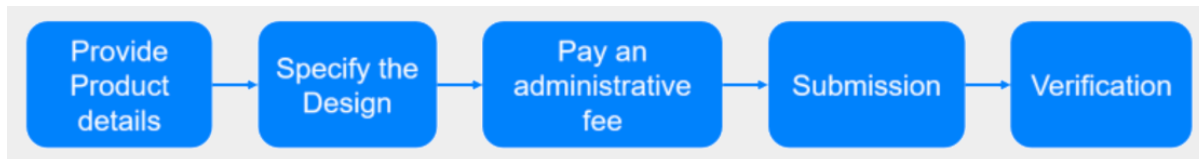
The Bluetooth Qualification Process promotes global product interoperability and reinforces the strength of the Bluetooth® brand and ecosystem to the benefit of all Bluetooth SIG members. The Bluetooth Qualification Process helps member companies ensure their products that incorporate Bluetooth technology comply with the Bluetooth Patent & Copyright License Agreement and the Bluetooth Trademark License Agreement (collectively, the Bluetooth License Agreement) and Bluetooth Specifications.

The Bluetooth Qualification Process is defined by the [Qualification Program Reference Document \(QPRD\) v3](#).

To demonstrate that a product complies with the Bluetooth Specification(s), each member must for each of its products:

- Identify the product, the design included in the product, the Bluetooth Specifications that the design implements, and the features of each implemented specification
- Complete the Bluetooth Qualification Process by submitting the required documentation for the product under a user account belonging to your company

The Bluetooth Qualification Process consists of the phases shown below:



To complete the Qualification Process the company developing a Bluetooth End Product shall be a member of the Bluetooth SIG. To start the application please use the following link: [Apply for Adopter Membership](#)

21.2 Scope

This guide is intended to provide guidance on the Bluetooth Qualification Process for End Products that reference multiple existing designs, that have not been modified, (refer to Section 3.2.2.1 of the [Qualification Program Reference Document v3](#)).

For a Product that includes a new Design created by combining two or more unmodified designs that have DNs or QDIDs into one of the permitted combinations in Table 3.1 of the QPRDv3, a Member must also provide the following information:

- DNs or QDIDs for Designs included in the new Design
- The desired Core Configuration of the new Design (if applicable, see Table 3.1 below)
- The active TCRL Package version used for checking the applicable Core Configuration (including transport compatibility) and evaluating test requirements

Any included Design must not implement any Layers using withdrawn specification(s).

When creating a new Design using Option 2a, the Inter-Layer Dependency (ILD) between Layers included in the Design will be checked based on the latest TCRL Package version used among the included Designs.

For the purposes of this document, it is assumed that the member is combining unmodified Core-Controller Configuration and Core-Host Configuration designs, to complete a Core-Complete Configuration.

21.3 Qualification Steps When Referencing multiple existing designs, (unmodified) – Option 2a in the QPRDv3

For this qualification option, follow these steps:

1. To start a listing, go to: <https://qualification.bluetooth.com/>
2. Select **Start the Bluetooth Qualification Process**.
3. Product Details to be entered:
 - Project Name (this can be the product name or the Bluetooth Design name).
 - Product Description
 - Model Number

- Product Publication Date (the product publication date may not be later than 90 days after submission)
 - Product Website (optional)
 - Internal Visibility (this will define if the product will be visible to other users prior to publication)
 - If you have multiple End Products to list then you can select 'Import Multiple Products', firstly downloading and completing the template, then by 'Upload Product List'. This will populate Qualification Workspace with all your products.
4. Specify the Design:
- Do you include any existing Design(s) in your Product? Answer Yes, I do.
 - Enter the multiple DNs or QDIDs used in your, (for Option 2a two or more DNs or QDIDs must be referenced)
 - Select 'I'm finished entering DN's
 - Once the DNs or QDIDs are selected they will appear on the left-hand side, indicating the layers covered by the design (should show Core-Controller and Core Host Layers covered).
 - What do you want to do next? Answer, 'Combine unmodified Designs'.
 - The Qualification Workspace Tool will indicate that a new Design will be created and what type of Core-Complete configuration is selected.
 - An active TCRL will be selected for the design.
 - Perform the Consistency Check, which should result in no inconsistencies
 - If there are any inconsistencies these will need to be resolved before proceeding
 - Save and go to Test Plan and Documentation
5. Test Plan and Documentation
- a. As no modifications have been made to the combined designs the tool should report the following message:
'No test plan has been generated for your new Design. Test declarations and test reports do not need to be submitted. You can continue to the next step.'
 - b. Save and go to Product Qualification fee
6. Product Qualification Fee:
- It's important to make sure a Prepaid Product Qualification fee is available as it is required at this stage to complete the Qualification Process.
 - Prepaid Product Qualification Fee's will appear in the available list so select one for the listing.
 - If one is not available select 'Pay Product Qualification Fee', payment can be done immediately via credit card, or you can pay via Invoice. Payment via credit will release the number immediately, if paying via invoice the number will not be released until the invoice is paid.
 - Once you have selected the Prepaid Qualification Fee, select 'Save and go to Submission'
7. Submission:
- Some automatic checks occur to ensure all submission requirements are complete.
 - To complete the listing any errors must be corrected
 - Once you have confirmed all design information is correct, tick all of the three check boxes and add your name to the signature page.
 - Now select 'Complete the Submission'.
 - You will be asked a final time to confirm you want to proceed with the submission, select 'Complete the Submission'.
 - Qualification Workspace will confirm the submission has been submitted. The Bluetooth SIG will email confirmation once the submission has been accepted, (normally this takes 1 working day).
8. Download Product and Design Details (SDoC):
- a. You can now download a copy of the confirmed listing from the design listing page and save a copy in your Compliance Folder

For further information, please refer to the following webpage:

<https://www.bluetooth.com/develop-with-bluetooth/qualification-listing/>

21.4 Example Design Combinations

The following gives an example of a design possible under option 2a:

Ezurio Controller Subsystem + BlueZ 5.50 Host Stack (Ezurio Sona IF573 based design)

Design Name	Owner	Declaration ID	QD ID	Link to listing on the SIG website
Sona IF573	Ezurio	D063147	202782	https://qualification.bluetooth.com/ListingDetails/171057
BlueZ 5.50 Host Stack	Ezurio	D046330	138224	https://qualification.bluetooth.com/ListingDetails/93911

21.5 Qualify More Products

If you develop further products based on the same design in the future, it is possible to add them free of charge. The new product must not modify the existing design i.e add ICS functionality, otherwise a new design listing will be required.

To add more products to your design, select 'Manage Submitted Products' in the **Getting Started** page, Actions, Qualify More Products. The tool will take you through the updating process.

22 Additional Information

Please contact your local sales representative or our support team for further assistance:

Headquarters	Ezurio 50 S. Main St. Suite 1100 Akron, OH 44308 USA
Website	http://www.ezurio.com
Technical Support	http://www.ezurio.com/resources/support
Sales Contact	http://www.ezurio.com/contact

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